

# XMC4500

Microcontroller Series  
for Industrial Applications

XMC4000 Family

ARM<sup>®</sup> Cortex<sup>®</sup>-M4  
32-bit processor core

Data Sheet

V1.5 2017-12

**Edition 2017-12**

**Published by  
Infineon Technologies AG  
81726 Munich, Germany**

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## XMC4500 Data Sheet

### Revision History: V1.5 2017-12

Previous Versions:

V1.4, 2016-01

V1.3, 2014-03

V1.2, 2013-07

V1.1, 2013-07

V1.0, 2013-01

V0.9, 2012-12

V0.8, 2012-11

Page	Subjects
<b>51</b>	Added RMS Noise parameter in VADC Parameters table.
<b>52</b>	Added footnotes <sup>9)</sup> , <sup>10)</sup> , <sup>11)</sup> to RMS Noise parameter.
<b>44</b>	Added information that $\overline{\text{PORST}}$ Pull-up is identical to the pull-up on standard I/O pins.
<b>43</b>	Added footnote explaining minimum $V_{\text{BAT}}$ requirements to start the hibernate domain and/or oscillation of a crystal on RTC_XTAL.
<b>61</b>	Corrected parameter name of of USB pull device (upstream port receiving) definition according to USB standard (referenced to DM instead of DP)
<b>63</b>	Relaxed RTC_XTAL $V_{\text{PPX}}$ parameter value and changed it to a system requirement.
<b>117ff</b>	Added PG-LQFP-100-25 and PG-LQFP-144-24 package information.
<b>117</b>	Added tables describing the differences between PG-LQFP-100-11 to PG-LQFP-100-25 as well as PG-LQFP-144-18 to PG-LQFP-144-24 packages.

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## **About this Document**

This Data Sheet is addressed to embedded hardware and software developers. It provides the reader with detailed descriptions about the ordering designations, available features, electrical and physical characteristics of the XMC4500 series devices.

The document describes the characteristics of a superset of the XMC4500 series devices. For simplicity, the various device types are referred to by the collective term XMC4500 throughout this manual.

### **XMC4000 Family User Documentation**

The set of user documentation includes:

- **Reference Manual**
  - describes the functionality of the superset of devices.
- **Data Sheets**
  - list the complete ordering designations, available features and electrical characteristics of derivative devices.
- **Errata Sheets**
  - list deviations from the specifications given in the related Reference Manual or Data Sheets. Errata Sheets are provided for the superset of devices.

***Attention: Please consult all parts of the documentation set to attain consolidated knowledge about your device.***

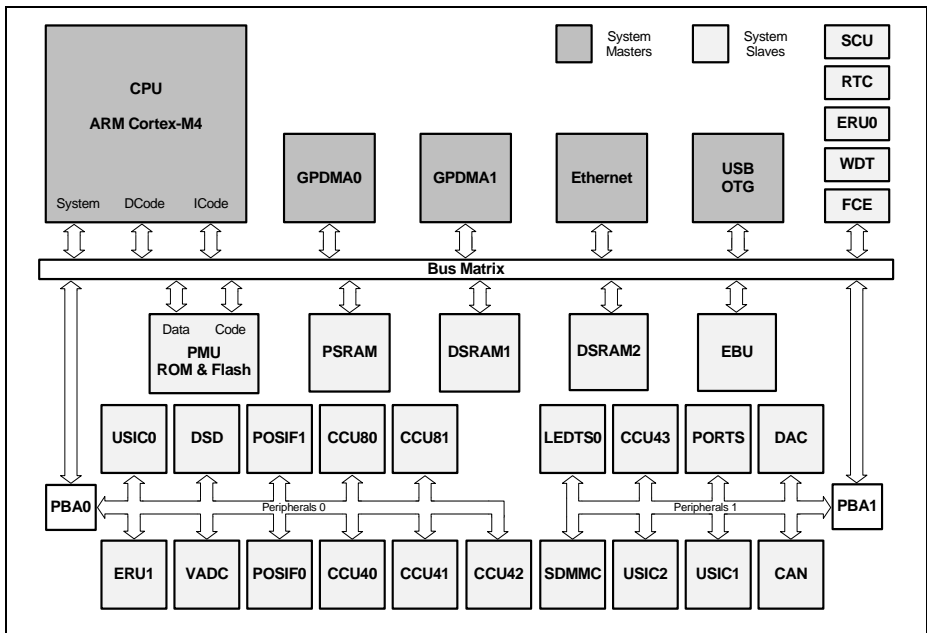
Application related guidance is provided by **Users Guides** and **Application Notes**.

Please refer to <http://www.infineon.com/xmc4000> to get access to the latest versions of those documents.



## 1 Summary of Features

The XMC4500 devices are members of the XMC4000 Family of microcontrollers based on the ARM Cortex-M4 processor core. The XMC4000 is a family of high performance and energy efficient microcontrollers optimized for Industrial Connectivity, Industrial Control, Power Conversion, Sense & Control.



**Figure 1 System Block Diagram**

### CPU Subsystem

- CPU Core
  - High Performance 32-bit ARM Cortex-M4 CPU
  - 16-bit and 32-bit Thumb2 instruction set
  - DSP/MAC instructions
  - System timer (SysTick) for Operating System support
- Floating Point Unit
- Memory Protection Unit
- Nested Vectored Interrupt Controller
- Two General Purpose DMA with up-to 12 channels
- Event Request Unit (ERU) for programmable processing of external and internal service requests

---

**Summary of Features**

- Flexible CRC Engine (FCE) for multiple bit error detection

**On-Chip Memories**

- 16 KB on-chip boot ROM
- 64 KB on-chip high-speed program memory
- 64 KB on-chip high speed data memory
- 32 KB on-chip high-speed communication
- 1024 KB on-chip Flash Memory with 4 KB instruction cache

**Communication Peripherals**

- Ethernet MAC module capable of 10/100 Mbit/s transfer rates
- Universal Serial Bus, USB 2.0 host, Full-Speed OTG, with integrated PHY
- Controller Area Network interface (MultiCAN), Full-CAN/Basic-CAN with 3 nodes, 64 message objects (MO), data rate up to 1MBit/s
- Six Universal Serial Interface Channels (USIC), providing 6 serial channels, usable as UART, double-SPI, quad-SPI, IIC, IIS and LIN interfaces
- LED and Touch-Sense Controller (LEDTS) for Human-Machine interface
- SD and Multi-Media Card interface (SDMMC) for data storage memory cards
- External Bus Interface Unit (EBU) enabling communication with external memories and off-chip peripherals

**Analog Frontend Peripherals**

- Four Analog-Digital Converters (VADC) of 12-bit resolution, 8 channels each, with input out-of-range comparators
- Delta Sigma Demodulator with four channels, digital input stage for A/D signal conversion
- Digital-Analogue Converter (DAC) with two channels of 12-bit resolution

**Industrial Control Peripherals**

- Two Capture/Compare Units 8 (CCU8) for motor control and power conversion
- Four Capture/Compare Units 4 (CCU4) for use as general purpose timers
- Two Position Interfaces (POSIF) for servo motor positioning
- Window Watchdog Timer (WDT) for safety sensitive applications
- Die Temperature Sensor (DTS)
- Real Time Clock module with alarm support
- System Control Unit (SCU) for system configuration and control

## Input/Output Lines

- Programmable port driver control module (PORTS)
- Individual bit addressability
- Tri-stated in input mode
- Push/pull or open drain output mode
- Boundary scan test support over JTAG interface

## On-Chip Debug Support

- Full support for debug features: 8 breakpoints, CoreSight, trace
- Various interfaces: ARM-JTAG, SWD, single wire trace

## 1.1 Ordering Information

The ordering code for an Infineon microcontroller provides an exact reference to a specific product. The code "XMC4<DDD>-<Z><PPP><T><FFFF>" identifies:

- <DDD> the derivatives function set
- <Z> the package variant
  - E: LFBGA
  - F: LQFP
  - Q: VQFN
- <PPP> package pin count
- <T> the temperature range:
  - F: -40°C to 85°C
  - X: -40°C to 105°C
  - K: -40°C to 125°C
- <FFFF> the Flash memory size.

For ordering codes for the XMC4500 please contact your sales representative or local distributor.

This document describes several derivatives of the XMC4500 series, some descriptions may not apply to a specific product.

For simplicity the term **XMC4500** is used for all derivatives throughout this document.

## 1.2 Device Types

These device types are available and can be ordered through Infineon's direct and/or distribution channels.

**Table 1 Synopsis of XMC4500 Device Types**

Derivative <sup>1)</sup>	Package	Flash Kbytes	SRAM Kbytes
XMC4500-E144x1024	PG-LFBGA-144	1024	160
XMC4500-F144x1024	PG-LQFP-144	1024	160
XMC4500-F100x1024	PG-LQFP-100	1024	160
XMC4500-F144x768	PG-LQFP-144	768	160
XMC4500-F100x768	PG-LQFP-100	768	160
XMC4502-F100x768	PG-LQFP-100	768	160
XMC4504-F144x512	PG-LQFP-144	512	128
XMC4504-F100x512	PG-LQFP-100	512	128

1) x is a placeholder for the supported temperature range.

## 1.3 Device Type Features

The following table lists the available features per device type.

**Table 2 Features of XMC4500 Device Types**

Derivative <sup>1)</sup>	LEDTS Intf.	SDMMC Intf.	EBU Intf. <sup>2)</sup>	ETH Intf. <sup>3)</sup>	USB Intf.	USIC Chan.	MultiCAN Nodes, MO
XMC4500-E144x1024	1	1	SDM	MR	1	3 x 2	N0, N1, N2 MO[0..63]
XMC4500-F144x1024	1	1	SDM	MR	1	3 x 2	N0, N1, N2 MO[0..63]
XMC4500-F100x1024	1	1	M16	R	1	3 x 2	N0, N1, N2 MO[0..63]
XMC4500-F144x768	1	1	SDM	MR	1	3 x 2	N0, N1, N2 MO[0..63]
XMC4500-F100x768	1	1	M16	R	1	3 x 2	N0, N1, N2 MO[0..63]
XMC4502-F100x768	1	1	M16	-	1	3 x 2	N0, N1, N2 MO[0..63]

**Summary of Features**

**Table 2 Features of XMC4500 Device Types (cont'd)**

Derivative <sup>1)</sup>	LEDTS Intf.	SDMMC Intf.	EBU Intf. <sup>2)</sup>	ETH Intf. <sup>3)</sup>	USB Intf.	USIC Chan.	MultiCAN Nodes, MO
XMC4504-F144x512	1	1	SDM	-	-	3 x 2	-
XMC4504-F100x512	1	1	M16	-	-	3 x 2	-

1) x is a placeholder for the supported temperature range.

2) Memory types supported S=SDRAM, D=DEMUX, M=MUX 16-bit and 32-bit, M16=MUX 16-bit

3) Supported interfaces, M=MII, R=RMII.

**Table 3 Features of XMC4500 Device Types**

Derivative <sup>1)</sup>	ADC Chan.	DSD Chan.	DAC Chan.	CCU4 Slice	CCU8 Slice	POSIF Intf.
XMC4500-E144x1024	32	4	2	4 x 4	2 x 4	2
XMC4500-F144x1024	32	4	2	4 x 4	2 x 4	2
XMC4500-F100x1024	24	4	2	4 x 4	2 x 4	2
XMC4500-F144x768	32	4	2	4 x 4	2 x 4	2
XMC4500-F100x768	24	4	2	4 x 4	2 x 4	2
XMC4502-F100x768	24	4	2	4 x 4	2 x 4	2
XMC4504-F144x512	32	4	2	4 x 4	2 x 4	2
XMC4504-F100x512	24	4	2	4 x 4	2 x 4	2

1) x is a placeholder for the supported temperature range.

## 1.4 Definition of Feature Variants

The XMC4500 types are offered with several memory sizes and number of available VADC channels. [Table 4](#) describes the location of the available Flash memory, [Table 5](#) describes the location of the available SRAMs, [Table 6](#) the available VADC channels.

**Table 4 Flash Memory Ranges**

Total Flash Size	Cached Range	Uncached Range
512 Kbytes	0800 0000 <sub>H</sub> – 0807 FFFF <sub>H</sub>	0C00 0000 <sub>H</sub> – 0C07 FFFF <sub>H</sub>

**Summary of Features**

**Table 4 Flash Memory Ranges (cont'd)**

Total Flash Size	Cached Range	Uncached Range
768 Kbytes	0800 0000 <sub>H</sub> – 080B FFFF <sub>H</sub>	0C00 0000 <sub>H</sub> – 0C0B FFFF <sub>H</sub>
1,024 Kbytes	0800 0000 <sub>H</sub> – 080F FFFF <sub>H</sub>	0C00 0000 <sub>H</sub> – 0C0F FFFF <sub>H</sub>

**Table 5 SRAM Memory Ranges**

Total SRAM Size	Program SRAM	System Data SRAM	Communication Data SRAM
128 Kbytes	1000 0000 <sub>H</sub> – 1000 FFFF <sub>H</sub>	2000 0000 <sub>H</sub> – 2000 FFFF <sub>H</sub>	–
160 Kbytes	1000 0000 <sub>H</sub> – 1000 FFFF <sub>H</sub>	2000 0000 <sub>H</sub> – 2000 FFFF <sub>H</sub>	3000 0000 <sub>H</sub> – 3000 7FFF <sub>H</sub>

**Table 6 ADC Channels<sup>1)</sup>**

Package	VADC G0	VADC G1	VADC G2	VADC G3
PG-LQFP-144 PG-LFBGA-144	CH0..CH7	CH0..CH7	CH0..CH7	CH0..CH7
PG-LQFP-100	CH0..CH7	CH0..CH7	CH0..CH3	CH0..CH3

1) Some pins in a package may be connected to more than one channel. For the detailed mapping see the Port I/O Function table.

## 1.5 Identification Registers

The identification registers allow software to identify the marking.

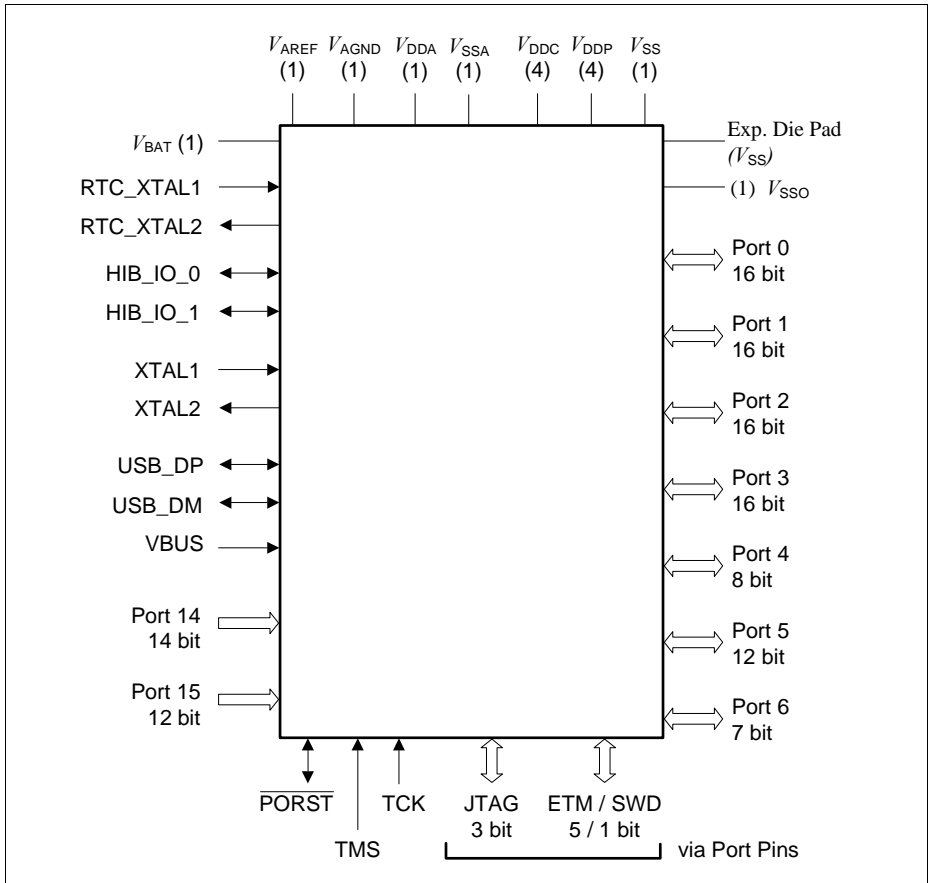
**Table 7 XMC4500 Identification Registers**

Register Name	Value	Marking
SCU_IDCHIP	0004 5002 <sub>H</sub>	EES-AA, ES-AA
SCU_IDCHIP	0004 5003 <sub>H</sub>	ES-AB, AB
SCU_IDCHIP	0004 5004 <sub>H</sub>	AC
JTAG IDCODE	101D B083 <sub>H</sub>	EES-AA, ES-AA
JTAG IDCODE	101D B083 <sub>H</sub>	ES-AB, AB
JTAG IDCODE	401D B083 <sub>H</sub>	AC

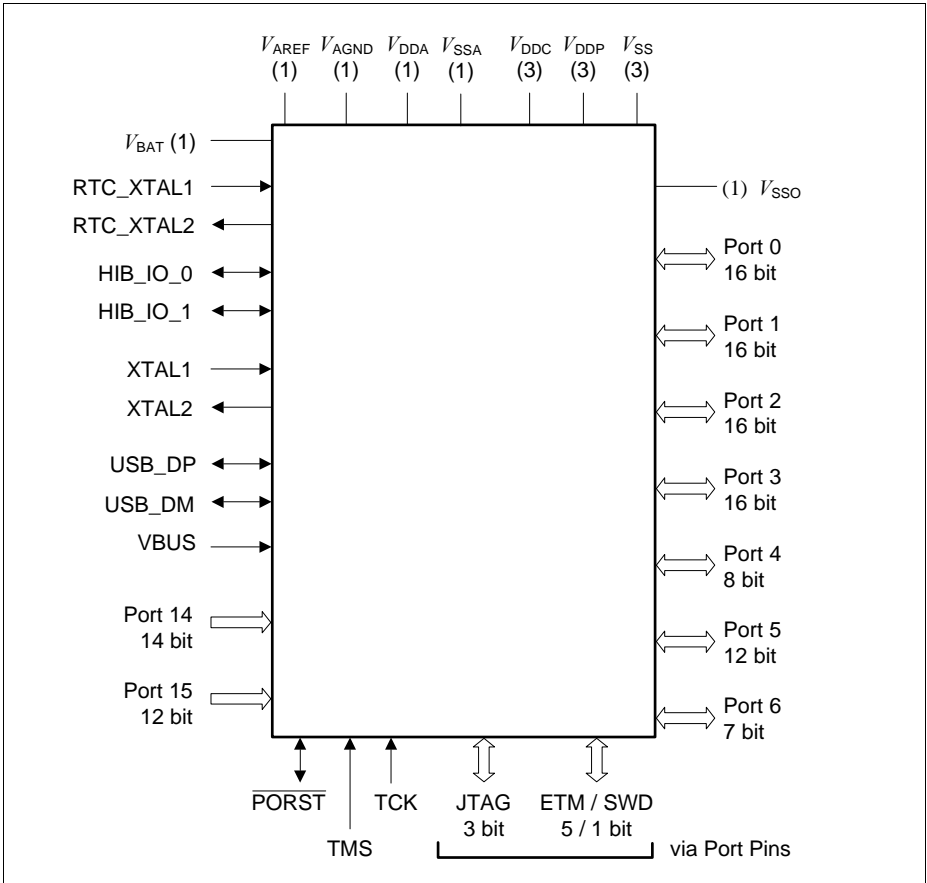
## 2 General Device Information

This section summarizes the logic symbols and package pin configurations with a detailed list of the functional I/O mapping.

### 2.1 Logic Symbols

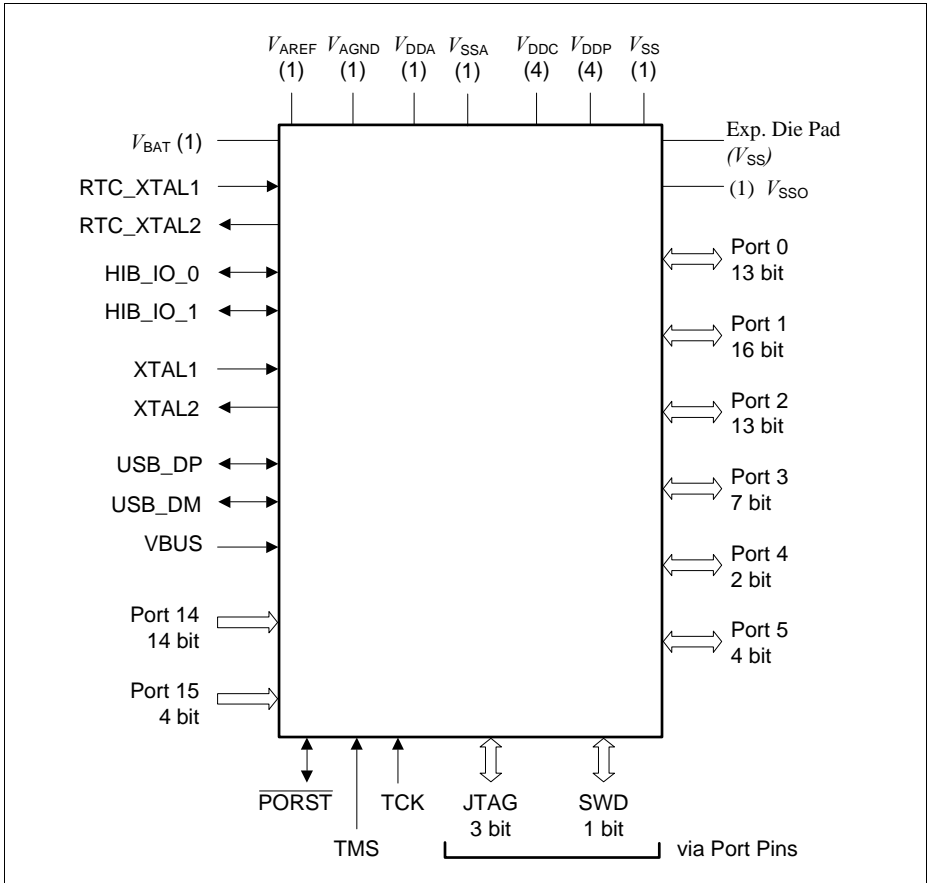


**Figure 2 XMC4500 Logic Symbol PG-LQFP-144**



**Figure 3 XMC4500 Logic Symbol PG-LFBGA-144**

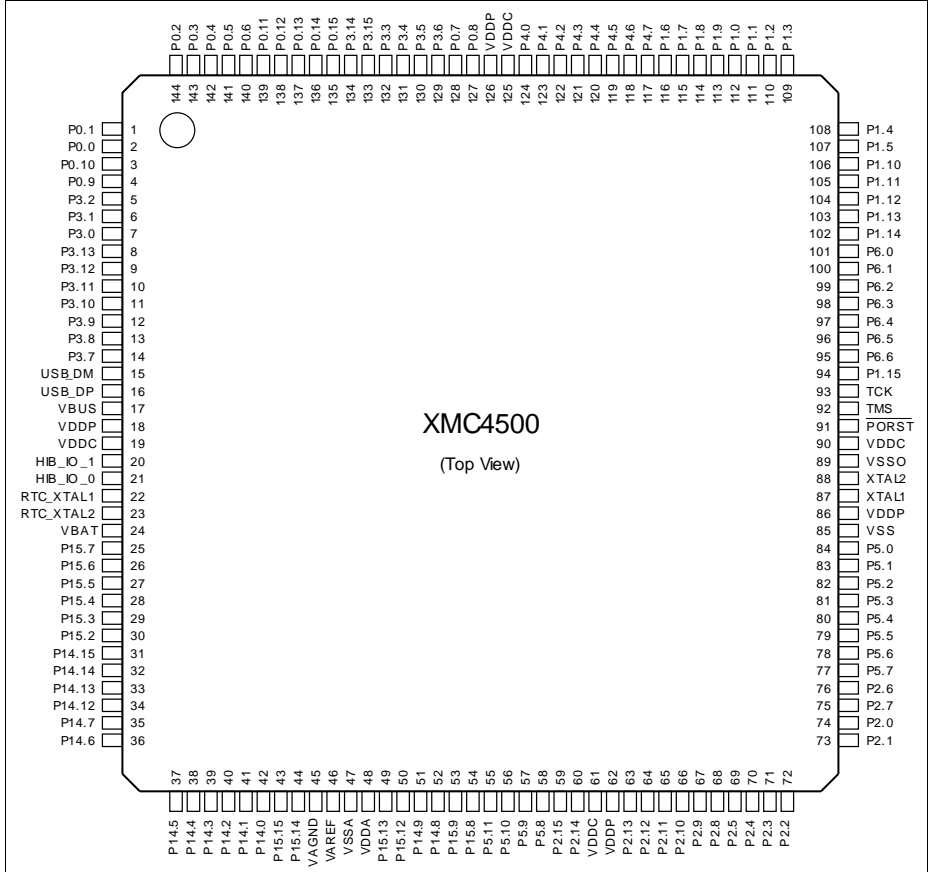




**Figure 4 XMC4500 Logic Symbol PG-LQFP-100**

## 2.2 Pin Configuration and Definition

The following figures summarize all pins, showing their locations on the four sides of the different packages.



**Figure 5 XMC4500 PG-LQFP-144 Pin Configuration (top view)**

**General Device Information**

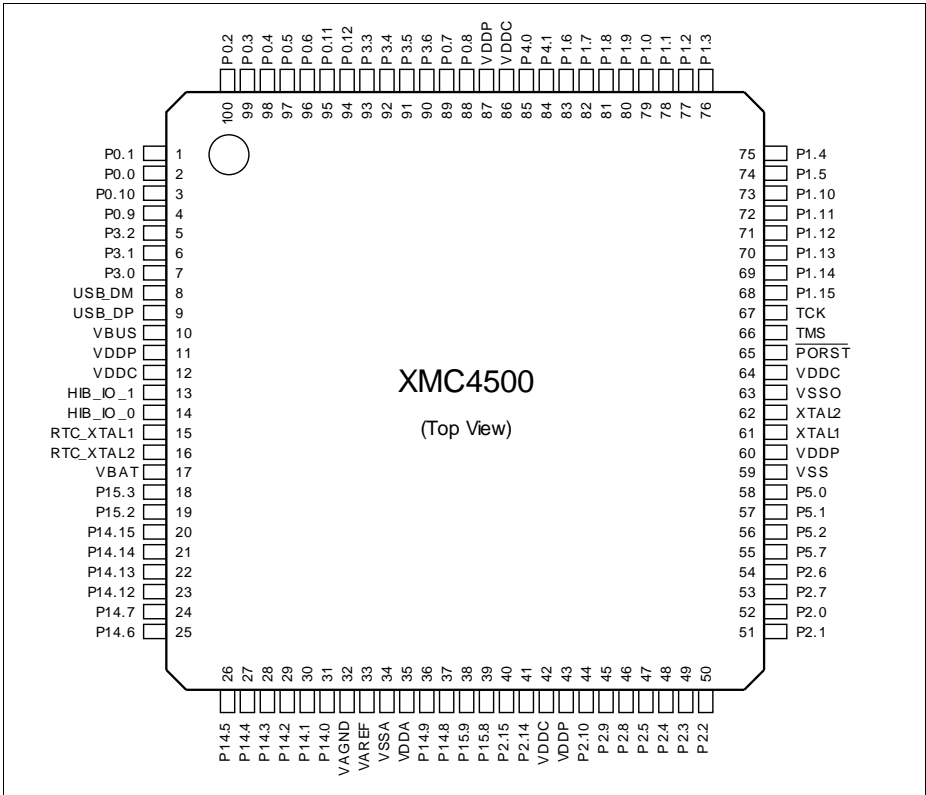
	1	2	3	4	5	6	7	8	9	10	11	12	
A	VSS	VDDC	P0.2	P0.3	P0.5	P0.6	P3.6	P0.8	P4.1	P1.8	VDDP	VSS	A
B	VDDP	P3.1	P3.2	P0.10	P0.4	P3.5	P0.7	P4.0	P1.6	P1.7	P1.9	VDDC	B
C	P3.0	P3.13	P0.1	P0.0	P0.13	P0.15	P4.4	P4.6	P4.7	P1.4	P1.2	P1.3	C
D	USB_D M	P3.12	P3.11	P0.9	P0.12	P3.14	P3.15	P4.5	P1.0	P1.5	P1.11	P1.10	D
E	USB_D P	VBUS	P3.8	P3.7	P0.11	P0.14	P3.4	P4.2	P1.1	P1.14	P1.12	P1.13	E
F	RTC_X TAL2	RTC_X TAL1	HIB_I O_1	HIB_I O_0	P3.9	P3.10	P3.3	P4.3	P6.1	P6.4	P6.5	P6.6	F
G	VBAT	P15.3	P15.5	P15.4	P15.6	P15.7	TMS	TCK	P6.3	P6.0	$\overline{\text{PORST}}$	P1.15	G
H	P15.2	P14.15	P14.14	P14.13	P5.10	P5.8	P5.2	P5.1	P5.0	P6.2	XTAL1	XTAL2	H
J	P14.12	P14.7	P14.6	P14.3	P5.11	P2.15	P5.7	P5.5	P2.6	P5.3	P2.0	VSSO	J
K	P14.4	P14.5	P14.2	P15.15	P15.12	P5.9	P2.14	P5.6	P2.7	P5.4	P2.2	P2.1	K
L	VDDA	P14.1	P14.0	P15.14	P14.9	P15.9	P2.12	P2.10	P2.8	P2.4	P2.3	VDDP	L
M	VSSA	VAGND	VAREF	P15.13	P14.8	P15.8	P2.13	P2.11	P2.9	P2.5	VDDC	VSS	M

1    2    3    4    5    6    7    8    9    10    11    12

XMC4500- (top view)

**Figure 6 XMC4500 PG-LFBGA-144 Pin Configuration (top view)**

**General Device Information**



**Figure 7 XMC4500 PG-LQFP-100 Pin Configuration (top view)**

## 2.2.1 Package Pin Summary

The following general scheme is used to describe each pin:

**Table 8 Package Pin Mapping Description**

Function	Package A	Package B	...	Pad Type	Notes
Name	N	Ax	...	A2	

The table is sorted by the “Function” column, starting with the regular Port pins (Px.y), followed by the dedicated pins (i.e. PORST) and supply pins.

The following columns, titled with the supported package variants, lists the package pin number to which the respective function is mapped in that package.

The “Pad Type” indicates the employed pad type (A1, A1+, A2, special=special pad, In=input pad, AN/DIG\_IN=analog and digital input, Power=power supply). Details about the pad properties are defined in the Electrical Parameters.

In the “Notes”, special information to the respective pin/function is given, i.e. deviations from the default configuration after reset. Per default the regular Port pins are configured as direct input with no internal pull device active.

**Table 9 Package Pin Mapping**

Function	LQFP-144	LFBGA-144	LQFP-100	Pad Type	Notes
P0.0	2	C4	2	A1+	
P0.1	1	C3	1	A1+	
P0.2	144	A3	100	A2	
P0.3	143	A4	99	A2	
P0.4	142	B5	98	A2	
P0.5	141	A5	97	A2	
P0.6	140	A6	96	A2	
P0.7	128	B7	89	A2	After a system reset, via HWSEL this pin selects the DB.TDI function.
P0.8	127	A8	88	A2	After a system reset, via HWSEL this pin selects the DB.TRST function, with a weak pull-down active.
P0.9	4	D4	4	A2	
P0.10	3	B4	3	A1+	

**General Device Information**

**Table 9 Package Pin Mapping (cont'd)**

Function	LQFP-144	LFBGA-144	LQFP-100	Pad Type	Notes
P0.11	139	E5	95	A1+	
P0.12	138	D5	94	A1+	
P0.13	137	C5	-	A1+	
P0.14	136	E6	-	A1+	
P0.15	135	C6	-	A1+	
P1.0	112	D9	79	A1+	
P1.1	111	E9	78	A1+	
P1.2	110	C11	77	A2	
P1.3	109	C12	76	A2	
P1.4	108	C10	75	A1+	
P1.5	107	D10	74	A1+	
P1.6	116	B9	83	A2	
P1.7	115	B10	82	A2	
P1.8	114	A10	81	A2	
P1.9	113	B11	80	A2	
P1.10	106	D12	73	A1+	
P1.11	105	D11	72	A1+	
P1.12	104	E11	71	A2	
P1.13	103	E12	70	A2	
P1.14	102	E10	69	A2	
P1.15	94	G12	68	A2	
P2.0	74	J11	52	A2	
P2.1	73	K12	51	A2	After a system reset, via HWSEL this pin selects the DB.TDO function.
P2.2	72	K11	50	A2	
P2.3	71	L11	49	A2	
P2.4	70	L10	48	A2	
P2.5	69	M10	47	A2	
P2.6	76	J9	54	A1+	
P2.7	75	K9	53	A1+	
P2.8	68	L9	46	A2	
P2.9	67	M9	45	A2	

**General Device Information**

**Table 9 Package Pin Mapping (cont'd)**

Function	LQFP-144	LFBGA-144	LQFP-100	Pad Type	Notes
P2.10	66	L8	44	A2	
P2.11	65	M8	-	A2	
P2.12	64	L7	-	A2	
P2.13	63	M7	-	A2	
P2.14	60	K7	41	A2	
P2.15	59	J6	40	A2	
P3.0	7	C1	7	A2	
P3.1	6	B2	6	A2	
P3.2	5	B3	5	A2	
P3.3	132	F7	93	A1+	
P3.4	131	E7	92	A1+	
P3.5	130	B6	91	A2	
P3.6	129	A7	90	A2	
P3.7	14	E4	-	A1+	
P3.8	13	E3	-	A1+	
P3.9	12	F5	-	A1+	
P3.10	11	F6	-	A1+	
P3.11	10	D3	-	A1+	
P3.12	9	D2	-	A2	
P3.13	8	C2	-	A2	
P3.14	134	D6	-	A1+	
P3.15	133	D7	-	A1+	
P4.0	124	B8	85	A2	
P4.1	123	A9	84	A2	
P4.2	122	E8	-	A1+	
P4.3	121	F8	-	A1+	
P4.4	120	C7	-	A1+	
P4.5	119	D8	-	A1+	
P4.6	118	C8	-	A1+	
P4.7	117	C9	-	A1+	
P5.0	84	H9	58	A1+	
P5.1	83	H8	57	A1+	
P5.2	82	H7	56	A1+	

**Table 9 Package Pin Mapping (cont'd)**

Function	LQFP-144	LFBGA-144	LQFP-100	Pad Type	Notes
P5.3	81	J10	-	A2	
P5.4	80	K10	-	A2	
P5.5	79	J8	-	A2	
P5.6	78	K8	-	A2	
P5.7	77	J7	55	A1+	
P5.8	58	H6	-	A2	
P5.9	57	K6	-	A2	
P5.10	56	H5	-	A1+	
P5.11	55	J5	-	A1+	
P6.0	101	G10	-	A2	
P6.1	100	F9	-	A2	
P6.2	99	H10	-	A2	
P6.3	98	G9	-	A1+	
P6.4	97	F10	-	A2	
P6.5	96	F11	-	A2	
P6.6	95	F12	-	A2	
P14.0	42	L3	31	AN/DIG_IN	
P14.1	41	L2	30	AN/DIG_IN	
P14.2	40	K3	29	AN/DIG_IN	
P14.3	39	J4	28	AN/DIG_IN	
P14.4	38	K1	27	AN/DIG_IN	
P14.5	37	K2	26	AN/DIG_IN	
P14.6	36	J3	25	AN/DIG_IN	
P14.7	35	J2	24	AN/DIG_IN	
P14.8	52	M5	37	AN/DAC/DI G_IN	
P14.9	51	L5	36	AN/DAC/DI G_IN	
P14.12	34	J1	23	AN/DIG_IN	
P14.13	33	H4	22	AN/DIG_IN	
P14.14	32	H3	21	AN/DIG_IN	
P14.15	31	H2	20	AN/DIG_IN	
P15.2	30	H1	19	AN/DIG_IN	



**General Device Information**

**Table 9 Package Pin Mapping (cont'd)**

Function	LQFP-144	LFBGA-144	LQFP-100	Pad Type	Notes
P15.3	29	G2	18	AN/DIG_IN	
P15.4	28	G4	-	AN/DIG_IN	
P15.5	27	G3	-	AN/DIG_IN	
P15.6	26	G5	-	AN/DIG_IN	
P15.7	25	G6	-	AN/DIG_IN	
P15.8	54	M6	39	AN/DIG_IN	
P15.9	53	L6	38	AN/DIG_IN	
P15.12	50	K5	-	AN/DIG_IN	
P15.13	49	M4	-	AN/DIG_IN	
P15.14	44	L4	-	AN/DIG_IN	
P15.15	43	K4	-	AN/DIG_IN	
USB_DP	16	E1	9	special	
USB_DM	15	D1	8	special	
HIB_IO_0	21	F4	14	A1 special	At the first power-up and with every reset of the hibernate domain this pin is configured as open-drain output and drives "0". As output the medium driver mode is active.
HIB_IO_1	20	F3	13	A1 special	At the first power-up and with every reset of the hibernate domain this pin is configured as input with no pull device active. As output the medium driver mode is active.
TCK	93	G8	67	A1	Weak pull-down active.
TMS	92	G7	66	A1+	Weak pull-up active. As output the strong-soft driver mode is active.
$\overline{\text{PORST}}$	91	G11	65	special	Weak pull-up permanently active, strong pull-down controlled by EVR.
XTAL1	87	H11	61	clock_IN	
XTAL2	88	H12	62	clock_O	

**General Device Information**

**Table 9 Package Pin Mapping (cont'd)**

Function	LQFP-144	LFBGA-144	LQFP-100	Pad Type	Notes
RTC_XTAL1	22	F2	15	clock_IN	
RTC_XTAL2	23	F1	16	clock_O	
VBAT	24	G1	17	Power	When VDDP is supplied VBAT has to be supplied as well.
VBUS	17	E2	10	special	
VAREF	46	M3	33	AN_Ref	
VAGND	45	M2	32	AN_Ref	
VDDA	48	L1	35	AN_Power	
VSSA	47	M1	34	AN_Power	
VDDC	19	-	12	Power	
VDDC	61	-	42	Power	
VDDC	90	-	64	Power	
VDDC	125	-	86	Power	
VDDC	-	A2	-	Power	
VDDC	-	B12	-	Power	
VDDC	-	M11	-	Power	
VDDP	18	-	11	Power	
VDDP	62	-	43	Power	
VDDP	86	-	60	Power	
VDDP	126	-	87	Power	
VDDP	-	A11	-	Power	
VDDP	-	B1	-	Power	
VDDP	-	L12	-	Power	
VSS	85	-	59	Power	
VSS	-	A1	-	Power	
VSS	-	A12	-	Power	
VSS	-	M12	-	Power	

**General Device Information**

**Table 9 Package Pin Mapping (cont'd)**

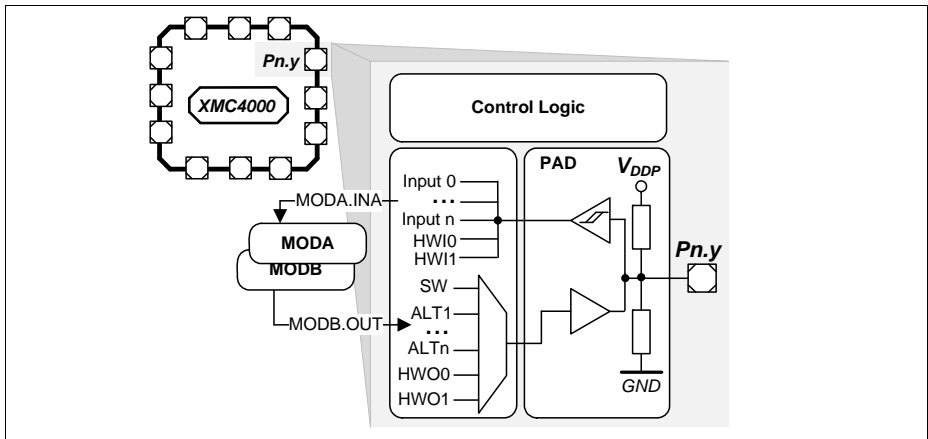
Function	LQFP-144	LFBGA-144	LQFP-100	Pad Type	Notes
VSSO	89	J12	63	Power	
VSS	Exp. Pad	-	Exp. Pad	Power	<p><b>Exposed Die Pad</b> The exposed die pad is connected internally to VSS. For proper operation, it is mandatory to connect the exposed pad directly to the common ground on the board. For thermal aspects, please refer to the Data Sheet. Board layout examples are given in an application note.</p>

### 2.2.2 Port I/O Functions

The following general scheme is used to describe each Port pin:

**Table 10 Port I/O Function Description**

Function	Outputs			Inputs		
	ALT1	ALn	HWO0	HWIO	Input	Input
P0.0		MODA.OUT	MODB.OUT	MODB.INA	MODC.INA	
Pn.y	MODA.OUT				MODA.INA	MODC.INB



**Figure 8 Simplified Port Structure**

Pn.y is the port pin name, defining the control and data bits/registers associated with it. As GPIO, the port is under software control. Its input value is read via Pn\_IN.y, Pn\_OUT defines the output value.

Up to four alternate output functions (ALT1/2/3/4) can be mapped to a single port pin, selected by Pn\_IOCR.PC. The output value is directly driven by the respective module, with the pin characteristics controlled by the port registers (within the limits of the connected pad).

The port pin input can be connected to multiple peripherals. Most peripherals have an input multiplexer to select between different possible input sources.

The input path is also active while the pin is configured as output. This allows to feedback an output to on-chip resources without wasting an additional external pin.

By Pn\_HWSEL it is possible to select between different hardware “masters” (HWO0/HWIO, HWO1/HW11). The selected peripheral can take control of the pin(s). Hardware control overrules settings in the respective port pin registers.

## 2.2.2.1 Port I/O Function Table

**Table 11 Port I/O Functions**

Function	Outputs						Inputs									
	ALT1	ALT2	ALT3	ALT4	HWO0	HWO1	HWI0	HWI1	Input	Input	Input	Input	Input	Input	Input	Input
P0.0		CAN. NO_TXD	CCU80. OUT21	LEDS0. COL2					U1C1. DX0D	ETH0. CLK_RMIB	ERU0. 0B0					ETH0. CLKRXB
P0.1	USB. DRIVEVBUS	U1C1. DOUT0	CCU80. OUT11	LEDS0. COL3						ETH0. CRS_DVB	ERU0. 0A0					ETH0. RXDVB
P0.2		U1C1. SELO1	CCU80. OUT0		U1C0. DOUT3	EBU. AD0	U1C0. HWIN3	EBU. D0	ETH0. RXD0B		ERU0. 3B3					
P0.3			CCU80. OUT20		U1C0. DOUT2	EBU. AD1	U1C0. HWIN2	EBU. D1	ETH0. RXD1B			ERU1. 3B0				
P0.4	ETH0. TX_EN		CCU80. OUT10		U1C0. DOUT1	EBU. AD2	U1C0. HWIN1	EBU. D2		U1C0. DX0A	ERU0. 2B3					
P0.5	ETH0. TXD0	U1C0. DOUT0	CCU80. OUT00		U1C0. DOUT0	EBU. AD3	U1C0. HWIN0	EBU. D3		U1C0. DX0B		ERU1. 3A0				
P0.6	ETH0. TXD1	U1C0. SELO0	CCU80. OUT30			EBU. ADV				U1C0. DX2A	ERU0. 3B2		CCU80. IN2B			
P0.7	WWDT. SERVICE_OUT	U0C0. SELO0				EBU. AD6	DB. TDI	EBU. D6	U0C0. DX2B	DSD. DIN1A	ERU0. 2B1		CCU80. IN0A	CCL80. IN1A	CCL80. IN2A	CCU80. IN3A
P0.8	SCU. EXTCLK	U0C0. SCLKOUT				EBU. AD7	DB. TRST	EBU. D7	U0C0. DX1B	DSD. DIN0A	ERU0. 2A1		CCU80. IN1B			
P0.9		U1C1. SELO0	CCU80. OUT12	LEDS0. COL0	ETH0. MOD	EBU. CST	ETH0. MDIA		U1C1. DX2A	USB. ID	ERU0. 1B0					
P0.10	ETH0. MDC	U1C1. SCLKOUT	CCU80. OUT02	LEDS0. COL1					U1C1. DX1A		ERU0. 1A0					
P0.11		U1C0. SCLKOUT	CCU80. OUT31		SDMMC. RST	EBU. BREQ			ETH0. RXERB	U1C0. DX1A	ERU0. 3A2					
P0.12		U1C1. SELO0	CCU40. OUT3			EBU. HLDA		EBU. HLDA		U1C1. DX2B	ERU0. 2B2					
P0.13		U1C1. SCLKOUT	CCU40. OUT2							U1C1. DX1B	ERU0. 2A2					
P0.14		U1C0. SELO1	CCU40. OUT1		U1C1. DOUT3		U1C1. HWIN3						CCU42. IN3C			
P0.15		U1C0. SELO2	CCU40. OUT0		U1C1. DOUT2		U1C1. HWIN2						CCU42. IN2C			
P1.0	DSD. CGPWMM	U0C0. SELO0	CCU40. OUT3	ERU1. PDOUT3					U0C0. DX2A		ERU0. 3B0		CCU40. IN3A			
P1.1	DSD. CGPWMP	U0C0. SCLKOUT	CCU40. OUT2	ERU1. PDOUT2			SDMMC. SDWC		U0C0. DX1A	POSIF0. IN2A	ERU0. 3A0		CCU40. IN2A			
P1.2			CCU40. OUT1	ERU1. PDOUT1	U0C0. DOUT3	EBU. AD14	U0C0. HWIN3	EBU. D14		POSIF0. IN1A		ERU1. 2B0	CCU40. IN1A			
P1.3		U0C0. MCLKOUT	CCU40. OUT0	ERU1. PDOUT0	U0C0. DOUT2	EBU. AD15	U0C0. HWIN2	EBU. D15		POSIF0. IN0A		ERU1. 2A0	CCU40. IN0A			
P1.4	WWDT. SERVICE_OUT	CAN. NO_TXD	CCU80. OUT33	CCU81. OUT20	U0C0. DOUT1		U0C0. HWIN1		U0C0. DX0B	CAN. INT_RXDD	ERU0. 2B0		CCU41. IN0C			

**Table 11 Port I/O Functions (cont'd)**

Function	Outputs						Inputs								
	ALT1	ALT2	ALT3	ALT4	HWO0	HWO1	HWO0	HWO1	Input	Input	Input	Input	Input	Input	Input
P1.5	CAN_N1_TXD	U0C0_DOUT0	CCU80_OUT23	CCU81_OUT10	U0C0_DOUT0		U0C0_HWO0		U0C0_DX0A	CAN_NO_RXDA	ERU0_ZA0	ERU1_0A0	CCU41_IN1C	DSD_DIN2B	
P1.6		U0C0_SCLKOUT			SDMMC_DATA1_OUT	EBU_AD10	SDMMC_DATA1_IN	EBU_D10	DSD_DIN2A						
P1.7		U0C0_DOUT0	DSD_MCLK2		SDMMC_DATA2_OUT	EBU_AD11	SDMMC_DATA2_IN	EBU_D11		DSD_MCLK2A					
P1.8		U0C0_SELO1	DSD_MCLK1		SDMMC_DATA4_OUT	EBU_AD12	SDMMC_DATA4_IN	EBU_D12	CAN_N2_RXDA	DSD_MCLK1A					
P1.9		CAN_N2_TXD			SDMMC_DATA5_OUT	EBU_AD13	SDMMC_DATA5_IN	EBU_D13		DSD_MCLK0A					
P1.10	ETH0_MDC	U0C0_SCLKOUT	CCU81_OUT21				SDMMC_SDCD						CCU41_IN2C		
P1.11		U0C0_SELO0	CCU81_OUT11		ETH0_MDO		ETH0_MDIC						CCU41_IN3C		
P1.12	ETH0_TX_EN	CAN_N1_TXD	CCU81_OUT01		SDMMC_DATA6_OUT	EBU_AD16	SDMMC_DATA6_IN	EBU_D16							
P1.13	ETH0_TXD0	U0C1_SELO3	CCU81_OUT20		SDMMC_DATA7_OUT	EBU_AD17	SDMMC_DATA7_IN	EBU_D17	CAN_N1_RXDC						
P1.14	ETH0_TXD1	U0C1_SELO2	CCU81_OUT10			EBU_AD18		EBU_D18							
P1.15	SCU_EXCLK	DSD_MCLK2	CCU81_OUT00			EBU_AD19		EBU_D19		DSD_MCLK2B		ERU1_1A0			
P2.0		CCU81_OUT21	DSD_CGPWMN	LEDT50_COL1	ETH0_MDO	EBU_AD20	ETH0_MDIB	EBU_D20			ERU0_0B3		CCU40_IN1C		
P2.1		CCU81_OUT11	DSD_CGPWMP	LEDT50_COL0	DB_TDO/TRACESWO	EBU_AD21		EBU_D21	ETH0_CLK_RMIIA			ERU1_0B0	CCU40_IN0C		ETH0_CLKRXA
P2.2	VADC_EMUX00	CCU81_OUT01	CCU41_OUT3	LEDT50_LINE0	LEDT50_EXTENDED0	EBU_AD22	LEDT50_TSINA0	EBU_D22	ETH0_RXD0A	U0C1_DX0A	ERU0_1B2		CCU41_IN3A		
P2.3	VADC_EMUX01	U0C1_SELO0	CCU41_OUT2	LEDT50_LINE1	LEDT50_EXTENDED1	EBU_AD23	LEDT50_TSINA1A	EBU_D23	ETH0_RXD1A	U0C1_DX2A	ERU0_1A2	POSIF1_IN2A	CCU41_IN2A		
P2.4	VADC_EMUX02	U0C1_SCLKOUT	CCU41_OUT1	LEDT50_LINE2	LEDT50_EXTENDED2	EBU_AD24	LEDT50_TSINA2A	EBU_D24	ETH0_RXERA	U0C1_DX1A	ERU0_0B2	POSIF1_IN1A	CCU41_IN1A		
P2.5	ETH0_TX_EN	U0C1_DOUT0	CCU41_OUT0	LEDT50_LINE3	LEDT50_EXTENDED3	EBU_AD25	LEDT50_TSINA3A	EBU_D25	ETH0_RXDVA	U0C1_DX0B	ERU0_0A2	POSIF1_IN0A	CCU41_IN0A		ETH0_CRS_DVA
P2.6	U2C0_SELO4		CCU80_OUT13	LEDT50_COL3	U2C0_DOUT3		U2C0_HWO3		DSD_DIN1B	CAN_N1_RXDA	ERU0_1B3		CCU40_IN3C		
P2.7	ETH0_MDC	CAN_N1_TXD	CCU80_OUT03	LEDT50_COL2					DSD_DIN0B			ERU1_1B0	CCU40_IN2C		
P2.8	ETH0_TXD0		CCU80_OUT32	LEDT50_LINE4	LEDT50_EXTENDED4	EBU_AD26	LEDT50_TSINA4A	EBU_D26	DAC_TRIGGERS				CCU40_IN0B	CCU40_IN2B	CCU40_IN3B
P2.9	ETH0_TXD1		CCU80_OUT22	LEDT50_LINE5	LEDT50_EXTENDED5	EBU_AD27	LEDT50_TSINA5A	EBU_D27	DAC_TRIGGER4				CCU41_IN0B	CCU41_IN2B	CCU41_IN3B
P2.10	VADC_EMUX10				DB_ETM_TRACEDA_TA3	EBU_AD28		EBU_D28							
P2.11	ETH0_TXER		CCU80_OUT20		DB_ETM_TRACEDA_TA2	EBU_AD29		EBU_D29							

**Table 11 Port I/O Functions (cont'd)**

Function	Outputs						Inputs								
	ALT1	ALT2	ALT3	ALT4	HWO0	HWO1	HWO0	HWI1	Input	Input	Input	Input	Input	Input	Input
P2.12	ETH0_TXD2		CCU81_OUT33	ETH0_TXD0	DB_ETM_TRACEDA_TA1	EBU_AD30		EBU_D30					CCU43_IN3C		
P2.13	ETH0_TXD3			ETH0_TXD1	DB_ETM_TRACEDA_TA0	EBU_AD31		EBU_D31					CCU43_IN2C		
P2.14	VADC_EMUX11	U1C0_DOUT0	CCU80_OUT21		DB_ETM_TRACECLK	EBU_BC0				U1C0_DX0D			CCU43_IN0B	CCU43_IN1B	CCU43_IN2B
P2.15	VADC_EMUX12		CCU80_OUT11	LEDT50_LINE6	LEDT50_EXTENDED6	EBU_BCT	LEDT50_TSIN6A	ETH0_COLA		U1C0_DX0C			CCU42_IN0B	CCU42_IN1B	CCU42_IN2B
P3.0	U2C1_SEL00	U0C1_SCLKOUT	CCU42_OUT0			EBU_RD			U0C1_DX1B				CCU80_IN2C	CCU81_IN0C	
P3.1		U0C1_SEL00				EBU_RD_WR			U0C1_DX2B		ERU0_0B1		CCU80_IN1C		
P3.2	USB_DRIVEVBUS	CAN_NO_TXD		LEDT50_COLA		EBU_CS0					ERU0_0A1		CCU80_IN0C		
P3.3		U1C1_SEL01	CCU42_OUT3		SDMMC_LED			EBU_WAIT		DSD_DIN3B			CCU42_IN3A	CCU80_IN3B	
P3.4	U2C1_MCLKOUT	U1C1_SEL02	CCU42_OUT2	DSD_MCLK3	SDMMC_BUS_POWER			EBU_HOLD	U2C1_DX0B	DSD_MCLK3B			CCU42_IN2A	CCU80_IN0B	
P3.5	U2C1_DOUT0	U1C1_SEL03	CCU42_OUT1	U0C1_DOUT0	SDMMC_CMD_OUT	EBU_AD4	SDMMC_CMD_IN	EBU_D4	U2C1_DX0A		ERU0_3B1		CCU42_IN1A		
P3.6	U2C1_SCLKOUT	U1C1_SEL04	CCU42_OUT0	U0C1_SCLKOUT	SDMMC_CLK_OUT	EBU_AD5	SDMMC_CLK_IN	EBU_D5	U2C1_DX1B		ERU0_3A1		CCU42_IN0A		
P3.7		CAN_NZ_TXD	CCU41_OUT3	LEDT50_LINE0						U2C0_DX0C					
P3.8	U2C0_DOUT0	U0C1_SEL03	CCU41_OUT2	LEDT50_LINE1									POSIF1_IN2B		
P3.9	U2C0_SCLKOUT	CAN_N1_TXD	CCU41_OUT1	LEDT50_LINE2									POSIF1_IN1B		
P3.10	U2C0_SEL00	CAN_NO_TXD	CCU41_OUT0	LEDT50_LINE3	U0C1_DOUT3		U0C1_HWIN3						POSIF1_IN0B		
P3.11	U2C1_DOUT0	U0C1_SEL02	CCU42_OUT3	LEDT50_LINE4	U0C1_DOUT2		U0C1_HWIN2			CAN_N1_RXDB				CCU81_IN3C	
P3.12		U0C1_SEL01	CCU42_OUT2	LEDT50_LINE5	U0C1_DOUT1		U0C1_HWIN1		CAN_NO_RXDC	U2C1_DX0D				CCU81_IN2C	
P3.13	U2C1_SCLKOUT	U0C1_DOUT0	CCU42_OUT1	LEDT50_LINE6	U0C1_DOUT0		U0C1_HWIN0		U0C1_DX0D				CCU80_IN3C	CCU81_IN1C	
P3.14		U1C0_SEL03			U1C1_DOUT1			U1C1_HWIN1		U1C1_DX0B			CCU42_IN1C		
P3.15		U1C1_DOUT0			U1C1_DOUT0			U1C1_HWIN0		U1C1_DX0A			CCU42_IN0C		
P4.0			DSD_MCLK1		SDMMC_DATA0_OUT	EBU_AD6	SDMMC_DATA0_IN	EBU_D6	U1C1_DX1C	DSD_MCLK1B	U0C1_DX0E	U2C1_DX0C			
P4.1	U2C1_SEL00		DSD_MCLK0	U0C1_SEL00	SDMMC_DATA3_OUT	EBU_AD9	SDMMC_DATA3_IN	EBU_D9	U2C1_DX2B	DSD_MCLK0B		U2C1_DX2A			
P4.2	U2C1_SEL01	U1C1_DOUT0		U2C1_SCLKOUT					U1C1_DX0C			U2C1_DX1A	CCU43_IN1C		

**Table 11 Port I/O Functions (cont'd)**

Function	Outputs						Inputs								
	ALT1	ALT2	ALT3	ALT4	HWO0	HWO1	HWI0	HWI1	Input	Input	Input	Input	Input	Input	Input
P4.3	U2C1. SELO2	U2C0. SELOS	CCU43. OUT3											CCU43. IN3A	
P4.4		U2C0. SELO4	CCU43. OUT2		U2C1. DOUT3		U2C1. HWIN3							CCU43. IN2A	
P4.5		U2C0. SELO3	CCU43. OUT1		U2C1. DOUT2		U2C1. HWIN2							CCU43. IN1A	
P4.6		U2C0. SELO2	CCU43. OUT0		U2C1. DOUT1		U2C1. HWIN1		CAN. NZ_RXDC					CCU43. IN0A	
P4.7		CAN. NZ_TXD			U2C1. DOUT0		U2C1. HWIN0		U2C0. DX0C					CCU43. IN0C	
P5.0	U2C0. DOUT0	DSD. CGPWMM	CCU81. OUT33		U2C0. DOUT0		U2C0. HWIN0		U2C0. DX0B	ETH0. RXD0D	U2C0. DX0D			CCU81. IN0A	CCU81. IN2A
P5.1	U2C0. DOUT0	DSD. CGPWMP	CCU81. OUT32		U2C0. DOUT1		U2C0. HWIN1		U2C0. DX0A	ETH0. RXD1D				CCU81. IN0B	
P5.2	U2C0. SCLKOUT		CCU81. OUT23						U2C0. DX1A	ETH0. CRS_DVD				CCU81. IN1B	ETH0. RXD0D
P5.3	U2C0. SELO0		CCU81. OUT22		EBU. CKE	EBU. A20			U2C0. DX2A	ETH0. RXERD				CCU81. IN2B	
P5.4	U2C0. SELO1		CCU81. OUT13		EBU. RAS	EBU. A21				ETH0. CRSD				CCU81. IN3B	
P5.5	U2C0. SELO2		CCU81. OUT12		EBU. CAS	EBU. A22				ETH0. COLD					
P5.6	U2C0. SELO3		CCU81. OUT03		EBU. BFCKLO	EBU. A23			EBU. BFCLKI						
P5.7			CCU81. OUT02	LEDS0. COLA	U2C0. DOUT2		U2C0. HWIN2								
P5.8		U1C0. SCLKOUT	CCU80. OUT01		EBU. SDCKLO	EBU. CS2			ETH0. RXD2A	U1C0. DX1B					
P5.9		U1C0. SELO0	CCU80. OUT20	ETH0. TX_EN	EBU. BFCKLO	EBU. CS3			ETH0. RXD3A	U1C0. DX2B					
P5.10		U1C0. MCLKOUT	CCU80. OUT10	LEDS0. LINE7	LEDS0. EXTENDED7		LEDS0. TSIN7A		ETH0. CLK_TXA						
P5.11		U1C0. SELO1	CCU80. OUT00						ETH0. CRSA						
P6.0	ETH0. TXD2	U2C1. SELO1	CCU81. OUT31		DB. ETM_TRACECLK	EBU. A16									
P6.1	ETH0. TXD3	U2C1. SELO0	CCU81. OUT30		DB. ETM_TRACEDA TA3	EBU. A17			U2C1. DX2C						
P6.2	ETH0. TXER	U2C1. SCLKOUT	CCU43. OUT3		DB. ETM_TRACEDA TA2	EBU. A18			U2C1. DX1C						
P6.3			CCU43. OUT2						U2C1. DX0C	ETH0. RXD3B					
P6.4		U2C1. DOUT0	CCU43. OUT1		EBU. SDCKLO	EBU. A19			EBU. SDCLKI	ETH0. RXD2B					
P6.5		U2C1. MCLKOUT	CCU43. OUT0		DB. ETM_TRACEDA TA1	EBU. BC2			DSD. DIN3A	ETH0. CLK_RMIIID					ETH0. CLKRXD



**Table 11 Port I/O Functions (cont'd)**

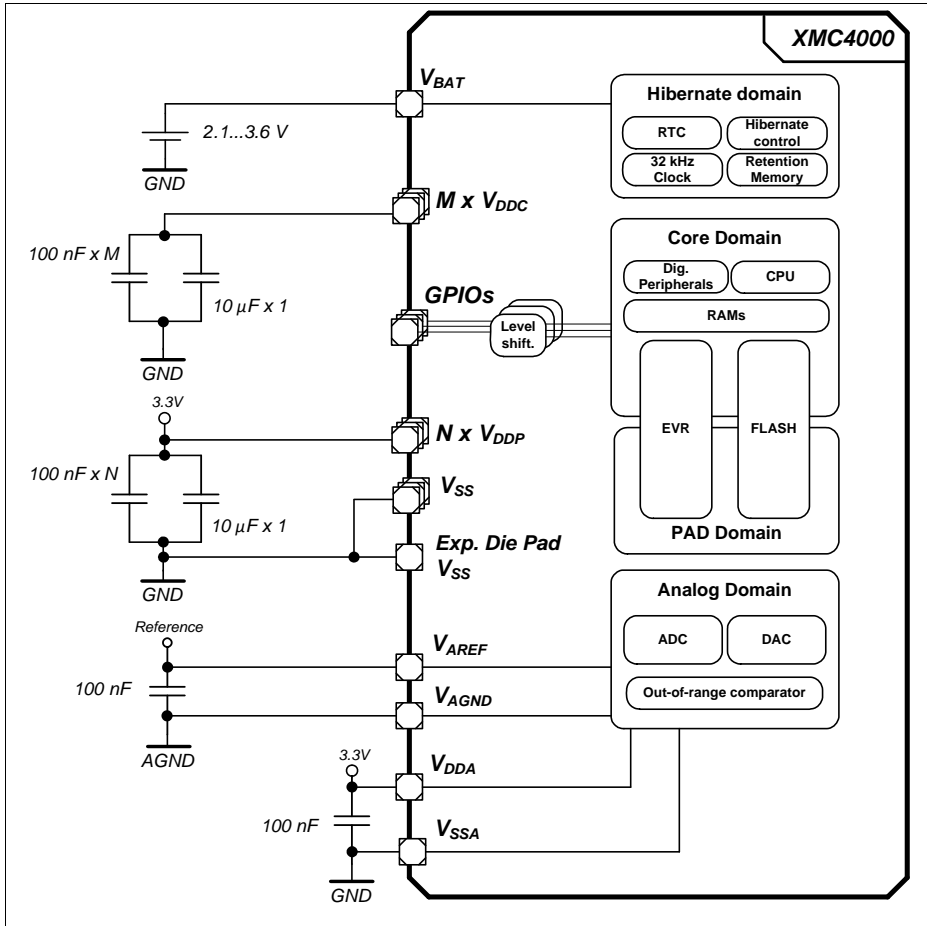
Function	Outputs						Inputs									
	ALT1	ALT2	ALT3	ALT4	HWO0	HWO1	HWI0	HWI1	Input	Input	Input	Input	Input	Input	Input	Input
P6.6			DSD. MCLK3		DE. ETM_TRACEDA TA0	EBU. BC3			DSD. MCLK3A	ETH0. CLK_TXB						
P14.0									VADC. G0CH0							
P14.1									VADC. G0CH1							
P14.2									VADC. G0CH2	VADC. G1CH2						
P14.3									VADC. G0CH3	VADC. G1CH3			CAN. NO_RXDB			
P14.4									VADC. G0CH4		VADC. G2CH0					
P14.5									VADC. G0CH5		VADC. G2CH1		POSIF0. IN2B			
P14.6									VADC. G0CH6				POSIF0. IN1B		G0ORC6	
P14.7									VADC. G0CH7				POSIF0. IN0B		G0ORC7	
P14.8					DAC. OUT_0				VADC. G1CH0		VADC. G3CH2	ETH0. RXD0C				
P14.9					DAC. OUT_1				VADC. G1CH1		VADC. G3CH3	ETH0. RXD1C				
P14.12									VADC. G1CH4							
P14.13									VADC. G1CH5							
P14.14									VADC. G1CH6						G1ORC6	
P14.15									VADC. G1CH7						G1ORC7	
P15.2											VADC. G2CH2					
P15.3											VADC. G2CH3					
P15.4											VADC. G2CH4					
P15.5											VADC. G2CH5					
P15.6											VADC. G2CH6					
P15.7											VADC. G2CH7					
P15.8											VADC. G3CH0	ETH0. CLK_RMIIIC				ETH0. CLKRXIC
P15.9											VADC. G3CH1	ETH0. CRS_DVC				ETH0. RXDVC

**Table 11 Port I/O Functions (cont'd)**

Function	Outputs						Inputs									
	ALT1	ALT2	ALT3	ALT4	HWO0	HWO1	HWI0	HWI1	Input	Input	Input	Input	Input	Input	Input	Input
P15.12												VADC_G3CH4				
P15.13												VADC_G3CH5				
P15.14												VADC_G3CH6				
P15.15												VADC_G3CH7				
USB_DP																
USB_DM																
HIB_IO_0	HIBOUT	WWDT. SERVICE_OUT							WAKEUPA							
HIB_IO_1	HIBOUT	WWDT. SERVICE_OUT							WAKEUPB							
TCK							DB.TCK/ SWCLK									
TMS					DB.TMS/ SWDIO											
PORST																
XTAL1									U0C0. DX0F	U0C1. DX0F	U1C0. DX0F	U1C1. DX0F	U2C0. DX0F	U2C1. DX0F		
XTAL2																
RTC_XTAL1											ERU0. 1B1					
RTC_XTAL2																

### 2.3 Power Connection Scheme

Figure 9. shows a reference power connection scheme for the XMC4500.



**Figure 9 Power Connection Scheme**

Every power supply pin needs to be connected. Different pins of the same supply need also to be externally connected. As example, all  $V_{DDP}$  pins must be connected externally to one  $V_{DDP}$  net. In this reference scheme one 100 nF capacitor is connected at each supply pin against  $V_{SS}$ . An additional 10  $\mu$ F capacitor is connected to the  $V_{DDP}$  nets and an additional 10  $\mu$ F capacitor to the  $V_{DDC}$  nets.

The XMC4500 has a common ground concept, all  $V_{SS}$ ,  $V_{SSA}$  and  $V_{SSO}$  pins share the same ground potential. In packages with an exposed die pad it must be connected to the common ground as well.

$V_{AGND}$  is the low potential to the analog reference  $V_{AREF}$ . Depending on the application it can share the common ground or have a different potential.

When  $V_{DDP}$  is supplied,  $V_{BAT}$  must be supplied as well. If no other supply source (e.g. battery) is connected to  $V_{BAT}$ , the  $V_{BAT}$  pin can also be connected directly to  $V_{DDP}$ .

## **3 Electrical Parameters**

### **3.1 General Parameters**

#### **3.1.1 Parameter Interpretation**

The parameters listed in this section partly represent the characteristics of the XMC4500 and partly its requirements on the system. To aid interpreting the parameters easily when evaluating them for a design, they are marked with a two-letter abbreviation in column "Symbol":

- **CC**  
Such parameters indicate **C**ontroller **C**haracteristics, which are a distinctive feature of the XMC4500 and must be regarded for system design.
- **SR**  
Such parameters indicate **S**ystem **R**equirements, which must be provided by the application system in which the XMC4500 is designed in.

### 3.1.2 Absolute Maximum Ratings

Stresses above the values listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions may affect device reliability.

**Table 12 Absolute Maximum Rating Parameters**

Parameter	Symbol		Values			Unit	Note / Test Condition
			Min.	Typ.	Max.		
Storage temperature	$T_{ST}$	SR	-65	–	150	°C	–
Junction temperature	$T_J$	SR	-40	–	150	°C	–
Voltage at 3.3 V power supply pins with respect to $V_{SS}$	$V_{DDP}$	SR	–	–	4.3	V	–
Voltage on any Class A and dedicated input pin with respect to $V_{SS}$	$V_{IN}$	SR	-1.0	–	$V_{DDP} + 1.0$ or max. 4.3	V	whichever is lower
Voltage on any analog input pin with respect to $V_{AGND}$	$V_{AIN}$ $V_{AREF}$	SR	-1.0	–	$V_{DDP} + 1.0$ or max. 4.3	V	whichever is lower
Input current on any pin during overload condition	$I_{IN}$	SR	-10	–	+10	mA	
Absolute maximum sum of all input circuit currents for one port group during overload condition <sup>1)</sup>	$\Sigma I_{IN}$	SR	-25	–	+25	mA	
Absolute maximum sum of all input circuit currents during overload condition	$\Sigma I_{IN}$	SR	-100	–	+100	mA	

1) The port groups are defined in [Table 16](#).

**Figure 10** explains the input voltage ranges of  $V_{IN}$  and  $V_{AIN}$  and its dependency to the supply level of  $V_{DDP}$ . The input voltage must not exceed 4.3 V, and it must not be more than 1.0 V above  $V_{DDP}$ . For the range up to  $V_{DDP} + 1.0$  V also see the definition of the overload conditions in [Section 3.1.3](#).

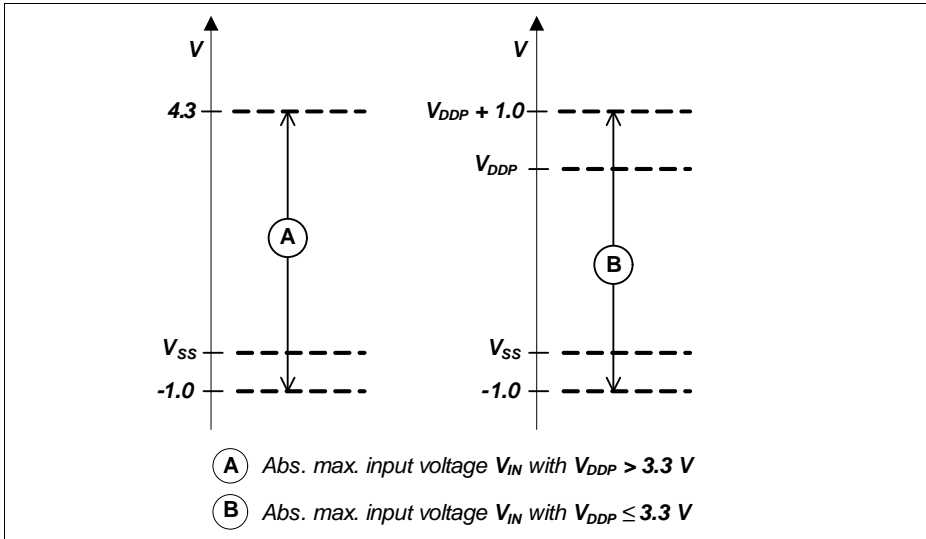


Figure 10 Absolute Maximum Input Voltage Ranges

### 3.1.3 Pin Reliability in Overload

When receiving signals from higher voltage devices, low-voltage devices experience overload currents and voltages that go beyond their own IO power supplies specification.

**Table 13** defines overload conditions that will not cause any negative reliability impact if all the following conditions are met:

- full operation life-time is not exceeded
- **Operating Conditions** are met for
  - pad supply levels ( $V_{DDP}$  or  $V_{DDA}$ )
  - temperature

If a pin current is outside of the **Operating Conditions** but within the overload conditions, then the parameters of this pin as stated in the Operating Conditions can no longer be guaranteed. Operation is still possible in most cases but with relaxed parameters.

*Note: An overload condition on one or more pins does not require a reset.*

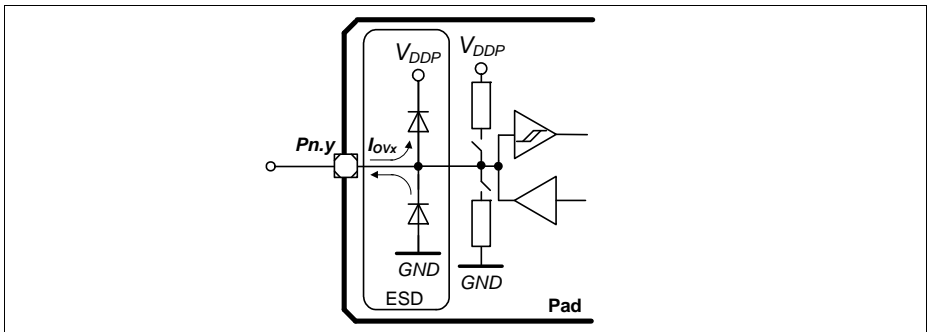
*Note: A series resistor at the pin to limit the current to the maximum permitted overload current is sufficient to handle failure situations like short to battery.*

**Table 13**      **Overload Parameters**

Parameter	Symbol		Values			Unit	Note / Test Condition
			Min.	Typ.	Max.		
Input current on any port pin during overload condition	$I_{OV}$	SR	-5	–	5	mA	
Absolute sum of all input circuit currents for one port group during overload condition <sup>1)</sup>	$I_{OVG}$	SR	–	–	20	mA	$\Sigma  I_{OVx} $ , for all $I_{OVx} < 0$ mA
			–	–	20	mA	$\Sigma  I_{OVx} $ , for all $I_{OVx} > 0$ mA
Absolute sum of all input circuit currents during overload condition	$I_{OVs}$	SR	–	–	80	mA	$\Sigma I_{OVG}$

1) The port groups are defined in [Table 16](#).

**Figure 11** shows the path of the input currents during overload via the ESD protection structures. The diodes against  $V_{DDP}$  and ground are a simplified representation of these ESD protection structures.



**Figure 11**      **Input Overload Current via ESD structures**

[Table 14](#) and [Table 15](#) list input voltages that can be reached under overload conditions. Note that the absolute maximum input voltages as defined in the [Absolute Maximum Ratings](#) must not be exceeded during overload.



**Table 14 PN-Junction Characteristics for positive Overload**

Pad Type	$I_{OV} = 5 \text{ mA}, T_J = -40 \text{ }^\circ\text{C}$	$I_{OV} = 5 \text{ mA}, T_J = 150 \text{ }^\circ\text{C}$
A1 / A1+	$V_{IN} = V_{DDP} + 1.0 \text{ V}$	$V_{IN} = V_{DDP} + 0.75 \text{ V}$
A2	$V_{IN} = V_{DDP} + 0.7 \text{ V}$	$V_{IN} = V_{DDP} + 0.6 \text{ V}$
AN/DIG_IN	$V_{IN} = V_{DDP} + 1.0 \text{ V}$	$V_{IN} = V_{DDP} + 0.75 \text{ V}$

**Table 15 PN-Junction Characteristics for negative Overload**

Pad Type	$I_{OV} = 5 \text{ mA}, T_J = -40 \text{ }^\circ\text{C}$	$I_{OV} = 5 \text{ mA}, T_J = 150 \text{ }^\circ\text{C}$
A1 / A1+	$V_{IN} = V_{SS} - 1.0 \text{ V}$	$V_{IN} = V_{SS} - 0.75 \text{ V}$
A2	$V_{IN} = V_{SS} - 0.7 \text{ V}$	$V_{IN} = V_{SS} - 0.6 \text{ V}$
AN/DIG_IN	$V_{IN} = V_{DDP} - 1.0 \text{ V}$	$V_{IN} = V_{DDP} - 0.75 \text{ V}$

**Table 16 Port Groups for Overload and Short-Circuit Current Sum Parameters**

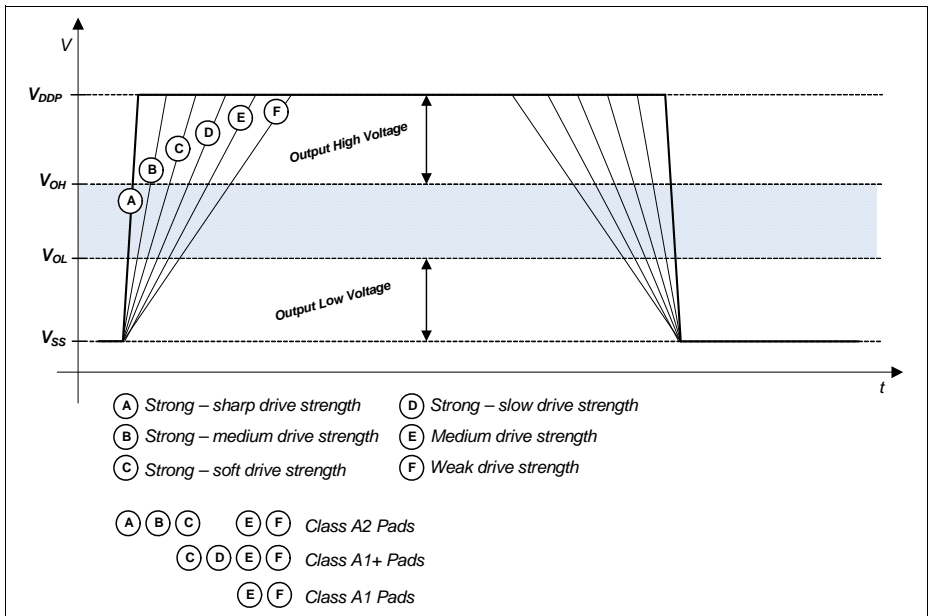
Group	Pins
1	P0.[15:0], P3.[15:0]
2	P14.[15:0], P15.[15:0]
3	P2.[15:0], P5.[11:0]
4	P1.[15:0], P4.[7:0], P6.[6:0]

### 3.1.4 Pad Driver and Pad Classes Summary

This section gives an overview on the different pad driver classes and their basic characteristics.

**Table 17 Pad Driver and Pad Classes Overview**

Class	Power Supply	Type	Sub-Class	Speed Grade	Load	Termination
A	3.3 V	LVTTTL I/O	<b>A1</b> (e.g. GPIO)	6 MHz	100 pF	No
			<b>A1+</b> (e.g. serial I/Os)	25 MHz	50 pF	Series termination recommended
			<b>A2</b> (e.g. ext. Bus)	80 MHz	15 pF	Series termination recommended



**Figure 12 Output Slopes with different Pad Driver Modes**

**Figure 12** is a qualitative display of the resulting output slope performance with different output driver modes. The detailed input and output characteristics are listed in [Section 3.2.1](#).

### 3.1.5 Operating Conditions

The following operating conditions must not be exceeded in order to ensure correct operation and reliability of the XMC4500. All parameters specified in the following sections refer to these operating conditions, unless noted otherwise.

**Table 18 Operating Conditions Parameters**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Ambient Temperature	$T_A$ SR	-40	–	85	°C	Temp. Range F
		-40	–	105	°C	Temp. Range X
		-40	–	125	°C	Temp. Range K
Digital supply voltage	$V_{DDP}$ SR	3.13 <sup>1)</sup>	3.3	3.63 <sup>2)</sup>	V	
Core Supply Voltage	$V_{DDC}$ CC	– <sup>1)</sup>	1.3	–	V	Generated internally
Digital ground voltage	$V_{SS}$ SR	0	–	–	V	
Analog supply voltage	$V_{DDA}$ SR	3.0	3.3	3.6 <sup>2)</sup>	V	
Analog ground voltage for $V_{DDA}$	$V_{SSA}$ SR	-0.1	0	0.1	V	
Battery Supply Voltage for Hibernate Domain	$V_{BAT}$ SR	1.95 <sup>3)</sup>	–	3.63	V	When $V_{DDP}$ is supplied $V_{BAT}$ has to be supplied as well.
System Frequency	$f_{SYS}$ SR	–	–	120	MHz	
Short circuit current of digital outputs	$I_{SC}$ SR	-5	–	5	mA	
Absolute sum of short circuit currents per pin group <sup>4)</sup>	$\Sigma I_{SC\_PG}$ SR	–	–	20	mA	
Absolute sum of short circuit currents of the device	$\Sigma I_{SC\_D}$ SR	–	–	100	mA	

1) See also the Supply Monitoring thresholds. [Section 3.3.2](#).

2) Voltage overshoot to 4.0 V is permissible at Power-Up and  $\overline{PORST}$  low, provided the pulse duration is less than 100  $\mu$ s and the cumulated sum of the pulses does not exceed 1 h over lifetime.

3) To start the hibernate domain it is required that  $V_{BAT} \geq 2.1$  V, for a reliable start of the oscillation of RTC\_XTAL in crystal mode it is required that  $V_{BAT} \geq 3.0$  V.

4) The port groups are defined in [Table 16](#).

## 3.2 DC Parameters

### 3.2.1 Input/Output Pins

The digital input stage of the shared analog/digital input pins is identical to the input stage of the standard digital input/output pins.

The Pull-up on the PORST pin is identical to the Pull-up on the standard digital input/output pins.

*Note: These parameters are not subject to production test, but verified by design and/or characterization.*

**Table 19 Standard Pad Parameters**

Parameter	Symbol	Values		Unit	Note / Test Condition
		Min.	Max.		
Pin capacitance (digital inputs/outputs)	$C_{IO}$ CC	–	10	pF	
Pull-down current	$ I_{PDL} $ CC	150	–	$\mu$ A	<sup>1)</sup> $V_{IN} \geq 0.6 \times V_{DDP}$
		–	10	$\mu$ A	<sup>2)</sup> $V_{IN} \leq 0.36 \times V_{DDP}$
Pull-Up current	$ I_{PUH} $ CC	–	10	$\mu$ A	<sup>2)</sup> $V_{IN} \geq 0.6 \times V_{DDP}$
		100	–	$\mu$ A	<sup>1)</sup> $V_{IN} \leq 0.36 \times V_{DDP}$
Input Hysteresis for pads of all A classes <sup>3)</sup>	$HYS_A$ CC	$0.1 \times V_{DDP}$	–	V	
PORST spike filter always blocked pulse duration	$t_{SF1}$ CC	–	10	ns	
PORST spike filter pass-through pulse duration	$t_{SF2}$ CC	100	–	ns	
PORST pull-down current	$ I_{PPD} $ CC	13	–	mA	$V_{IN} = 1.0$ V

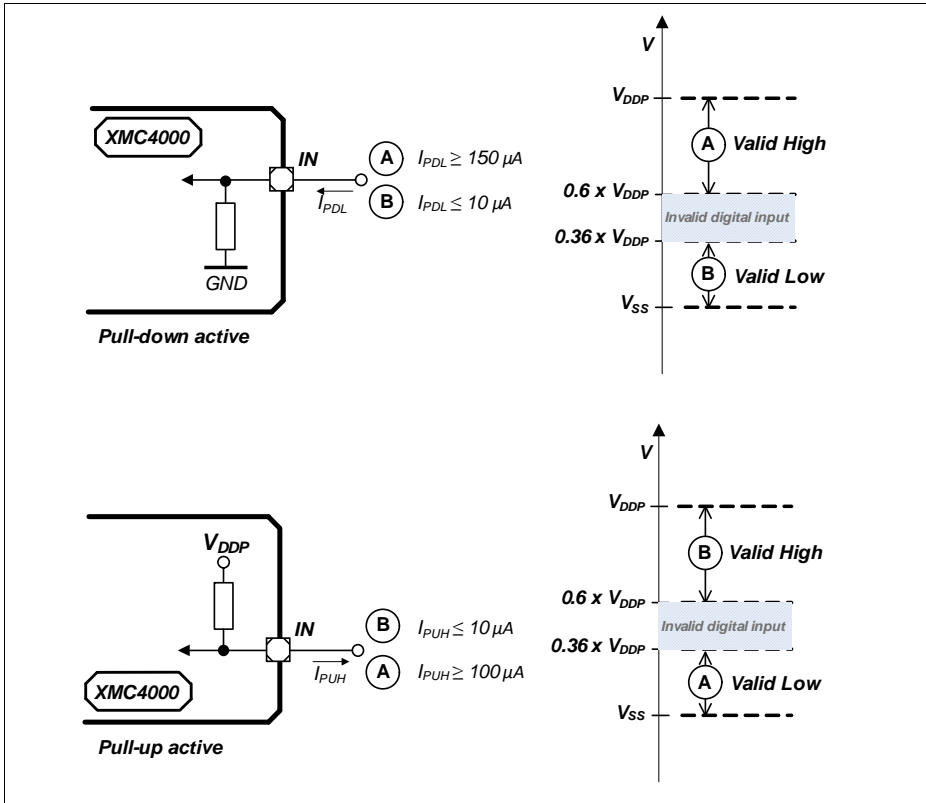
1) Current required to override the pull device with the opposite logic level (“force current”).

With active pull device, at load currents between force and keep current the input state is undefined.

2) Load current at which the pull device still maintains the valid logic level (“keep current”).

With active pull device, at load currents between force and keep current the input state is undefined.

3) Hysteresis is implemented to avoid metastable states and switching due to internal ground bounce. It can not be guaranteed that it suppresses switching due to external system noise.



**Figure 13 Pull Device Input Characteristics**

**Figure 13** visualizes the input characteristics with an active internal pull device:

- in the cases "A" the internal pull device is overridden by a strong external driver;
- in the cases "B" the internal pull device defines the input logical state against a weak external load.

**Table 20 Standard Pads Class\_A1**

Parameter	Symbol	Values		Unit	Note / Test Condition
		Min.	Max.		
Input leakage current	$I_{OZA1}$ CC	-500	500	nA	$0\text{ V} \leq V_{IN} \leq V_{DDP}$
Input high voltage	$V_{IHA1}$ SR	$0.6 \times V_{DDP}$	$V_{DDP} + 0.3$	V	max. 3.6 V
Input low voltage	$V_{ILA1}$ SR	-0.3	$0.36 \times V_{DDP}$	V	
Output high voltage, POD <sup>1)</sup> = weak	$V_{OHA1}$ CC	$V_{DDP} - 0.4$	–	V	$I_{OH} \geq -400\ \mu\text{A}$
		2.4	–	V	$I_{OH} \geq -500\ \mu\text{A}$
Output high voltage, POD <sup>1)</sup> = medium		$V_{DDP} - 0.4$	–	V	$I_{OH} \geq -1.4\ \text{mA}$
		2.4	–	V	$I_{OH} \geq -2\ \text{mA}$
Output low voltage	$V_{OLA1}$ CC	–	0.4	V	$I_{OL} \leq 500\ \mu\text{A}$ ; POD <sup>1)</sup> = weak
		–	0.4	V	$I_{OL} \leq 2\ \text{mA}$ ; POD <sup>1)</sup> = medium
Fall time	$t_{FA1}$ CC	–	150	ns	$C_L = 20\ \text{pF}$ ; POD <sup>1)</sup> = weak
		–	50	ns	$C_L = 50\ \text{pF}$ ; POD <sup>1)</sup> = medium
Rise time	$t_{RA1}$ CC	–	150	ns	$C_L = 20\ \text{pF}$ ; POD <sup>1)</sup> = weak
		–	50	ns	$C_L = 50\ \text{pF}$ ; POD <sup>1)</sup> = medium

1) POD = Pin Out Driver

**Table 21 Standard Pads Class\_A1+**

Parameter	Symbol	Values		Unit	Note / Test Condition
		Min.	Max.		
Input leakage current	$I_{OZA1+}$ CC	-1	1	$\mu\text{A}$	$0\text{ V} \leq V_{IN} \leq V_{DDP}$
Input high voltage	$V_{IHA1+}$ SR	$0.6 \times V_{DDP}$	$V_{DDP} + 0.3$	V	max. 3.6 V
Input low voltage	$V_{ILA1+}$ SR	-0.3	$0.36 \times V_{DDP}$	V	

**Electrical Parameters**
**Table 21 Standard Pads Class\_A1+**

Parameter	Symbol	Values		Unit	Note / Test Condition	
		Min.	Max.			
Output high voltage, POD <sup>1)</sup> = weak	$V_{\text{OHA1+}}$ CC	$V_{\text{DDP}} - 0.4$	–	V	$I_{\text{OH}} \geq -400 \mu\text{A}$	
		2.4	–	V	$I_{\text{OH}} \geq -500 \mu\text{A}$	
Output high voltage, POD <sup>1)</sup> = medium		$V_{\text{DDP}} - 0.4$	–	V	$I_{\text{OH}} \geq -1.4 \text{ mA}$	
		2.4	–	V	$I_{\text{OH}} \geq -2 \text{ mA}$	
Output high voltage, POD <sup>1)</sup> = strong		$V_{\text{DDP}} - 0.4$	–	V	$I_{\text{OH}} \geq -1.4 \text{ mA}$	
		2.4	–	V	$I_{\text{OH}} \geq -2 \text{ mA}$	
Output low voltage		$V_{\text{OLA1+}}$ CC	–	0.4	V	$I_{\text{OL}} \leq 500 \mu\text{A}$ ; POD <sup>1)</sup> = weak
			–	0.4	V	$I_{\text{OL}} \leq 2 \text{ mA}$ ; POD <sup>1)</sup> = medium
	–		0.4	V	$I_{\text{OL}} \leq 2 \text{ mA}$ ; POD <sup>1)</sup> = strong	
Fall time	$t_{\text{FA1+}}$ CC	–	150	ns	$C_{\text{L}} = 20 \text{ pF}$ ; POD <sup>1)</sup> = weak	
		–	50	ns	$C_{\text{L}} = 50 \text{ pF}$ ; POD <sup>1)</sup> = medium	
		–	28	ns	$C_{\text{L}} = 50 \text{ pF}$ ; POD <sup>1)</sup> = strong; edge = slow	
		–	16	ns	$C_{\text{L}} = 50 \text{ pF}$ ; POD <sup>1)</sup> = strong; edge = soft;	
Rise time	$t_{\text{RA1+}}$ CC	–	150	ns	$C_{\text{L}} = 20 \text{ pF}$ ; POD <sup>1)</sup> = weak	
		–	50	ns	$C_{\text{L}} = 50 \text{ pF}$ ; POD <sup>1)</sup> = medium	
		–	28	ns	$C_{\text{L}} = 50 \text{ pF}$ ; POD <sup>1)</sup> = strong; edge = slow	
		–	16	ns	$C_{\text{L}} = 50 \text{ pF}$ ; POD <sup>1)</sup> = strong; edge = soft	

1) POD = Pin Out Driver

**Table 22 Standard Pads Class\_A2**

Parameter	Symbol	Values		Unit	Note / Test Condition
		Min.	Max.		
Input Leakage current	$I_{OZA2}$ CC	-6	6	$\mu\text{A}$	$0\text{ V} \leq V_{IN} < 0.5 \cdot V_{DDP} - 1\text{ V};$ $0.5 \cdot V_{DDP} + 1\text{ V} < V_{IN} \leq V_{DDP}$
		-3	3	$\mu\text{A}$	$0.5 \cdot V_{DDP} - 1\text{ V} < V_{IN} < 0.5 \cdot V_{DDP} + 1\text{ V}$
Input high voltage	$V_{IHA2}$ SR	$0.6 \times V_{DDP}$	$V_{DDP} + 0.3$	V	max. 3.6 V
Input low voltage	$V_{ILA2}$ SR	-0.3	$0.36 \times V_{DDP}$	V	
Output high voltage, POD = weak	$V_{OHA2}$ CC	$V_{DDP} - 0.4$	-	V	$I_{OH} \geq -400\ \mu\text{A}$
		2.4	-	V	$I_{OH} \geq -500\ \mu\text{A}$
Output high voltage, POD = medium		$V_{DDP} - 0.4$	-	V	$I_{OH} \geq -1.4\ \text{mA}$
		2.4	-	V	$I_{OH} \geq -2\ \text{mA}$
Output high voltage, POD = strong		$V_{DDP} - 0.4$	-	V	$I_{OH} \geq -1.4\ \text{mA}$
		2.4	-	V	$I_{OH} \geq -2\ \text{mA}$
Output low voltage, POD = weak	$V_{OLA2}$ CC	-	0.4	V	$I_{OL} \leq 500\ \mu\text{A}$
Output low voltage, POD = medium		-	0.4	V	$I_{OL} \leq 2\ \text{mA}$
Output low voltage, POD = strong		-	0.4	V	$I_{OL} \leq 2\ \text{mA}$



**Electrical Parameters**

**Table 22 Standard Pads Class\_A2**

Parameter	Symbol	Values		Unit	Note / Test Condition
		Min.	Max.		
Fall time	$t_{FA2}$ CC	–	150	ns	$C_L = 20$ pF; POD = weak
		–	50	ns	$C_L = 50$ pF; POD = medium
		–	3.7	ns	$C_L = 50$ pF; POD = strong; edge = sharp
		–	7	ns	$C_L = 50$ pF; POD = strong; edge = medium
		–	16	ns	$C_L = 50$ pF; POD = strong; edge = soft
Rise time	$t_{RA2}$ CC	–	150	ns	$C_L = 20$ pF; POD = weak
		–	50	ns	$C_L = 50$ pF; POD = medium
		–	3.7	ns	$C_L = 50$ pF; POD = strong; edge = sharp
		–	7.0	ns	$C_L = 50$ pF; POD = strong; edge = medium
		–	16	ns	$C_L = 50$ pF; POD = strong; edge = soft

### 3.2.2 Analog to Digital Converters (VADC)

Note: These parameters are not subject to production test, but verified by design and/or characterization.

**Table 23 VADC Parameters (Operating Conditions apply)**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Analog reference voltage <sup>5)</sup>	$V_{AREF}$ SR	$V_{AGND} + 1$	–	$V_{DDA} + 0.05^{1)}$	V	
Analog reference ground <sup>5)</sup>	$V_{AGND}$ SR	$V_{SSM} - 0.05$	–	$V_{AREF} - 1$	V	
Analog reference voltage range <sup>2)5)</sup>	$V_{AREF} - V_{AGND}$ SR	1	–	$V_{DDA} + 0.1$	V	
Analog input voltage	$V_{AIN}$ SR	$V_{AGND}$	–	$V_{DDA}$	V	
Input leakage at analog inputs <sup>3)</sup>	$I_{OZ1}$ CC	-100	–	200	nA	$0.03 \times V_{DDA} < V_{AIN} < 0.97 \times V_{DDA}$
		-500	–	100	nA	$0 \text{ V} \leq V_{AIN} \leq 0.03 \times V_{DDA}$
		-100	–	500	nA	$0.97 \times V_{DDA} \leq V_{AIN} \leq V_{DDA}$
Input leakage current at VAREF	$I_{OZ2}$ CC	-1	–	1	μA	$0 \text{ V} \leq V_{AREF} \leq V_{DDA}$
Input leakage current at VAGND	$I_{OZ3}$ CC	-1	–	1	μA	$0 \text{ V} \leq V_{AGND} \leq V_{DDA}$
Internal ADC clock	$f_{ADCI}$ CC	2	–	30	MHz	$V_{DDA} = 3.3 \text{ V}$
Switched capacitance at the analog voltage inputs <sup>4)</sup>	$C_{AINSW}$ CC	–	7	20	pF	
Total capacitance of an analog input	$C_{AINTOT}$ CC	–	25	30	pF	
Switched capacitance at the positive reference voltage input <sup>5)6)</sup>	$C_{AREFSW}$ CC	–	15	30	pF	
Total capacitance of the voltage reference inputs <sup>5)</sup>	$C_{AREFTOT}$ CC	–	20	40	pF	

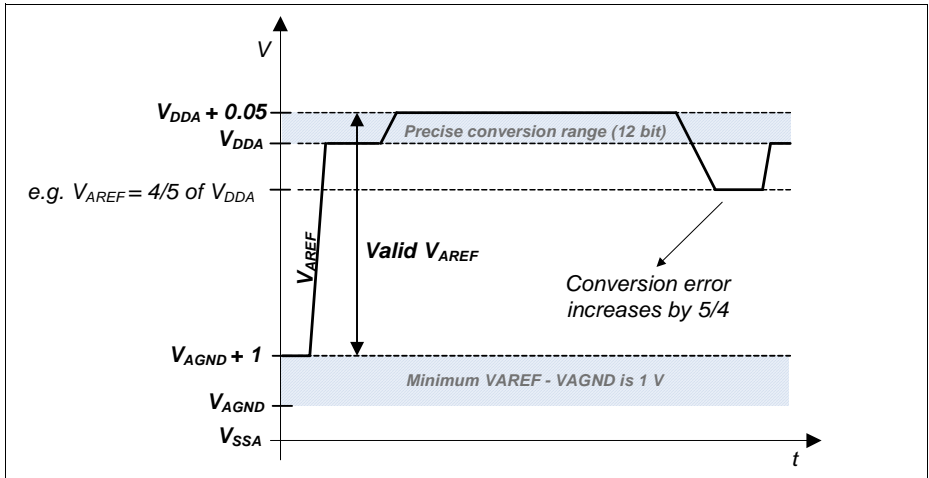
**Electrical Parameters**
**Table 23 VADC Parameters (Operating Conditions apply)**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Total Unadjusted Error	$TUE_{CC}$	-4	–	4	LSB	12-bit resolution; $V_{DDA} = 3.3\text{ V}$ ; $V_{AREF} = V_{DDA}$ <sup>7)</sup>
Differential Non-Linearity Error <sup>8)</sup>	$EA_{DNL_{CC}}$	-3	–	3	LSB	
Gain Error <sup>8)</sup>	$EA_{GAIN_{CC}}$	-4	–	4	LSB	
Integral Non-Linearity <sup>8)</sup>	$EA_{INL_{CC}}$	-3	–	3	LSB	
Offset Error <sup>8)</sup>	$EA_{OFF_{CC}}$	-4	–	4	LSB	
RMS Noise <sup>9)</sup>	$EN_{RMS_{CC}}$	–	1	2 <sup>10/11)</sup>	LSB	
Worst case ADC $V_{DDA}$ power supply current per active converter	$I_{DDAA_{CC}}$	–	1.5	2	mA	during conversion $V_{DDP} = 3.6\text{ V}$ , $T_J = 150\text{ °C}$
Charge consumption on $V_{AREF}$ per conversion <sup>5)</sup>	$Q_{CONV_{CC}}$	–	30	–	pC	$0\text{ V} \leq V_{AREF} \leq V_{DDA}$ <sup>12)</sup>
ON resistance of the analog input path	$R_{AIN_{CC}}$	–	700	1 700	Ohm	
ON resistance for the ADC test (pull down for AIN7)	$R_{AIN7T_{CC}}$	180	550	900	Ohm	
Resistance of the reference voltage input path	$R_{AREF_{CC}}$	–	700	1 700	Ohm	

- 1) A running conversion may become imprecise in case the normal conditions are violated (voltage overshoot).
- 2) If the analog reference voltage is below  $V_{DDA}$ , then the ADC converter errors increase. If the reference voltage is reduced by the factor k ( $k < 1$ ), TUE, DNL, INL, Gain, and Offset errors increase also by the factor 1/k.
- 3) The leakage current definition is a continuous function, as shown in figure ADCx Analog Inputs Leakage. The numerical values defined determine the characteristic points of the given continuous linear approximation - they do not define step function (see [Figure 16](#)).
- 4) The sampling capacity of the conversion C-network is pre-charged to  $V_{AREF}/2$  before the sampling moment. Because of the parasitic elements, the voltage measured at AINx can deviate from  $V_{AREF}/2$ .
- 5) Applies to AINx, when used as alternate reference input.
- 6) This represents an equivalent switched capacitance. This capacitance is not switched to the reference voltage at once. Instead, smaller capacitances are successively switched to the reference voltage.
- 7) For 10-bit conversions, the errors are reduced to 1/4; for 8-bit conversions, the errors are reduced to 1/16. Never less than  $\pm 1$  LSB.
- 8) The sum of DNL/INL/GAIN/OFF errors does not exceed the related total unadjusted error TUE.

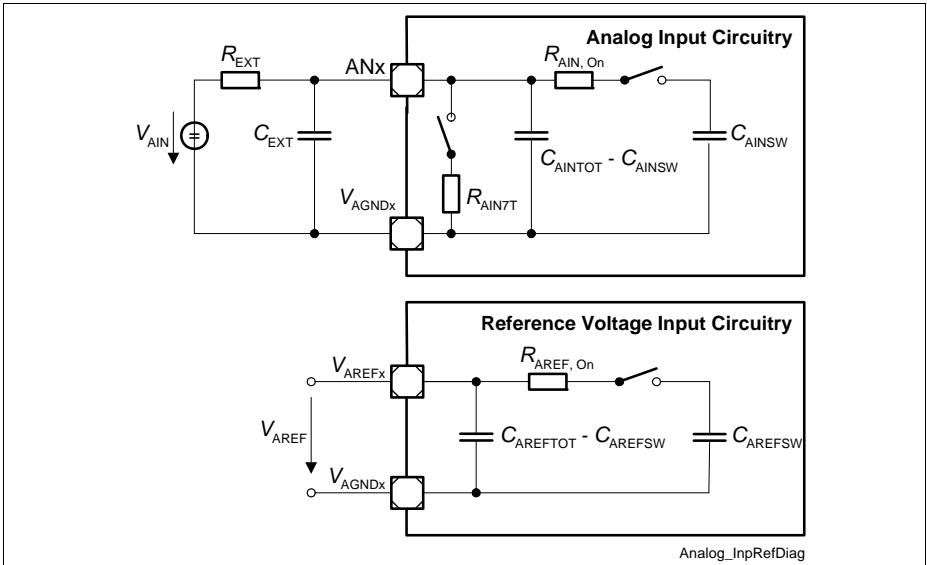
**Electrical Parameters**

- 9) This parameter is valid for soldered devices and requires careful analog board design.
- 10) Resulting worst case combined error is arithmetic combination of TUE and  $EN_{RMS}$ .
- 11) Value is defined for one sigma Gauss distribution.
- 12) The resulting current for a conversion can be calculated with  $I_{AREF} = Q_{CONV} / t_c$ .  
The fastest 12-bit post-calibrated conversion of  $t_c = 550$  ns results in a typical average current of  $I_{AREF} = 54.5$   $\mu$ A.

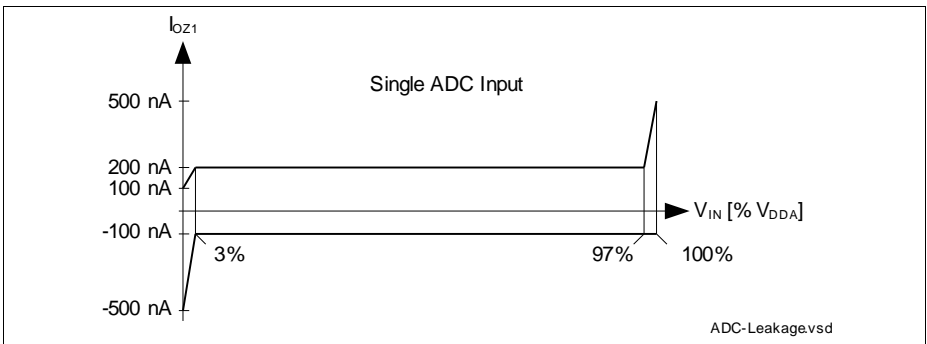


**Figure 14 VADC Reference Voltage Range**

The power-up calibration of the VADC requires a maximum number of  $4 \cdot 352 \cdot f_{ADCI}$  cycles.



**Figure 15 VADC Input Circuits**



**Figure 16 VADC Analog Input Leakage Current**

## Conversion Time

**Table 24 Conversion Time** (Operating Conditions apply)

Parameter	Symbol	Values	Unit	Note
Conversion time	$t_C$ CC	$2 \times T_{ADC} + (2 + N + STC + PC + DM) \times T_{ADCI}$	$\mu\text{s}$	N = 8, 10, 12 for N-bit conversion $T_{ADC} = 1 / f_{PERIPH}$ $T_{ADCI} = 1 / f_{ADCI}$

- STC defines additional clock cycles to extend the sample time
- PC adds two cycles if post-calibration is enabled
- DM adds one cycle for an extended conversion time of the MSB

### Conversion Time Examples

System assumptions:

$f_{ADC} = 120 \text{ MHz}$  i.e.  $t_{ADC} = 8.33 \text{ ns}$ ,  $DIVA = 3$ ,  $f_{ADCI} = 30 \text{ MHz}$  i.e.  $t_{ADCI} = 33.3 \text{ ns}$

According to the given formulas the following minimum conversion times can be achieved (STC = 0, DM = 0):

12-bit post-calibrated conversion (PC = 2):

$$t_{CN12C} = (2 + 12 + 2) \times t_{ADCI} + 2 \times t_{ADC} = 16 \times 33.3 \text{ ns} + 2 \times 8.33 \text{ ns} = 550 \text{ ns}$$

12-bit uncalibrated conversion:

$$t_{CN12} = (2 + 12) \times t_{ADCI} + 2 \times t_{ADC} = 14 \times 33.3 \text{ ns} + 2 \times 8.33 \text{ ns} = 483 \text{ ns}$$

10-bit uncalibrated conversion:

$$t_{CN10} = (2 + 10) \times t_{ADCI} + 2 \times t_{ADC} = 12 \times 33.3 \text{ ns} + 2 \times 8.33 \text{ ns} = 417 \text{ ns}$$

8-bit uncalibrated:

$$t_{CN8} = (2 + 8) \times t_{ADCI} + 2 \times t_{ADC} = 10 \times 33.3 \text{ ns} + 2 \times 8.33 \text{ ns} = 350 \text{ ns}$$

### 3.2.3 Digital to Analog Converters (DAC)

*Note: These parameters are not subject to production test, but verified by design and/or characterization.*

**Electrical Parameters**
**Table 25 DAC Parameters (Operating Conditions apply)**

Parameter	Symbol	CC	Values			Unit	Note / Test Condition
			Min.	Typ.	Max.		
RMS supply current	$I_{DD}$	CC	–	2.5	4	mA	per active DAC channel, without load currents of DAC outputs
Resolution	$RES$	CC	–	12	–	Bit	
Update rate	$f_{URATE\_A}$	CC	–		2	Msample/s	data rate, where DAC can follow 64 LSB code jumps to $\pm 1$ LSB accuracy
Update rate	$f_{URATE\_F}$	CC	–		5	Msample/s	data rate, where DAC can follow 64 LSB code jumps to $\pm 4$ LSB accuracy
Settling time	$t_{SETTLE}$	CC	–	1	2	$\mu$ s	at full scale jump, output voltage reaches target value $\pm 20$ LSB
Slew rate	$SR$	CC	2	5	–	V/ $\mu$ s	
Minimum output voltage	$V_{OUT\_MIN}$	CC	–	0.3	–	V	code value unsigned: 000 <sub>H</sub> ; signed: 800 <sub>H</sub>
Maximum output voltage	$V_{OUT\_MAX}$	CC	–	2.5	–	V	code value unsigned: FFF <sub>H</sub> ; signed: 7FF <sub>H</sub>
Integral non-linearity	$INL$	CC	-4	$\pm 2.5$	4	LSB	$R_L \geq 5$ kOhm, $C_L \leq 50$ pF
Differential non-linearity	$DNL$	CC	-2	$\pm 1$	2	LSB	$R_L \geq 5$ kOhm, $C_L \leq 50$ pF
Offset error	$ED_{OFF}$	CC		$\pm 20$		mV	
Gain error	$ED_{G\_IN}$	CC	-6.5	-1.5	3	%	
Startup time	$t_{STARTUP}$	CC	–	15	30	$\mu$ s	time from output enabling till code valid $\pm 16$ LSB

**Electrical Parameters**

**Table 25 DAC Parameters (Operating Conditions apply) (cont'd)**

Parameter	Symbol		Values			Unit	Note / Test Condition
			Min.	Typ.	Max.		
3dB Bandwidth of Output Buffer	$f_{C1}$	CC	2.5	5	–	MHz	verified by design
Output sourcing current	$I_{OUT\_SOURCE}$	CC	–	-30	–	mA	
Output sinking current	$I_{OUT\_SINK}$	CC	–	0.6	–	mA	
Output resistance	$R_{OUT}$	CC	–	50	–	Ohm	
Load resistance	$R_L$	SR	5	–	–	kOhm	
Load capacitance	$C_L$	SR	–	–	50	pF	
Signal-to-Noise Ratio	SNR	CC	–	70	–	dB	examination bandwidth < 25 kHz
Total Harmonic Distortion	THD	CC	–	70	–	dB	examination bandwidth < 25 kHz
Power Supply Rejection Ratio	PSRR	CC	–	56	–	dB	to $V_{DDA}$ verified by design

**Conversion Calculation**

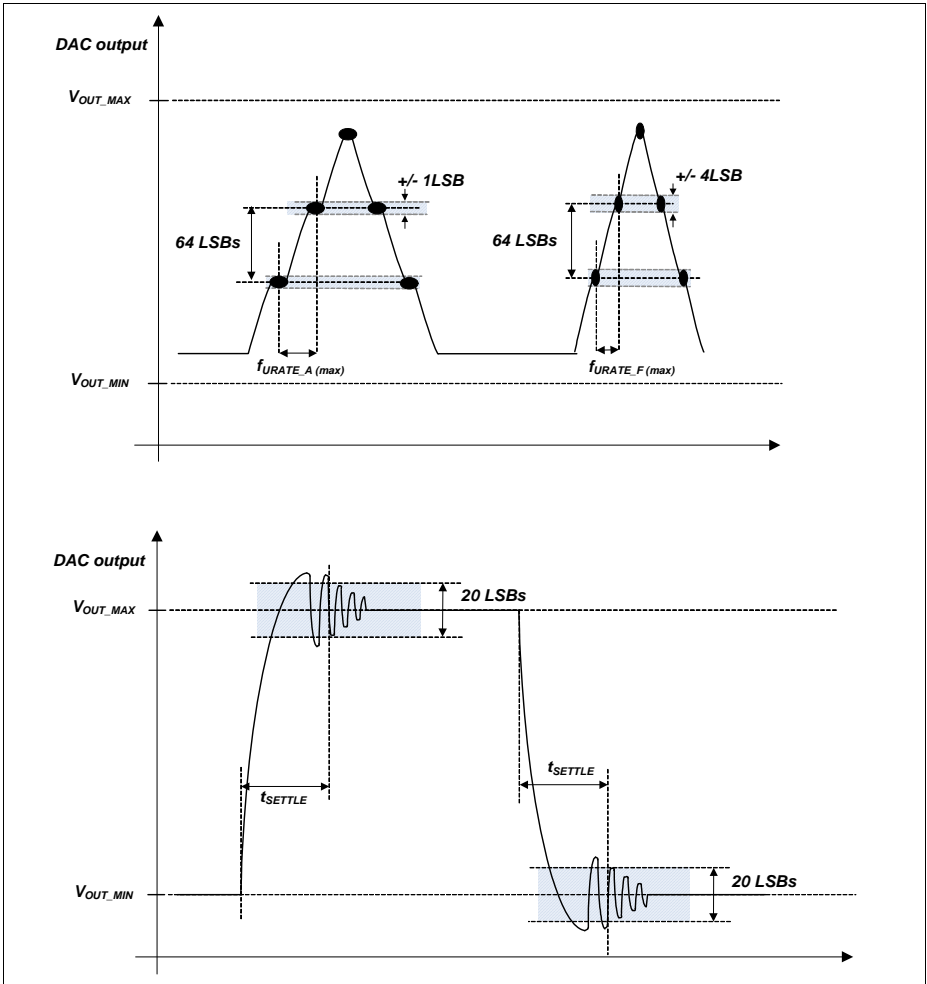
Unsigned:

$$DACxDATA = 4095 \times (V_{OUT} - V_{OUT\_MIN}) / (V_{OUT\_MAX} - V_{OUT\_MIN})$$

Signed:

$$DACxDATA = 4095 \times (V_{OUT} - V_{OUT\_MIN}) / (V_{OUT\_MAX} - V_{OUT\_MIN}) - 2048$$





**Figure 17 DAC Conversion Examples**

### 3.2.4 Out-of-Range Comparator (ORC)

The Out-of-Range Comparator (ORC) triggers on analog input voltages ( $V_{AIN}$ ) above the analog reference<sup>1)</sup> ( $V_{AREF}$ ) on selected input pins (GxORCy) and generates a service request trigger (GxORCOUTy).

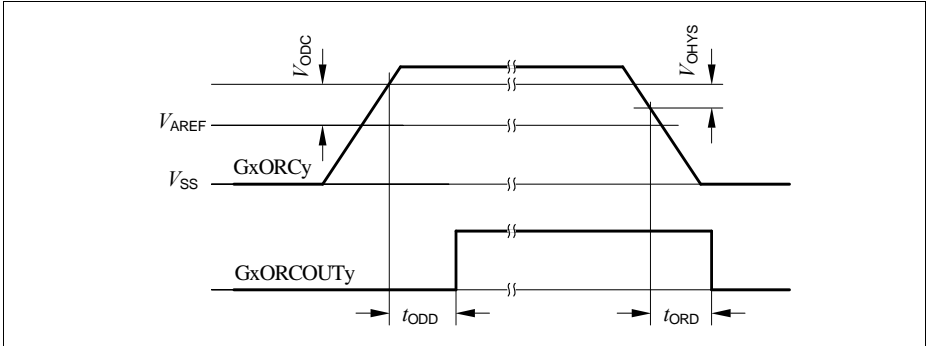
*Note: These parameters are not subject to production test, but verified by design and/or characterization.*

The parameters in **Table 26** apply for the maximum reference voltage  $V_{AREF} = V_{DDA} + 50$  mV.

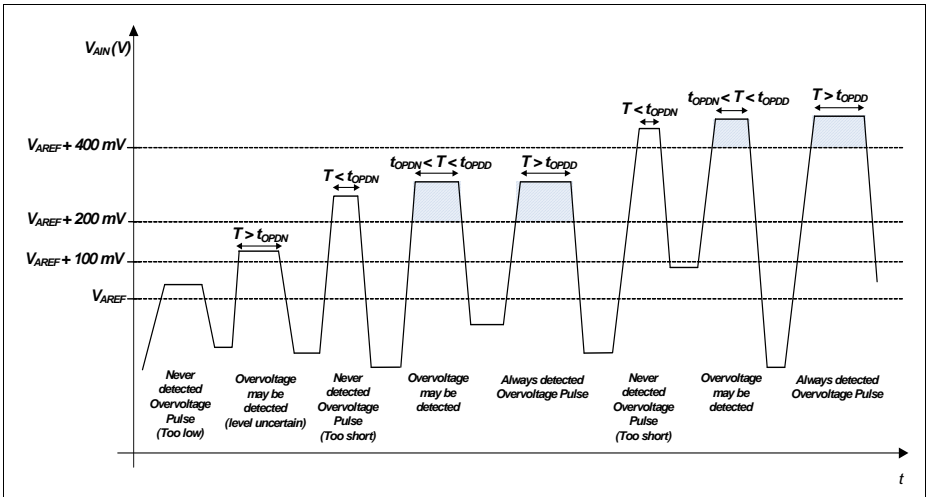
**Table 26 ORC Parameters** (Operating Conditions apply)

Parameter	Symbol		Values			Unit	Note / Test Condition
			Min.	Typ.	Max.		
DC Switching Level	$V_{ODC}$	CC	100	125	200	mV	$V_{AIN} \geq V_{AREF} + V_{ODC}$
Hysteresis	$V_{OHYS}$	CC	50	–	$V_{ODC}$	mV	
Detection Delay of a persistent Overvoltage	$t_{ODD}$	CC	55	–	450	ns	$V_{AIN} \geq V_{AREF} + 200$ mV
			45	–	105	ns	$V_{AIN} \geq V_{AREF} + 400$ mV
Always detected Overvoltage Pulse	$t_{OPDD}$	CC	440	–	–	ns	$V_{AIN} \geq V_{AREF} + 200$ mV
			90	–	–	ns	$V_{AIN} \geq V_{AREF} + 400$ mV
Never detected Overvoltage Pulse	$t_{OPDN}$	CC	–	–	49	ns	$V_{AIN} \geq V_{AREF} + 200$ mV
			–	–	30	ns	$V_{AIN} \geq V_{AREF} + 400$ mV
Release Delay	$t_{ORD}$	CC	65	–	105	ns	$V_{AIN} \leq V_{AREF}$
Enable Delay	$t_{OED}$	CC	–	100	200	ns	

1) Always the standard VADC reference, alternate references do not apply to the ORC.



**Figure 18 GxORCOUTy Trigger Generation**



**Figure 19 ORC Detection Ranges**

### 3.2.5 Die Temperature Sensor

The Die Temperature Sensor (DTS) measures the junction temperature  $T_J$ .

*Note: These parameters are not subject to production test, but verified by design and/or characterization.*

**Table 27 Die Temperature Sensor Parameters**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Temperature sensor range	$T_{SR}$ SR	-40	–	150	°C	
Linearity Error (to the below defined formula)	$\Delta T_{LE}$ CC	–	±1	–	°C	per $\Delta T_J \leq 30$ °C
Offset Error	$\Delta T_{OE}$ CC	–	±6	–	°C	$\Delta T_{OE} = T_J - T_{DTS}$ $V_{DDP} \leq 3.3$ V <sup>1)</sup>
Measurement time	$t_M$ CC	–	–	100	µs	
Start-up time after reset inactive	$t_{TSST}$ SR	–	–	10	µs	

1) At  $V_{DDP\_max} = 3.63$  V the typical offset error increases by an additional  $\Delta T_{OE} = \pm 1$  °C.

The following formula calculates the temperature measured by the DTS in [°C] from the RESULT bit field of the DTSSTAT register.

$$\text{Temperature } T_{DTS} = (\text{RESULT} - 605) / 2.05 \text{ [°C]}$$

This formula and the values defined in [Table 27](#) apply with the following calibration values:

- DTSCON.BGTRIM = 8<sub>H</sub>
- DTSCON.REFTRIM = 4<sub>H</sub>

### 3.2.6 USB OTG Interface DC Characteristics

The Universal Serial Bus (USB) Interface is compliant to the USB Rev. 2.0 Specification and the OTG Specification Rev. 1.3. High-Speed Mode is not supported.

*Note: These parameters are not subject to production test, but verified by design and/or characterization.*

**Table 28 USB OTG VBUS and ID Parameters (Operating Conditions apply)**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
VBUS input voltage range	$V_{IN}$ CC	0.0	–	5.25	V	
A-device VBUS valid threshold	$V_{B1}$ CC	4.4	–	–	V	
A-device session valid threshold	$V_{B2}$ CC	0.8	–	2.0	V	
B-device session valid threshold	$V_{B3}$ CC	0.8	–	4.0	V	
B-device session end threshold	$V_{B4}$ CC	0.2	–	0.8	V	
VBUS input resistance to ground	$R_{VBUS\_IN}$ CC	40	–	100	kOhm	
B-device VBUS pull-up resistor	$R_{VBUS\_PU}$ CC	281	–	–	Ohm	Pull-up voltage = 3.0 V
B-device VBUS pull-down resistor	$R_{VBUS\_PD}$ CC	656	–	–	Ohm	
USB.ID pull-up resistor	$R_{UID\_PU}$ CC	14	–	25	kOhm	
VBUS input current	$I_{VBUS\_IN}$ CC	–	–	150	$\mu$ A	$0\text{ V} \leq V_{IN} \leq 5.25\text{ V}$ : $T_{AVG} = 1\text{ ms}$

**Table 29 USB OTG Data Line (USB\_DP, USB\_DM) Parameters** (Operating Conditions apply)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input low voltage	$V_{IL}$ SR	–	–	0.8	V	
Input high voltage (driven)	$V_{IH}$ SR	2.0	–	–	V	
Input high voltage (floating) <sup>1)</sup>	$V_{IHZ}$ SR	2.7	–	3.6	V	
Differential input sensitivity	$V_{DIS}$ CC	0.2	–	–	V	
Differential common mode range	$V_{CM}$ CC	0.8	–	2.5	V	
Output low voltage	$V_{OL}$ CC	0.0	–	0.3	V	1.5 kOhm pull-up to 3.6 V
Output high voltage	$V_{OH}$ CC	2.8	–	3.6	V	15 kOhm pull-down to 0 V
DP pull-up resistor (idle bus)	$R_{PUI}$ CC	900	–	1 575	Ohm	
DP pull-up resistor (upstream port receiving)	$R_{PUA}$ CC	1 425	–	3 090	Ohm	
DP, DM pull-down resistor	$R_{PD}$ CC	14.25	–	24.8	kOhm	
Input impedance DP, DM	$Z_{INP}$ CC	300	–	–	kOhm	$0 V \leq V_{IN} \leq V_{DDP}$
Driver output resistance DP, DM	$Z_{DRV}$ CC	28	–	44	Ohm	

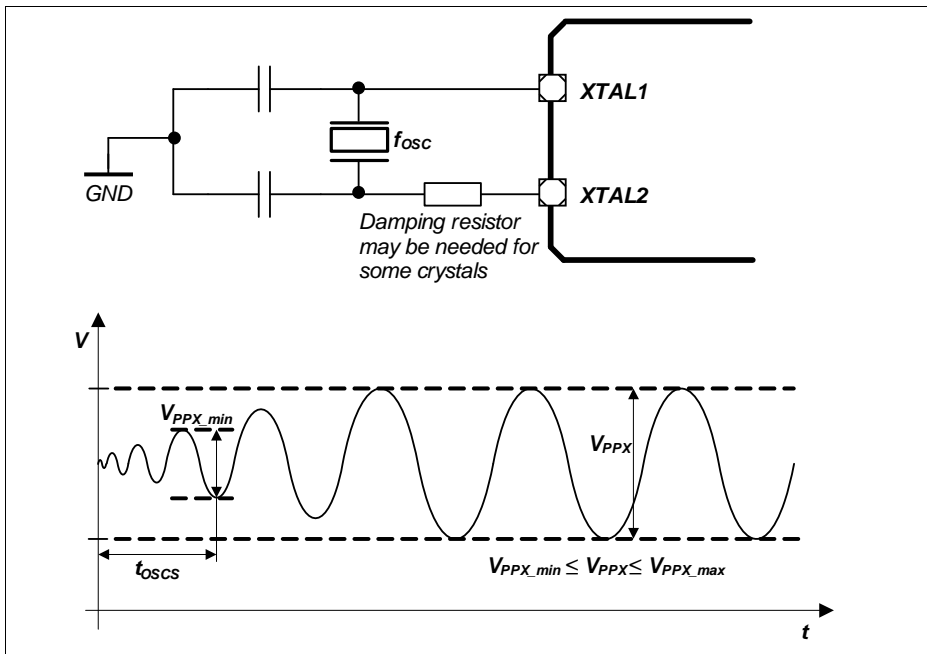
1) Measured at A-connector with 1.5 kOhm  $\pm$  5% to 3.3 V  $\pm$  0.3 V connected to USB\_DP or USB\_DM and at B-connector with 15 kOhm  $\pm$  5% to ground connected to USB\_DP and USB\_DM.

### 3.2.7 Oscillator Pins

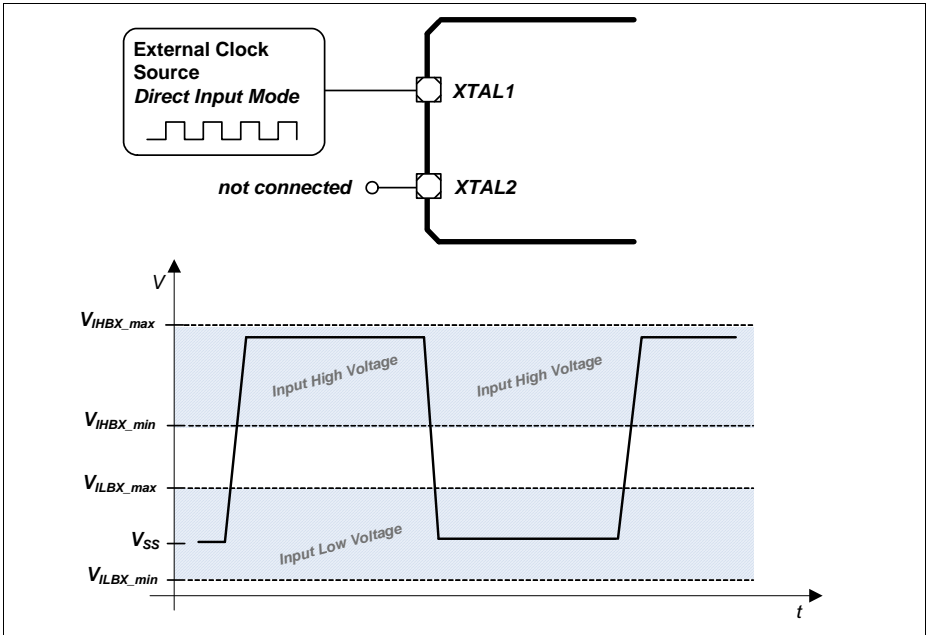
*Note: It is strongly recommended to measure the oscillation allowance (negative resistance) in the final target system (layout) to determine the optimal parameters for the oscillator operation. Please refer to the limits specified by the crystal or ceramic resonator supplier.*

*Note: These parameters are not subject to production test, but verified by design and/or characterization.*

The oscillator pins can be operated with an external crystal (see [Figure 20](#)) or in direct input mode (see [Figure 21](#)).



**Figure 20 Oscillator in Crystal Mode**



**Figure 21 Oscillator in Direct Input Mode**



**Table 30 OSC\_XTAL Parameters**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input frequency	$f_{\text{OSC}}$ SR	4	–	40	MHz	Direct Input Mode selected
		4	–	25	MHz	External Crystal Mode selected
Oscillator start-up time <sup>1)2)</sup>	$t_{\text{OSCS}}$ CC	–	–	10	ms	
Input voltage at XTAL1	$V_{\text{IX}}$ SR	-0.5	–	$V_{\text{DDP}} + 0.5$	V	
Input amplitude (peak-to-peak) at XTAL1 <sup>2)3)</sup>	$V_{\text{PPX}}$ SR	$0.4 \times V_{\text{DDP}}$	–	$V_{\text{DDP}} + 1.0$	V	
Input high voltage at XTAL1 <sup>4)</sup>	$V_{\text{IHBX}}$ SR	1.0	–	$V_{\text{DDP}} + 0.5$	V	
Input low voltage at XTAL1 <sup>4)</sup>	$V_{\text{ILBX}}$ SR	-0.5	–	0.4	V	
Input leakage current at XTAL1	$I_{\text{ILX1}}$ CC	-100	–	100	nA	Oscillator power down $0 \text{ V} \leq V_{\text{IX}} \leq V_{\text{DDP}}$

1)  $t_{\text{OSCS}}$  is defined from the moment the oscillator is enabled with SCU\_OSCHPCTRL.MODE until the oscillations reach an amplitude at XTAL1 of  $0.4 * V_{\text{DDP}}$ .

2) The external oscillator circuitry must be optimized by the customer and checked for negative resistance and amplitude as recommended and specified by crystal suppliers.

3) If the shaper unit is enabled and not bypassed.

4) If the shaper unit is bypassed, dedicated DC-thresholds have to be met.

**Table 31 RTC\_XTAL Parameters**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input frequency	$f_{OSC}$ SR	–	32.768	–	kHz	
Oscillator start-up time <sup>1)2)3)</sup>	$t_{OSCS}$ CC	–	–	5	s	
Input voltage at RTC_XTAL1	$V_{IX}$ SR	-0.3	–	$V_{BAT} + 0.3$	V	
Input amplitude (peak-to-peak) at RTC_XTAL1 <sup>2)4)</sup>	$V_{PPX}$ SR	0.4	–	–	V	
Input high voltage at RTC_XTAL1 <sup>5)</sup>	$V_{IHBX}$ SR	$0.6 \times V_{BAT}$	–	$V_{BAT} + 0.3$	V	
Input low voltage at RTC_XTAL1 <sup>5)</sup>	$V_{ILBX}$ SR	-0.3	–	$0.36 \times V_{BAT}$	V	
Input Hysteresis for RTC_XTAL1 <sup>5)6)</sup>	$V_{HYSX}$ CC	$0.1 \times V_{BAT}$	–	–	V	$3.0 \text{ V} \leq V_{BAT} < 3.6 \text{ V}$
		$0.03 \times V_{BAT}$	–	–	V	$V_{BAT} < 3.0 \text{ V}$
Input leakage current at RTC_XTAL1	$I_{ILX1}$ CC	-100	–	100	nA	Oscillator power down $0 \text{ V} \leq V_{IX} \leq V_{BAT}$

- 1)  $t_{OSCS}$  is defined from the moment the oscillator is enabled by the user with SCU\_OSCULCTRL.MODE until the oscillations reach an amplitude at RTC\_XTAL1 of 400 mV.
- 2) The external oscillator circuitry must be optimized by the customer and checked for negative resistance and amplitude as recommended and specified by crystal suppliers.
- 3) For a reliable start of the oscillation in crystal mode it is required that  $V_{BAT} \geq 3.0 \text{ V}$ . A running oscillation is maintained across the full  $V_{BAT}$  voltage range.
- 4) If the shaper unit is enabled and not bypassed.
- 5) If the shaper unit is bypassed, dedicated DC-thresholds have to be met.
- 6) Hysteresis is implemented to avoid metastable states and switching due to internal ground bounce. It can not be guaranteed that it suppresses switching due to external system noise.

### 3.2.8 Power Supply Current

The total power supply current defined below consists of a leakage and a switching component.

Application relevant values are typically lower than those given in the following tables, and depend on the customer's system operating conditions (e.g. thermal connection or used application configurations).

*Note: These parameters are not subject to production test, but verified by design and/or characterization.*

If not stated otherwise, the operating conditions for the parameters in the following table are:

$$V_{DDP} = 3.3 \text{ V}, T_A = 25 \text{ }^\circ\text{C}$$

**Table 32 Power Supply Parameters**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Active supply current <sup>(1)(10)</sup> Peripherals enabled Frequency: $f_{CPU}/f_{PERIPH}/f_{CCU}$ in MHz	$I_{DDPA}$ CC	–	122	–	mA	120 / 120 / 120
		–	110	–		120 / 60 / 60
		–	85	–		60 / 60 / 120
		–	65	–		24 / 24 / 24
		–	52	–		1 / 1 / 1
Active supply current Code execution from RAM Flash in Sleep mode	$I_{DDPA}$ CC	–	98	–	mA	120 / 120 / 120
		–	80	–		120 / 60 / 60
Active supply current <sup>(2)</sup> Peripherals disabled Frequency: $f_{CPU}/f_{PERIPH}/f_{CCU}$ in MHz	$I_{DDPA}$ CC	–	115	–	mA	120 / 120 / 120
		–	105	–		120 / 60 / 60
		–	80	–		60 / 60 / 120
		–	63	–		24 / 24 / 24
		–	50	–		1 / 1 / 1
Sleep supply current <sup>(3)</sup> Peripherals enabled Frequency: $f_{CPU}/f_{PERIPH}/f_{CCU}$ in MHz	$I_{DDPS}$ CC	–	115	–	mA	120 / 120 / 120
		–	105	–		120 / 60 / 60
		–	83	–		60 / 60 / 120
		–	60	–		24 / 24 / 24
		–	48	–		1 / 1 / 1
		$f_{CPU}/f_{PERIPH}/f_{CCU}$ in kHz	–	46		–

**Electrical Parameters**
**Table 32 Power Supply Parameters**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Sleep supply current <sup>4)</sup> Peripherals disabled Frequency: $f_{CPU} / f_{PERIPH} / f_{CCU}$ in MHz	$I_{DDPS}$ CC	-	110	-	mA	120 / 120 / 120
		-	100	-		120 / 60 / 60
		-	77	-		60 / 60 / 120
		-	59	-		24 / 24 / 24
		-	48	-		1 / 1 / 1
		-	46	-		100 / 100 / 100
$f_{CPU} / f_{PERIPH} / f_{CCU}$ in kHz						
Deep Sleep supply current <sup>5)</sup> Flash in Sleep mode Frequency: $f_{CPU} / f_{PERIPH} / f_{CCU}$ in MHz $f_{CPU} / f_{PERIPH} / f_{CCU}$ in kHz	$I_{DDPD}$ CC	-	20	-	mA	24 / 24 / 24
		-	12	-		4 / 4 / 4
		-	10	-		1 / 1 / 1
		-	6	-		100 / 100 / 100 <sup>6)</sup>
Hibernate supply current RTC on <sup>7)</sup>	$I_{DDPH}$ CC	-	10	-	$\mu$ A	$V_{BAT} = 3.3$ V
		-	7.5	-		$V_{BAT} = 2.4$ V
		-	6.2	-		$V_{BAT} = 2.0$ V
Hibernate supply current RTC off <sup>8)</sup>	$I_{DDPH}$ CC	-	9.2	-	$\mu$ A	$V_{BAT} = 3.3$ V
		-	6.7	-		$V_{BAT} = 2.4$ V
		-	5.6	-		$V_{BAT} = 2.0$ V
Worst case active supply current <sup>9)</sup>	$I_{DDPA}$ CC	-	-	180 <sup>10)</sup>	mA	$V_{DDP} = 3.6$ V, $T_J = 150$ °C
$V_{DDA}$ power supply current	$I_{DDA}$ CC	-	-	- <sup>11)</sup>	mA	
$I_{DDP}$ current at $\overline{PORST}$ Low	$I_{DDP\_PORST}$ CC	-	-	16	mA	$V_{DDP} = 3.6$ V, $T_J = 150$ °C
Power Dissipation	$P_{DISS}$ CC	-	-	1	W	$V_{DDP} = 3.6$ V, $T_J = 150$ °C
Wake-up time from Sleep to Active mode	$t_{SSA}$ CC	-	6	-	cycles	

**Table 32 Power Supply Parameters**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Wake-up time from Deep Sleep to Active mode		–	–	–	ms	Defined by the wake-up of the Flash module, see <a href="#">Section 3.2.9</a>
Wake-up time from Hibernate mode		–	–	–	ms	Wake-up via power-on reset event, see <a href="#">Section 3.3.2</a>

- 1) CPU executing code from Flash, all peripherals idle.
- 2) CPU executing code from Flash.
- 3) CPU in sleep, all peripherals idle, Flash in Active mode.
- 4) CPU in sleep, Flash in Active mode.
- 5) CPU in sleep, peripherals disabled, after wake-up code execution from RAM.
- 6) To wake-up the Flash from its Sleep mode,  $f_{CPU} \geq 1$  MHz is required.
- 7) OSC\_ULP operating with external crystal on RTC\_XTAL
- 8) OSC\_ULP off, Hibernate domain operating with OSC\_SI clock
- 9) Test Power Loop:  $f_{SYS} = 120$  MHz, CPU executing benchmark code from Flash, all CCUs in 100kHz timer mode, all ADC groups in continuous conversion mode, USICs as SPI in internal loop-back mode, CAN in 500kHz internal loop-back mode, interrupt triggered DMA block transfers to parity protected RAMs and FCE, DTS measurements and FPU calculations.  
The power consumption of each customer application will most probably be lower than this value, but must be evaluated separately.
- 10)  $I_{DDP}$  decreases typically by approximately 6 mA when  $f_{SYS}$  decreases by 10 MHz, at constant  $T_J$
- 11) Sum of currents of all active converters (ADC and DAC)

### 3.2.9 Flash Memory Parameters

*Note: These parameters are not subject to production test, but verified by design and/or characterization.*

**Table 33 Flash Memory Parameters**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Erase Time per 256 Kbyte Sector	$t_{ERP}$ CC	–	5	5.5	s	
Erase Time per 64 Kbyte Sector	$t_{ERP}$ CC	–	1.2	1.4	s	
Erase Time per 16 Kbyte Logical Sector	$t_{ERP}$ CC	–	0.3	0.4	s	
Program time per page <sup>1)</sup>	$t_{PRP}$ CC	–	5.5	11	ms	
Erase suspend delay	$t_{FL\_ErSusp}$ CC	–	–	15	ms	
Wait time after margin change	$t_{FL\_MarginDel}$ CC	10	–	–	μs	
Wake-up time	$t_{WU}$ CC	–	–	270	μs	
Read access time	$t_a$ CC	22	–	–	ns	For operation with $1/f_{CPU} < t_a$ wait states must be configured <sup>2)</sup>
Data Retention Time, Physical Sector <sup>3)4)</sup>	$t_{RET}$ CC	20	–	–	years	Max. 1000 erase/program cycles
Data Retention Time, Logical Sector <sup>3)4)</sup>	$t_{RETL}$ CC	20	–	–	years	Max. 100 erase/program cycles
Data Retention Time, User Configuration Block (UCB) <sup>3)4)</sup>	$t_{RTU}$ CC	20	–	–	years	Max. 4 erase/program cycles per UCB

1) In case the Program Verify feature detects weak bits, these bits will be programmed once more. The reprogramming takes an additional time of 5.5 ms.

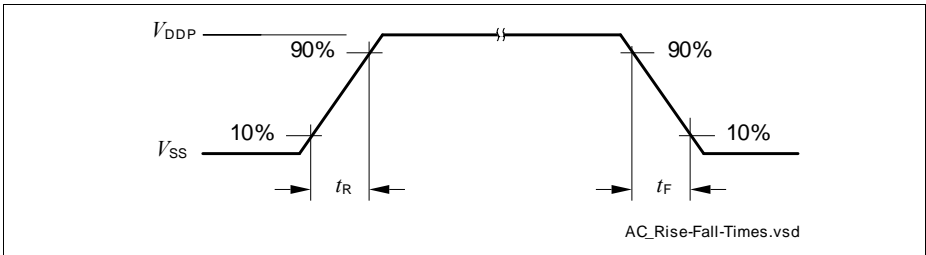
2) The following formula applies to the wait state configuration:  $FCON.WSPFLASH \times (1/f_{CPU}) \geq t_a$ .

3) Storage and inactive time included.

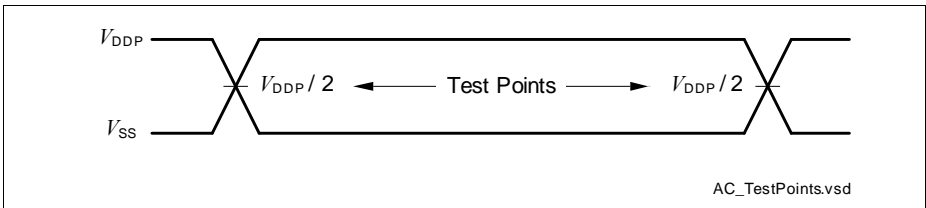
4) Values given are valid for an average weighted junction temperature of  $T_J = 110^\circ\text{C}$ .

### 3.3 AC Parameters

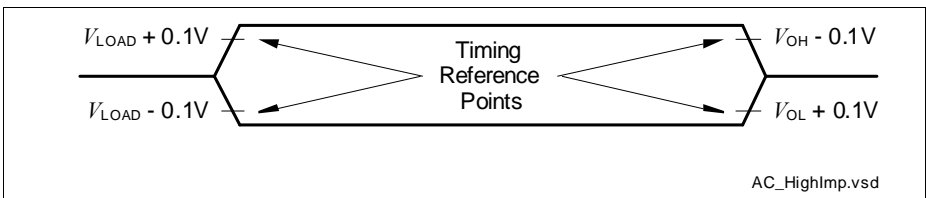
#### 3.3.1 Testing Waveforms



**Figure 22 Rise/Fall Time Parameters**



**Figure 23 Testing Waveform, Output Delay**

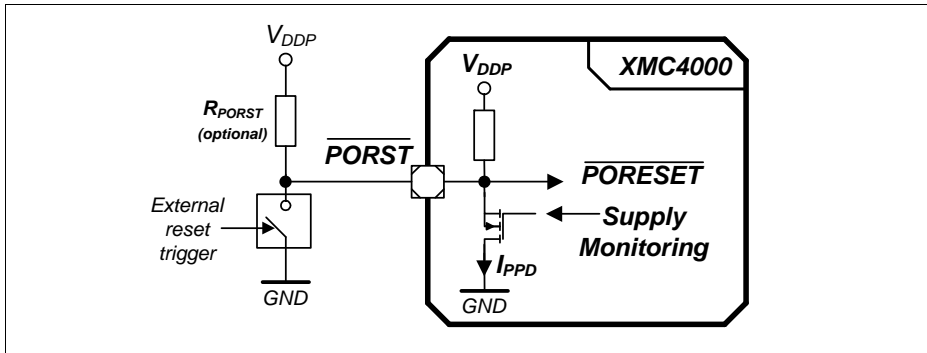


**Figure 24 Testing Waveform, Output High Impedance**

### 3.3.2 Power-Up and Supply Monitoring

$\overline{\text{PORST}}$  is always asserted when  $V_{\text{DDP}}$  and/or  $V_{\text{DDC}}$  violate the respective thresholds.

*Note: These parameters are not subject to production test, but verified by design and/or characterization.*



**Figure 25**  $\overline{\text{PORST}}$  Circuit

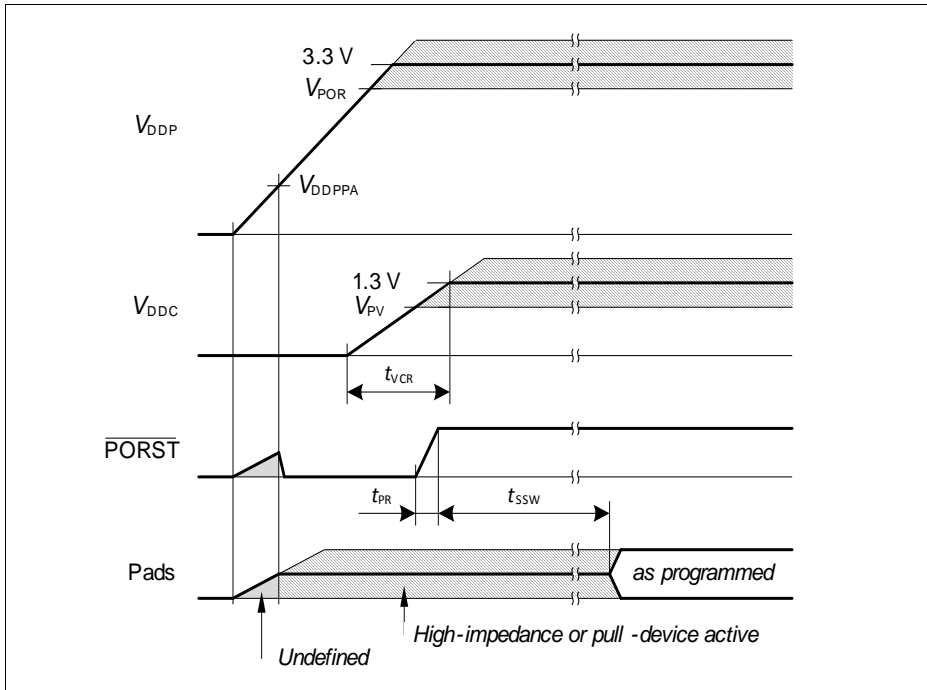
**Table 34** Supply Monitoring Parameters

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Digital supply voltage reset threshold	$V_{\text{POR}}$ CC	2.79 <sup>1)</sup>	–	3.05 <sup>2)</sup>	V	3)
Core supply voltage reset threshold	$V_{\text{PV}}$ CC	–	–	1.17	V	
$V_{\text{DDP}}$ voltage to ensure defined pad states	$V_{\text{DDPPA}}$ CC	–	1.0	–	V	
$\overline{\text{PORST}}$ rise time	$t_{\text{PR}}$ SR	–	–	2	$\mu\text{s}$	4)
Startup time from power-on reset with code execution from Flash	$t_{\text{SSW}}$ CC	–	2.5	3.5	ms	Time to the first user code instruction
$V_{\text{DDC}}$ ramp up time	$t_{\text{VCR}}$ CC	–	550	–	$\mu\text{s}$	Ramp up after power-on or after a reset triggered by a violation of $V_{\text{POR}}$ or $V_{\text{PV}}$

1) Minimum threshold for reset assertion.



- 2) Maximum threshold for reset deassertion.
- 3) The  $V_{DDP}$  monitoring has a typical hysteresis of  $V_{PORHYS} = 180$  mV.
- 4) If  $t_{PR}$  is not met, low spikes on  $\overline{PORST}$  may be seen during start up (e.g. reset pulses generated by the supply monitoring due to a slow ramping  $V_{DDP}$ ).



**Figure 26 Power-Up Behavior**

### 3.3.3 Power Sequencing

While starting up and shutting down as well as when switching power modes of the system it is important to limit the current load steps. A typical cause for such load steps is changing the CPU frequency  $f_{CPU}$ . Load steps exceeding the below defined values may cause a power on reset triggered by the supply monitor.

*Note: These parameters are not subject to production test, but verified by design and/or characterization.*

**Table 35 Power Sequencing Parameters**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Positive Load Step Current	$\Delta I_{PLS}$ SR	-	-	50	mA	Load increase on $V_{DDP}$ $\Delta t \leq 10$ ns
Negative Load Step Current	$\Delta I_{NLS}$ SR	-	-	150	mA	Load decrease on $V_{DDP}$ $\Delta t \leq 10$ ns
$V_{DDC}$ Voltage Over- / Undershoot from Load Step	$\Delta V_{LS}$ CC	-	-	$\pm 100$	mV	For maximum positive or negative load step
Positive Load Step Settling Time	$t_{PLSS}$ SR	50	-	-	$\mu$ s	
Negative Load Step Settling Time	$t_{NLSS}$ SR	100	-	-	$\mu$ s	
External Buffer Capacitor on $V_{DDC}$	$C_{EXT}$ SR	-	10	-	$\mu$ F	In addition $C = 100$ nF capacitor on each $V_{DDC}$ pin

### Positive Load Step Examples

System assumptions:

$f_{CPU} = f_{SYS}$ , target frequency  $f_{CPU} = 120$  MHz, main PLL  $f_{VCO} = 480$  MHz, stepping done by K2 divider,  $t_{PLSS}$  between individual steps:

24 MHz - 48 MHz - 68 MHz - 96 MHz - 120 MHz (K2 steps 20 - 10 - 7 - 5 - 4)

24 MHz - 68 MHz - 96 MHz - 120 MHz (K2 steps 20 - 7 - 5 - 4)

24 MHz - 68 MHz - 120 MHz (K2 steps 20 - 7 - 4)

### 3.3.4 Phase Locked Loop (PLL) Characteristics

*Note: These parameters are not subject to production test, but verified by design and/or characterization.*

#### Main and USB PLL

**Table 36 PLL Parameters**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Accumulated Jitter	$D_P$ CC	–	–	±5	ns	accumulated over 300 cycles $f_{SYS} = 120$ MHz
Duty Cycle <sup>1)</sup>	$D_{DC}$ CC	46	50	54	%	Low pulse to total period, assuming an ideal input clock source
PLL base frequency	$f_{PLLBASE}$ CC	30	–	140	MHz	
VCO input frequency	$f_{REF}$ CC	4	–	16	MHz	
VCO frequency range	$f_{VCO}$ CC	260	–	520	MHz	
PLL lock-in time	$t_L$ CC	–	–	400	µs	

1) 50% for even K2 divider values, 50±(10/K2) for odd K2 divider values.

### 3.3.5 Internal Clock Source Characteristics

*Note: These parameters are not subject to production test, but verified by design and/or characterization.*

#### Fast Internal Clock Source

**Table 37 Fast Internal Clock Parameters**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Nominal frequency	$f_{\text{OFINC}}$ CC	–	36.5	–	MHz	not calibrated
		–	24	–	MHz	calibrated
Accuracy	$\Delta f_{\text{OFI}}$ CC	-0.5	–	0.5	%	automatic calibration <sup>1)2)</sup>
		-15	–	15	%	factory calibration, $V_{\text{DDP}} = 3.3 \text{ V}$
		-25	–	25	%	no calibration, $V_{\text{DDP}} = 3.3 \text{ V}$
		-7	–	7	%	Variation over voltage range <sup>3)</sup> $3.13 \text{ V} \leq V_{\text{DDP}} \leq 3.63 \text{ V}$
Start-up time	$t_{\text{OFIS}}$ CC	–	50	–	$\mu\text{s}$	

1) Error in addition to the accuracy of the reference clock.

2) Automatic calibration compensates variations of the temperature and in the  $V_{\text{DDP}}$  supply voltage.

3) Deviations from the nominal  $V_{\text{DDP}}$  voltage induce an additional error to the uncalibrated and/or factory calibrated oscillator frequency.

**Slow Internal Clock Source**
**Table 38 Slow Internal Clock Parameters**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Nominal frequency	$f_{OSI}$ CC	–	32.768	–	kHz	
Accuracy	$\Delta f_{OSI}$ CC	-4	–	4	%	$V_{BAT} = \text{const.}$ $0\text{ }^{\circ}\text{C} \leq T_A \leq 85\text{ }^{\circ}\text{C}$
		-5	–	5	%	$V_{BAT} = \text{const.}$ $T_A < 0\text{ }^{\circ}\text{C}$ or $T_A > 85\text{ }^{\circ}\text{C}$
		-5	–	5	%	$2.4\text{ V} \leq V_{BAT}$ , $T_A = 25\text{ }^{\circ}\text{C}$
		-10	–	10	%	$1.95\text{ V} \leq V_{BAT} < 2.4\text{ V}$ , $T_A = 25\text{ }^{\circ}\text{C}$
Start-up time	$t_{OSIS}$ CC	–	50	–	$\mu\text{s}$	

### 3.3.6 JTAG Interface Timing

The following parameters are applicable for communication through the JTAG debug interface. The JTAG module is fully compliant with IEEE1149.1-2000.

*Note: These parameters are not subject to production test, but verified by design and/or characterization.*

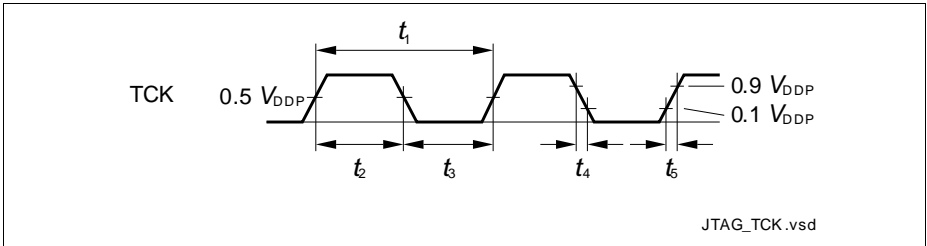
*Note: Operating conditions apply.*

**Table 39 JTAG Interface Timing Parameters**

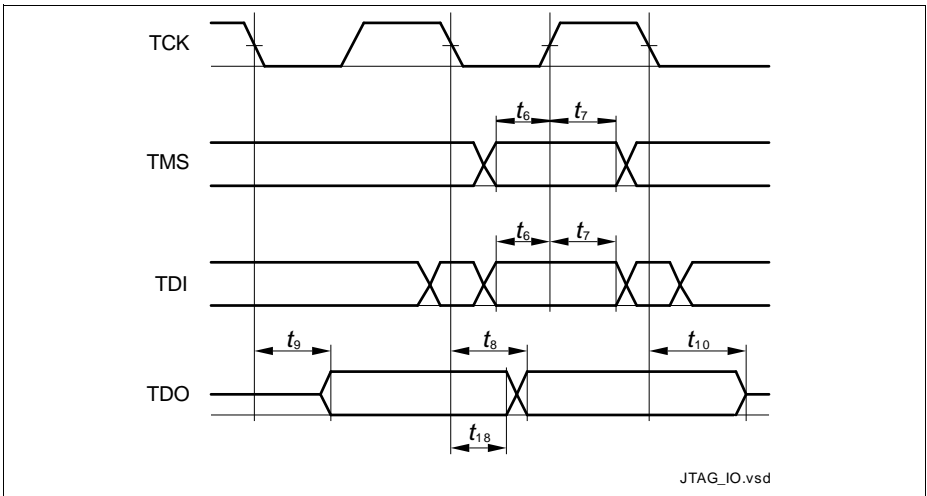
Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
TCK clock period	$t_1$ SR	25	–	–	ns	
TCK high time	$t_2$ SR	10	–	–	ns	
TCK low time	$t_3$ SR	10	–	–	ns	
TCK clock rise time	$t_4$ SR	–	–	4	ns	
TCK clock fall time	$t_5$ SR	–	–	4	ns	
TDI/TMS setup to TCK rising edge	$t_6$ SR	6	–	–	ns	
TDI/TMS hold after TCK rising edge	$t_7$ SR	6	–	–	ns	
TDO valid after TCK falling edge <sup>1)</sup> (propagation delay)	$t_8$ CC	–	–	13	ns	$C_L = 50$ pF
		3	–	–	ns	$C_L = 20$ pF
TDO hold after TCK falling edge <sup>1)</sup>	$t_{18}$ CC	2	–	–	ns	
TDO high imped. to valid from TCK falling edge <sup>1)2)</sup>	$t_9$ CC	–	–	14	ns	$C_L = 50$ pF
TDO valid to high imped. from TCK falling edge <sup>1)</sup>	$t_{10}$ CC	–	–	13.5	ns	$C_L = 50$ pF

1) The falling edge on TCK is used to generate the TDO timing.

2) The setup time for TDO is given implicitly by the TCK cycle time.



**Figure 27 Test Clock Timing (TCK)**



**Figure 28 JTAG Timing**

### 3.3.7 Serial Wire Debug Port (SW-DP) Timing

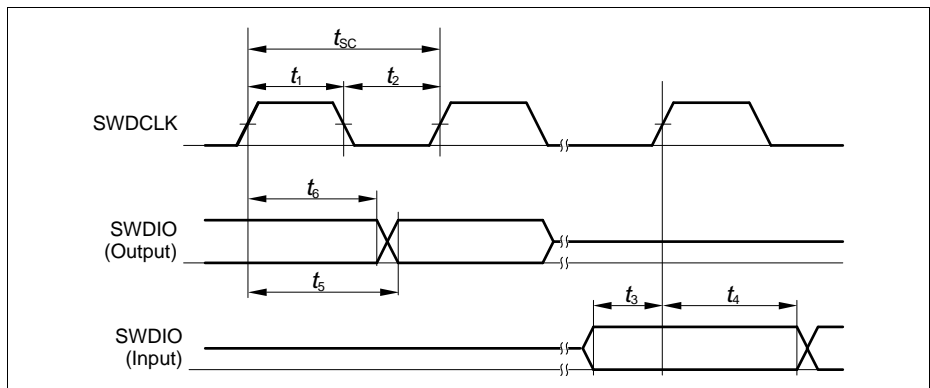
The following parameters are applicable for communication through the SW-DP interface.

*Note: These parameters are not subject to production test, but verified by design and/or characterization.*

*Note: Operating conditions apply.*

**Table 40 SWD Interface Timing Parameters (Operating Conditions apply)**

Parameter	Symbol	SR	Values			Unit	Note / Test Condition
			Min.	Typ.	Max.		
SWDCLK clock period	$t_{SC}$	SR	25	–	–	ns	$C_L = 30$ pF
			40	–	–	ns	$C_L = 50$ pF
SWDCLK high time	$t_1$	SR	10	–	500000	ns	
SWDCLK low time	$t_2$	SR	10	–	500000	ns	
SWDIO input setup to SWDCLK rising edge	$t_3$	SR	6	–	–	ns	
SWDIO input hold after SWDCLK rising edge	$t_4$	SR	6	–	–	ns	
SWDIO output valid time after SWDCLK rising edge	$t_5$	CC	–	–	17	ns	$C_L = 50$ pF
			–	–	13	ns	$C_L = 30$ pF
SWDIO output hold time from SWDCLK rising edge	$t_6$	CC	3	–	–	ns	



**Figure 29 SWD Timing**



### 3.3.8 Embedded Trace Macro Cell (ETM) Timing

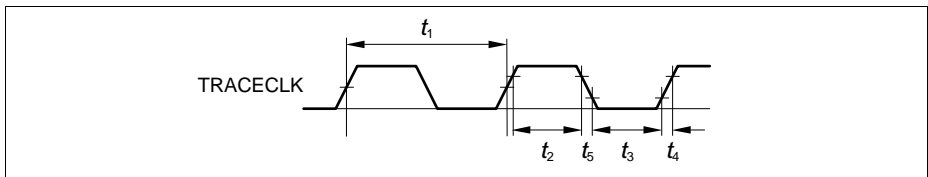
The data timing refers to the active clock edge. The XMC4500 ETM uses the half-rate clocking mode. In this mode both, the rising and falling clock edges are active clock edges.

*Note: These parameters are not subject to production test, but verified by design and/or characterization.*

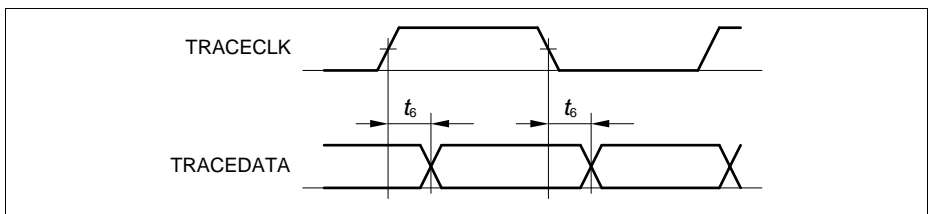
*Note: Operating conditions apply, with  $C_L \leq 15$  pF.*

**Table 41 ETM Interface Timing Parameters**

Parameter	Symbol	CC	Values			Unit	Note / Test Condition
			Min.	Typ.	Max.		
TRACECLK period	$t_1$	CC	16.7	–	–	ns	–
TRACECLK high time	$t_2$	CC	2	–	–	ns	–
TRACECLK low time	$t_3$	CC	2	–	–	ns	–
TRACECLK and TRACEDATA rise time	$t_4$	CC	–	–	3	ns	–
TRACECLK and TRACEDATA fall time	$t_5$	CC	–	–	3	ns	–
TRACEDATA output valid time	$t_6$	CC	-2	–	3	ns	–



**Figure 30 ETM Clock Timing**



**Figure 31 ETM Data Timing**

### 3.3.9 Peripheral Timing

#### 3.3.9.1 Delta-Sigma Demodulator Digital Interface Timing

The following parameters are applicable for the digital interface of the Delta-Sigma Demodulator (DSD).

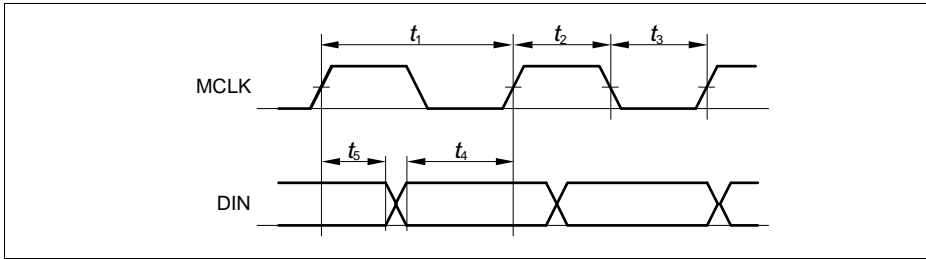
The data timing is relative to the active clock edge. Depending on the operation mode of the connected modulator that can be the rising and falling clock edge.

*Note: These parameters are not subject to production test, but verified by design and/or characterization.*

**Table 42 DSD Interface Timing Parameters**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
MCLK period in master mode	$t_1$ CC	33.3	–	–	ns	$t_1 \geq 4 \times t_{\text{PERIPH}}^{1)}$
MCLK high time in master mode	$t_2$ CC	9	–	–	ns	$t_2 > t_{\text{PERIPH}}^{1)}$
MCLK low time in master mode	$t_3$ CC	9	–	–	ns	$t_3 > t_{\text{PERIPH}}^{1)}$
MCLK period in slave mode	$t_1$ SR	33.3	–	–	ns	$t_1 \geq 4 \times t_{\text{PERIPH}}^{1)}$
MCLK high time in slave mode	$t_2$ SR	$t_{\text{PERIPH}}$	–	–	ns	1)
MCLK low time in slave mode	$t_3$ SR	$t_{\text{PERIPH}}$	–	–	ns	1)
DIN input setup time to the active clock edge	$t_4$ SR	$t_{\text{PERIPH}} + 4$	–	–	ns	1)
DIN input hold time from the active clock edge	$t_5$ SR	$t_{\text{PERIPH}} + 3$	–	–	ns	1)

1)  $t_{\text{PERIPH}} = 1 / f_{\text{PERIPH}}$



**Figure 32 DSD Data Timing**

### 3.3.9.2 Synchronous Serial Interface (USIC SSC) Timing

The following parameters are applicable for a USIC channel operated in SSC mode.

*Note: These parameters are not subject to production test, but verified by design and/or characterization.*

**Table 43 USIC SSC Master Mode Timing**

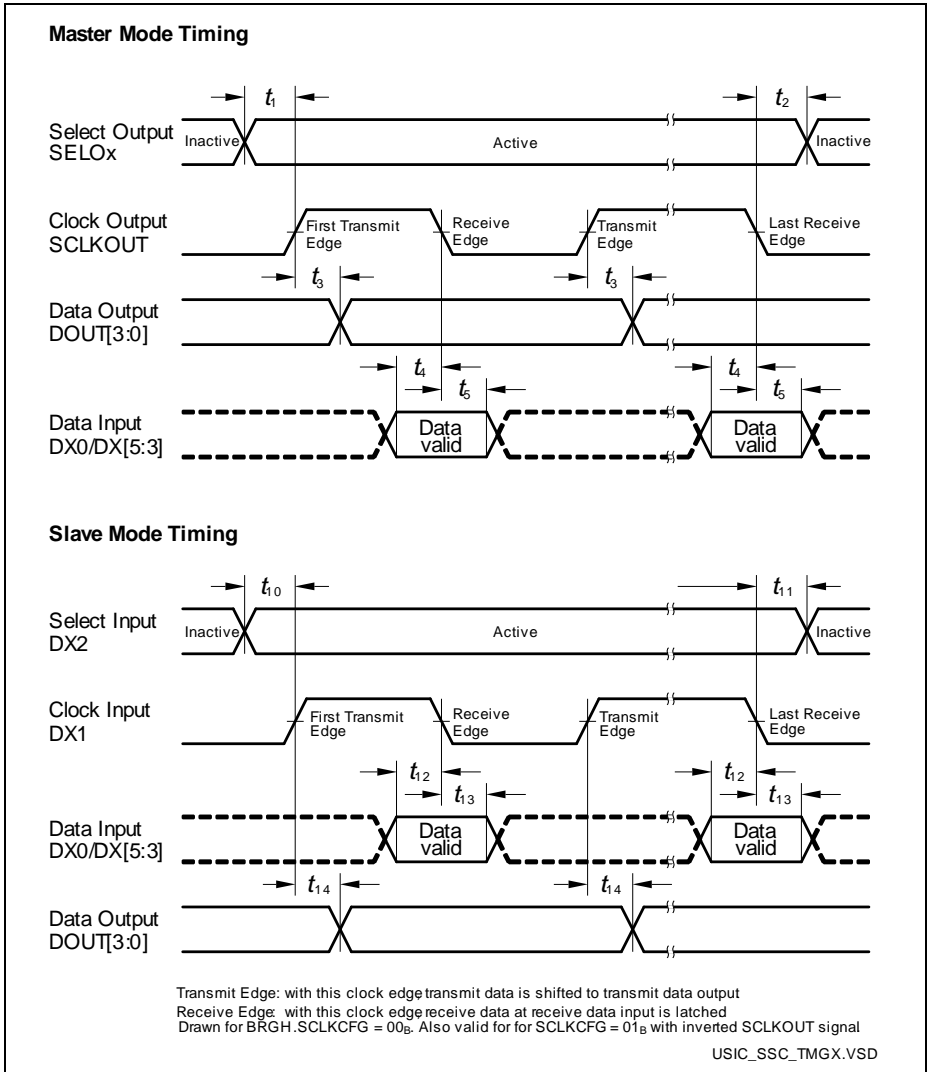
Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
SCLKOUT master clock period	$t_{CLK}$ CC	33.3	–	–	ns	
Slave select output SELO active to first SCLKOUT transmit edge	$t_1$ CC	$t_{PB} - 6.5^{1)}$	–	–	ns	
Slave select output SELO inactive after last SCLKOUT receive edge	$t_2$ CC	$t_{PB} - 8.5^{1)}$	–	–	ns	
Data output DOUT[3:0] valid time	$t_3$ CC	-6	–	8	ns	
Receive data input DX0/DX[5:3] setup time to SCLKOUT receive edge	$t_4$ SR	23	–	–	ns	
Data input DX0/DX[5:3] hold time from SCLKOUT receive edge	$t_5$ SR	1	–	–	ns	

1)  $t_{PB} = 1 / f_{PB}$

**Table 44 USIC SSC Slave Mode Timing**

Parameter	Symbol		Values			Unit	Note / Test Condition
			Min.	Typ.	Max.		
DX1 slave clock period	$t_{CLK}$	SR	66.6	–	–	ns	
Select input DX2 setup to first clock input DX1 transmit edge <sup>1)</sup>	$t_{10}$	SR	3	–	–	ns	
Select input DX2 hold after last clock input DX1 receive edge <sup>1)</sup>	$t_{11}$	SR	4	–	–	ns	
Receive data input DX0/DX[5:3] setup time to shift clock receive edge <sup>1)</sup>	$t_{12}$	SR	6	–	–	ns	
Data input DX0/DX[5:3] hold time from clock input DX1 receive edge <sup>1)</sup>	$t_{13}$	SR	4	–	–	ns	
Data output DOUT[3:0] valid time	$t_{14}$	CC	0	–	24	ns	

1) This input timing is valid for asynchronous input signal handling of slave select input, shift clock input, and receive data input (bits DXnCR.DSEN = 0).



**Figure 33 USIC - SSC Master/Slave Mode Timing**

*Note: This timing diagram shows a standard configuration, for which the slave select signal is low-active, and the serial clock signal is not shifted and not inverted.*

### 3.3.9.3 Inter-IC (IIC) Interface Timing

The following parameters are applicable for a USIC channel operated in IIC mode.

*Note: These parameters are not subject to production test, but verified by design and/or characterization.*

**Table 45 USIC IIC Standard Mode Timing<sup>1)</sup>**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Fall time of both SDA and SCL	$t_1$ CC/SR	-	-	300	ns	
Rise time of both SDA and SCL	$t_2$ CC/SR	-	-	1000	ns	
Data hold time	$t_3$ CC/SR	0	-	-	μs	
Data set-up time	$t_4$ CC/SR	250	-	-	ns	
LOW period of SCL clock	$t_5$ CC/SR	4.7	-	-	μs	
HIGH period of SCL clock	$t_6$ CC/SR	4.0	-	-	μs	
Hold time for (repeated) START condition	$t_7$ CC/SR	4.0	-	-	μs	
Set-up time for repeated START condition	$t_8$ CC/SR	4.7	-	-	μs	
Set-up time for STOP condition	$t_9$ CC/SR	4.0	-	-	μs	
Bus free time between a STOP and START condition	$t_{10}$ CC/SR	4.7	-	-	μs	
Capacitive load for each bus line	$C_b$ SR	-	-	400	pF	

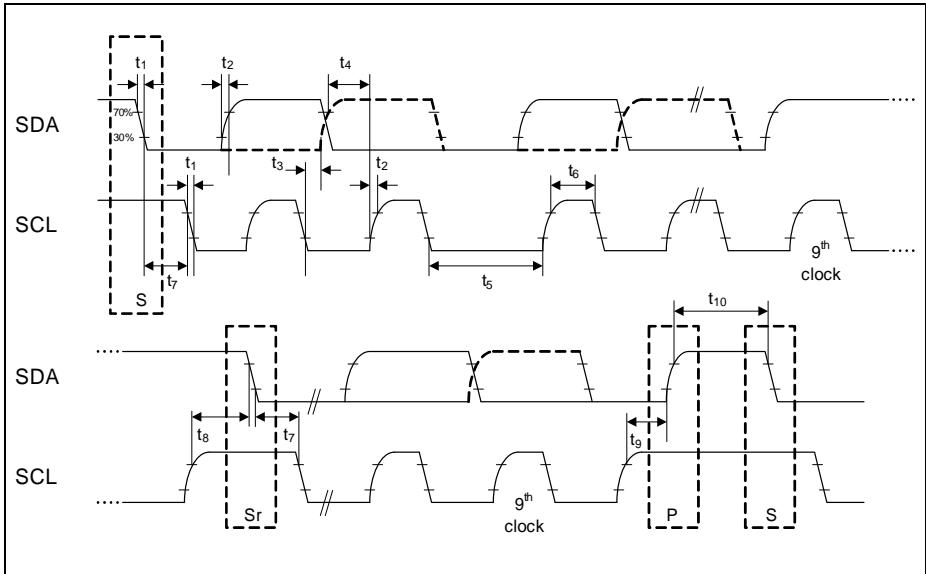
1) Due to the wired-AND configuration of an IIC bus system, the port drivers of the SCL and SDA signal lines need to operate in open-drain mode. The high level on these lines must be held by an external pull-up device, approximately 10 kOhm for operation at 100 kbit/s, approximately 2 kOhm for operation at 400 kbit/s.

**Table 46 USIC IIC Fast Mode Timing<sup>1)</sup>**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Fall time of both SDA and SCL	$t_1$ CC/SR	20 + 0.1 * C <sub>b</sub> 2)	-	300	ns	
Rise time of both SDA and SCL	$t_2$ CC/SR	20 + 0.1 * C <sub>b</sub> 2)	-	300	ns	
Data hold time	$t_3$ CC/SR	0	-	-	µs	
Data set-up time	$t_4$ CC/SR	100	-	-	ns	
LOW period of SCL clock	$t_5$ CC/SR	1.3	-	-	µs	
HIGH period of SCL clock	$t_6$ CC/SR	0.6	-	-	µs	
Hold time for (repeated) START condition	$t_7$ CC/SR	0.6	-	-	µs	
Set-up time for repeated START condition	$t_8$ CC/SR	0.6	-	-	µs	
Set-up time for STOP condition	$t_9$ CC/SR	0.6	-	-	µs	
Bus free time between a STOP and START condition	$t_{10}$ CC/SR	1.3	-	-	µs	
Capacitive load for each bus line	C <sub>b</sub> SR	-	-	400	pF	

1) Due to the wired-AND configuration of an IIC bus system, the port drivers of the SCL and SDA signal lines need to operate in open-drain mode. The high level on these lines must be held by an external pull-up device, approximately 10 kOhm for operation at 100 kbit/s, approximately 2 kOhm for operation at 400 kbit/s.

2) C<sub>b</sub> refers to the total capacitance of one bus line in pF.



**Figure 34 USIC IIC Stand and Fast Mode Timing**

### 3.3.9.4 Inter-IC Sound (IIS) Interface Timing

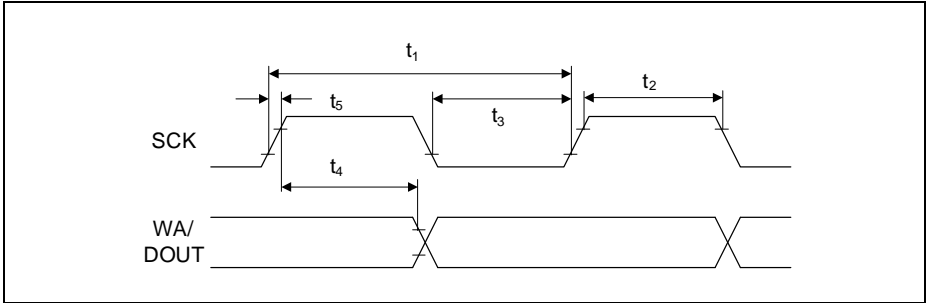
The following parameters are applicable for a USIC channel operated in IIS mode.

*Note: These parameters are not subject to production test, but verified by design and/or characterization.*

**Table 47 USIC IIS Master Transmitter Timing**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Clock period	$t_1$ CC	33.3	–	–	ns	
Clock high time	$t_2$ CC	0.35 x $t_{1min}$	–	–	ns	
Clock low time	$t_3$ CC	0.35 x $t_{1min}$	–	–	ns	
Hold time	$t_4$ CC	0	–	–	ns	
Clock rise time	$t_5$ CC	–	–	0.15 x $t_{1min}$	ns	

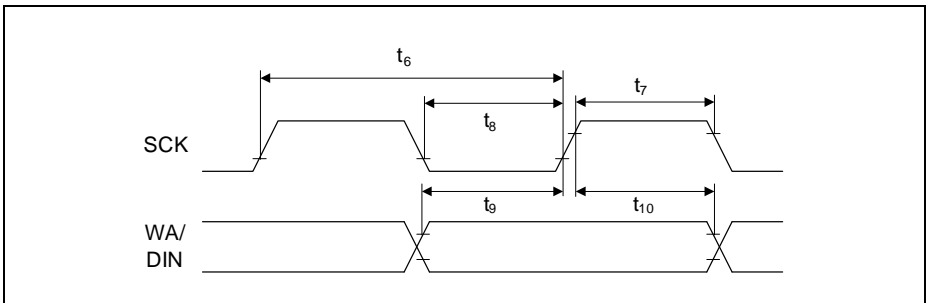




**Figure 35 USIC IIS Master Transmitter Timing**

**Table 48 USIC IIS Slave Receiver Timing**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Clock period	$t_6$ SR	66.6	—	—	ns	
Clock high time	$t_7$ SR	$0.35 \times t_{6min}$	—	—	ns	
Clock low time	$t_8$ SR	$0.35 \times t_{6min}$	—	—	ns	
Set-up time	$t_9$ SR	$0.2 \times t_{6min}$	—	—	ns	
Hold time	$t_{10}$ SR	0	—	—	ns	



**Figure 36 USIC IIS Slave Receiver Timing**

### 3.3.9.5 SDMMC Interface Timing

*Note: These parameters are not subject to production test, but verified by design and/or characterization.*

*Note: Operating Conditions apply, total external capacitive load  $C_L = 40$  pF.*

#### AC Timing Specifications (Full-Speed Mode)

**Table 49 SDMMC Timing for Full-Speed Mode**

Parameter	Symbol	Values	Unit		Note/ Test Condition
			Min.	Max.	
Clock frequency in full speed transfer mode ( $1/t_{pp}$ )	$f_{pp}$ CC	0	24	MHz	
Clock cycle in full speed transfer mode	$t_{pp}$ CC	40	–	ns	
Clock low time	$t_{WL}$ CC	10	–	ns	
Clock high time	$t_{WH}$ CC	10	–	ns	
Clock rise time	$t_{TLH}$ CC	–	10	ns	
Clock fall time	$t_{THL}$ CC	–	10	ns	
Inputs setup to clock rising edge	$t_{ISU\_F}$ SR	2	–	ns	
Inputs hold after clock rising edge	$t_{IH\_F}$ SR	2	–	ns	
Outputs valid time in full speed mode	$t_{ODLY\_F}$ CC	–	10	ns	
Outputs hold time in full speed mode	$t_{OH\_F}$ CC	0	–	ns	

**Table 50 SD Card Bus Timing for Full-Speed Mode<sup>1)</sup>**

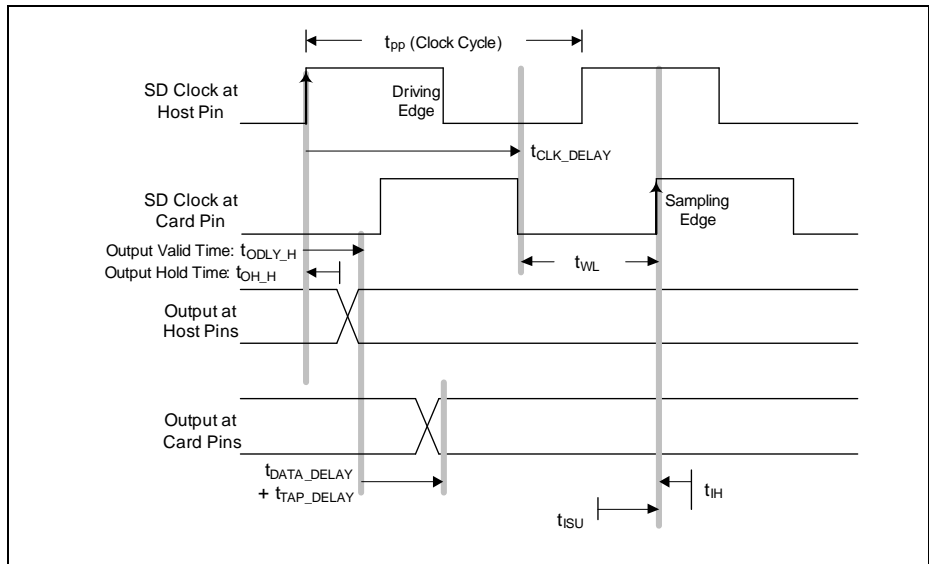
Parameter	Symbol	Values		Unit	Note/ Test Condition
		Min.	Max.		
SD card input setup time	$t_{ISU}$	5	–	ns	
SD card input hold time	$t_{IH}$	5	–	ns	

**Table 50 SD Card Bus Timing for Full-Speed Mode<sup>1)</sup> (cont'd)**

Parameter	Symbol	Values		Unit	Note/ Test Condition
		Min.	Max.		
SD card output valid time	$t_{ODLY}$	–	14	ns	
SD card output hold time	$t_{OH}$	0	–	ns	

1) Reference card timing values for calculation examples. Not subject to production test and not characterized.

**Full-Speed Output Path (Write)**



**Figure 37 Full-Speed Output Path**

**Full-Speed Write Meeting Setup (Maximum Delay)**

The following equations show how to calculate the allowed skew range between the SD\_CLK and SD\_DAT/CMD signals on the PCB.

No clock delay:

(1)

$$t_{ODLY\_F} + t_{DATA\_DELAY} + t_{TAP\_DELAY} + t_{ISU} < t_{WL}$$

With clock delay:

$$t_{\text{ODLY\_F}} + t_{\text{DATA\_DELAY}} + t_{\text{TAP\_DELAY}} + t_{\text{ISU}} < t_{\text{WL}} + t_{\text{CLK\_DELAY}} \quad (2)$$

$$t_{\text{DATA\_DELAY}} + t_{\text{TAP\_DELAY}} + t_{\text{WL}} < t_{\text{PP}} + t_{\text{CLK\_DELAY}} - t_{\text{ISU}} - t_{\text{ODLY\_F}} \quad (3)$$

$$t_{\text{DATA\_DELAY}} + t_{\text{TAP\_DELAY}} + 20 < 40 + t_{\text{CLK\_DELAY}} - 5 - 10$$

$$t_{\text{DATA\_DELAY}} < 5 + t_{\text{CLK\_DELAY}} - t_{\text{TAP\_DELAY}}$$

The data can be delayed versus clock up to 5 ns in ideal case of  $t_{\text{WL}} = 20$  ns.

### Full-Speed Write Meeting Hold (Minimum Delay)

The following equations show how to calculate the allowed skew range between the SD\_CLK and SD\_DAT/CMD signals on the PCB.

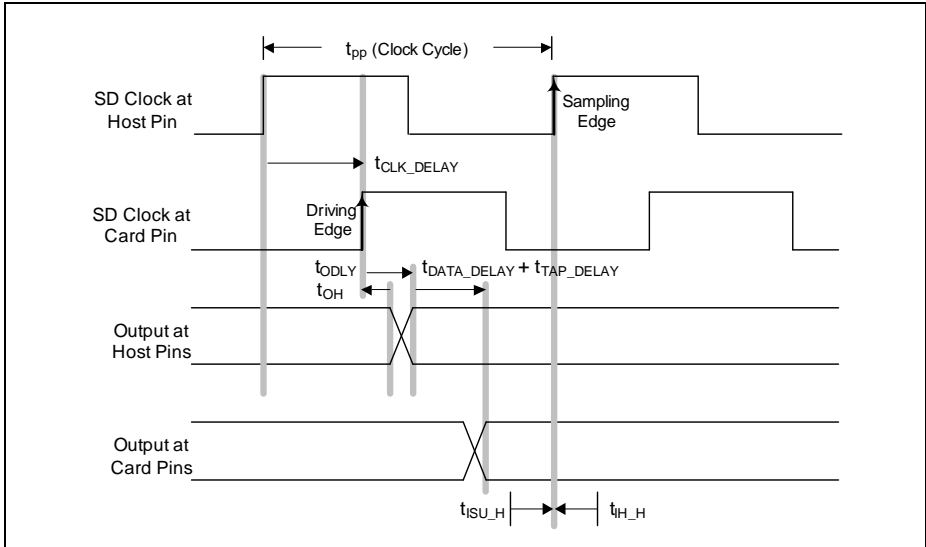
$$t_{\text{CLK\_DELAY}} < t_{\text{WL}} + t_{\text{OH\_F}} + t_{\text{DATA\_DELAY}} + t_{\text{TAP\_DELAY}} - t_{\text{IH}} \quad (4)$$

$$t_{\text{CLK\_DELAY}} < 20 + t_{\text{DATA\_DELAY}} + t_{\text{TAP\_DELAY}} - 5$$

$$t_{\text{DATA\_DELAY}} < 15 + t_{\text{CLK\_DELAY}} + t_{\text{TAP\_DELAY}}$$

The clock can be delayed versus data up to 18.2 ns (external delay line) in ideal case of  $t_{\text{WL}} = 20$  ns, with maximum  $t_{\text{TAP\_DELAY}} = 3.2$  ns programmed.

**Full-Speed Input Path (Read)**



**Figure 38 Full-Speed Input Path**

**Full-Speed Read Meeting Setup (Maximum Delay)**

The following equations show how to calculate the allowed combined propagation delay range of the SD\_CLK and SD\_DAT/CMD signals on the PCB.

(5)

$$t_{CLK\_DELAY} + t_{DATA\_DELAY} + t_{TAP\_DELAY} + t_{ODLY} + t_{ISU\_F} < 0,5 \times t_{pp}$$

$$t_{CLK\_DELAY} + t_{DATA\_DELAY} < 0,5 \times t_{pp} - t_{ODLY} - t_{ISU\_F} - t_{TAP\_DELAY}$$

$$t_{CLK\_DELAY} + t_{DATA\_DELAY} < 20 - 14 - 2 - t_{TAP\_DELAY}$$

$$t_{CLK\_DELAY} + t_{DATA\_DELAY} < 4 - t_{TAP\_DELAY}$$

The data + clock delay can be up to 4 ns for a 40 ns clock cycle.

**Electrical Parameters**

**Full-Speed Read Meeting Hold (Minimum Delay)**

The following equations show how to calculate the allowed combined propagation delay range of the SD\_CLK and SD\_DAT/CMD signals on the PCB.

(6)

$$t_{\text{CLK\_DELAY}} + t_{\text{OH}} + t_{\text{DATA\_DELAY}} + t_{\text{TAP\_DELAY}} > t_{\text{IH\_F}}$$

$$t_{\text{CLK\_DELAY}} + t_{\text{DATA\_DELAY}} > t_{\text{IH\_F}} - t_{\text{OH}} - t_{\text{TAP\_DELAY}}$$

$$t_{\text{CLK\_DELAY}} + t_{\text{DATA\_DELAY}} > 2 - t_{\text{TAP\_DELAY}}$$

The data + clock delay must be greater than 2 ns if  $t_{\text{TAP\_DELAY}}$  is not used.

If the  $t_{\text{TAP\_DELAY}}$  is programmed to at least 2 ns, the data + clock delay must be greater than 0 ns (or less). This is always fulfilled.

**AC Timing Specifications (High-Speed Mode)**

**Table 51 SDMMC Timing for High-Speed Mode**

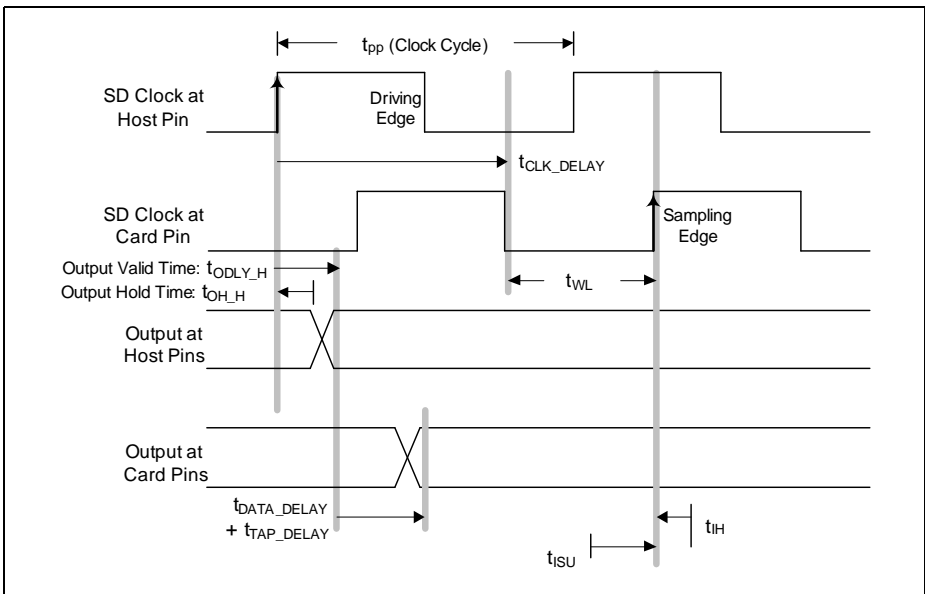
Parameter	Symbol	Values	Unit		Note/ Test Condition
			Min.	Max.	
Clock frequency in high speed transfer mode ( $1/t_{\text{pp}}$ )	$f_{\text{pp}}$ CC	0	48	MHz	
Clock cycle in high speed transfer mode	$t_{\text{pp}}$ CC	20	–	ns	
Clock low time	$t_{\text{WL}}$ CC	7	–	ns	
Clock high time	$t_{\text{WH}}$ CC	7	–	ns	
Clock rise time	$t_{\text{TLH}}$ CC	–	3	ns	
Clock fall time	$t_{\text{THL}}$ CC	–	3	ns	
Inputs setup to clock rising edge	$t_{\text{ISU\_H}}$ SR	2	–	ns	
Inputs hold after clock rising edge	$t_{\text{IH\_H}}$ SR	2	–	ns	
Outputs valid time in high speed mode	$t_{\text{ODLY\_H}}$ CC	–	14	ns	
Outputs hold time in high speed mode	$t_{\text{OH\_H}}$ CC	2	–	ns	

**Table 52 SD Card Bus Timing for High-Speed Mode<sup>1)</sup>**

Parameter	Symbol	Values		Unit	Note/ Test Condition
		Min.	Max.		
SD card input setup time	$t_{ISU}$	6	–	ns	
SD card input hold time	$t_{IH}$	2	–	ns	
SD card output valid time	$t_{ODLY}$	–	14	ns	
SD card output hold time	$t_{OH}$	2.5	–	ns	

1) Reference card timing values for calculation examples. Not subject to production test and not characterized.

**High-Speed Output Path (Write)**



**Figure 39 High-Speed Output Path**

**High-Speed Write Meeting Setup (Maximum Delay)**

The following equations show how to calculate the allowed skew between the SD\_CLK and SD\_DAT/CMD signals on the PCB.

No clock delay:

(7)

$$t_{ODLY\_H} + t_{DATA\_DELAY} + t_{TAP\_DELAY} + t_{ISU} < t_{WL}$$

With clock delay:

(8)

$$t_{ODLY\_H} + t_{DATA\_DELAY} + t_{TAP\_DELAY} + t_{ISU} < t_{WL} + t_{CLK\_DELAY}$$

(9)

$$t_{DATA\_DELAY} + t_{TAP\_DELAY} - t_{CLK\_DELAY} < t_{WL} - t_{ISU} - t_{ODLY\_H}$$

$$t_{DATA\_DELAY} - t_{CLK\_DELAY} < t_{WL} - t_{ISU} - t_{ODLY\_H} - t_{TAP\_DELAY}$$

$$t_{DATA\_DELAY} - t_{CLK\_DELAY} < 10 - 6 - 14 - t_{TAP\_DELAY}$$

$$t_{DATA\_DELAY} - t_{CLK\_DELAY} < -10 - t_{TAP\_DELAY}$$

The data delay is less than the clock delay by at least 10 ns in the ideal case where  $t_{WL} = 10$  ns.

### High-Speed Write Meeting Hold (Minimum Delay)

The following equations show how to calculate the allowed skew range between the SD\_CLK and SD\_DAT/CMD signals on the PCB.

(10)

$$t_{CLK\_DELAY} < t_{WL} + t_{OH\_H} + t_{DATA\_DELAY} + t_{TAP\_DELAY} - t_{IH}$$

$$t_{CLK\_DELAY} - t_{DATA\_DELAY} < t_{WL} + t_{OH\_H} + t_{TAP\_DELAY} - t_{IH}$$

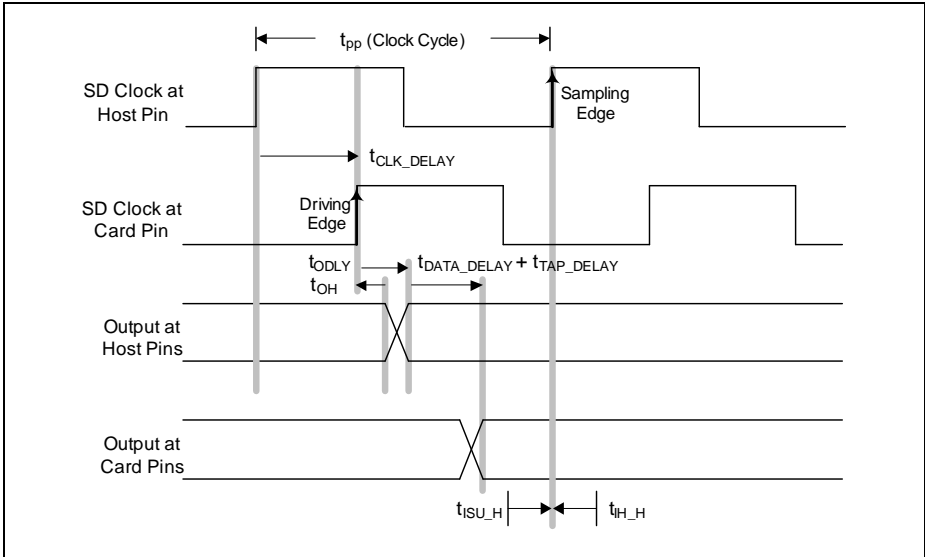
$$t_{CLK\_DELAY} - t_{DATA\_DELAY} < 10 + 2 + t_{TAP\_DELAY} - 2$$

$$t_{CLK\_DELAY} - t_{DATA\_DELAY} < 10 + t_{TAP\_DELAY}$$

The clock can be delayed versus data up to 13.2 ns (external delay line) in ideal case of  $t_{WL} = 10$  ns, with maximum  $t_{TAP\_DELAY} = 3.2$  ns programmed.



**High-Speed Input Path (Read)**



**Figure 40 High-Speed Input Path**

**High-Speed Read Meeting Setup (Maximum Delay)**

The following equations show how to calculate the allowed combined propagation delay range of the SD\_CLK and SD\_DAT/CMD signals on the PCB.

(11)

$$t_{CLK\_DELAY} + t_{DATA\_DELAY} + t_{TAP\_DELAY} + t_{ODLY} + t_{ISU\_H} < t_{pp}$$

$$t_{CLK\_DELAY} + t_{DATA\_DELAY} < t_{pp} - t_{ODLY} - t_{ISU\_H} - t_{TAP\_DELAY}$$

$$t_{CLK\_DELAY} + t_{DATA\_DELAY} < 20 - 14 - 2 - t_{TAP\_DELAY}$$

$$t_{CLK\_DELAY} + t_{DATA\_DELAY} < 4 - t_{TAP\_DELAY}$$

The data + clock delay can be up to 4 ns for a 20 ns clock cycle.

### High-Speed Read Meeting Hold (Minimum Delay)

The following equations show how to calculate the allowed combined propagation delay range of the SD\_CLK and SD\_DAT/CMD signals on the PCB.

(12)

$$t_{\text{CLK\_DELAY}} + t_{\text{OH}} + t_{\text{DATA\_DELAY}} + t_{\text{TAP\_DELAY}} > t_{\text{IH\_H}}$$

$$t_{\text{CLK\_DELAY}} + t_{\text{DATA\_DELAY}} > t_{\text{IH\_H}} - t_{\text{OH}} - t_{\text{TAP\_DELAY}}$$

$$t_{\text{CLK\_DELAY}} + t_{\text{DATA\_DELAY}} > 2 - 2,5 - t_{\text{TAP\_DELAY}}$$

$$t_{\text{CLK\_DELAY}} + t_{\text{DATA\_DELAY}} > -0,5 - t_{\text{TAP\_DELAY}}$$

The data + clock delay must be greater than -0.5 ns for a 20 ns clock cycle. This is always fulfilled.

### 3.3.10 EBU Timing

*Note: These parameters are not subject to production test, but verified by design and/or characterization.*

*Note: Operating Conditions apply, with Class A2 pins and  $C_L = 16$  pF.*

#### 3.3.10.1 EBU Asynchronous Timing

*Note: For each timing, the accumulated PLL jitter must be added separately.*

**Table 53 Common Timing Parameters for all Asynchronous Timings**

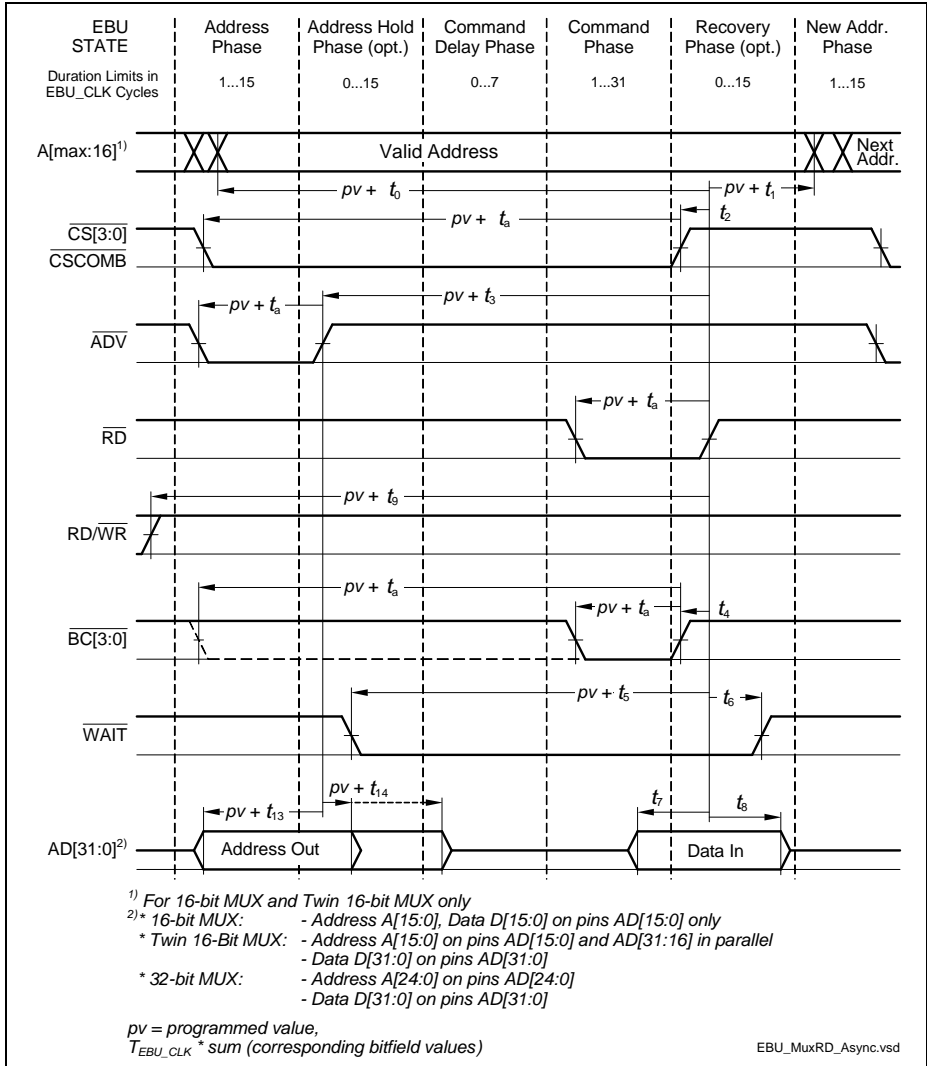
Parameter	Sym bol	Limit Values		Unit	Edge Setting	
		Min.	Max.			
Pulse width deviation from the ideal programmed width due to the A2 pad asymmetry, strong driver mode, rise delay - fall delay. $C_L = 16$ pF.	CC	$t_a$	-1	1.5	ns	sharp
			-2	1		medium
AD(24:16) output delay	CC	$t_{13}$	-5.5	2	-	-
AD(24:16) output delay	CC	$t_{14}$	-5.5	2		-

**Read Timing**

**Table 54 Asynchronous Read Timing, Multiplexed and Demultiplexed**

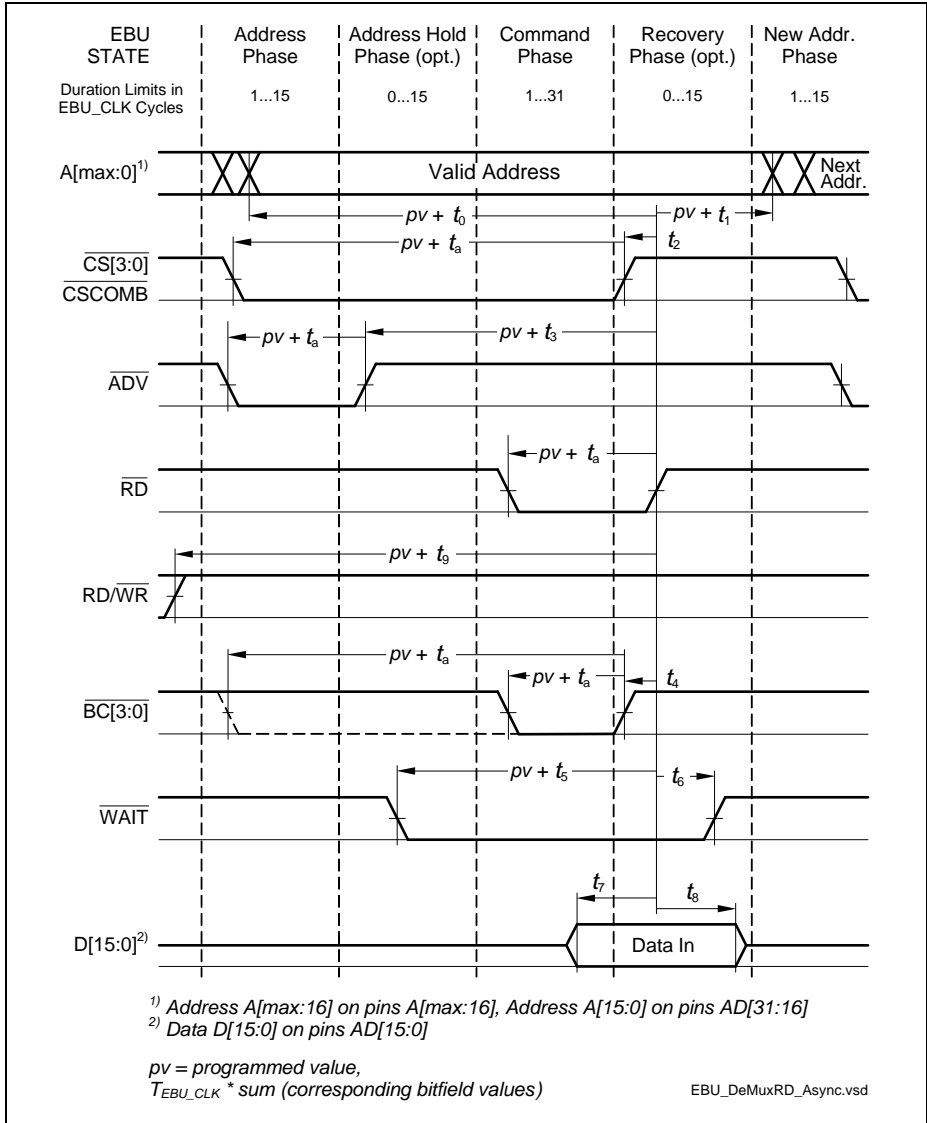
Parameter		Symbol	Limit Values		Unit	
			Min.	Max.		
A(24:16) output delay	to $\overline{RD}$ rising edge, deviation from the ideal programmed value.	CC	$t_0$	-2.5	2.5	ns
A(24:16) output delay		CC	$t_1$	-2.5	2.5	
$\overline{CS}$ rising edge		CC	$t_2$	-2	2.5	
$\overline{ADV}$ rising edge		CC	$t_3$	-1.5	4.5	
$\overline{BC}$ rising edge		CC	$t_4$	-2.5	2.5	
$\overline{WAIT}$ input setup		SR	$t_5$	12	–	
$\overline{WAIT}$ input hold		SR	$t_6$	0	–	
Data input setup		SR	$t_7$	12	–	
Data input hold		SR	$t_8$	0	–	
RD / $\overline{WR}$ output delay		CC	$t_9$	-2.5	1.5	

**Multiplexed Read Timing**



**Figure 41 Multiplexed Read Access**

Demultiplexed Read Timing



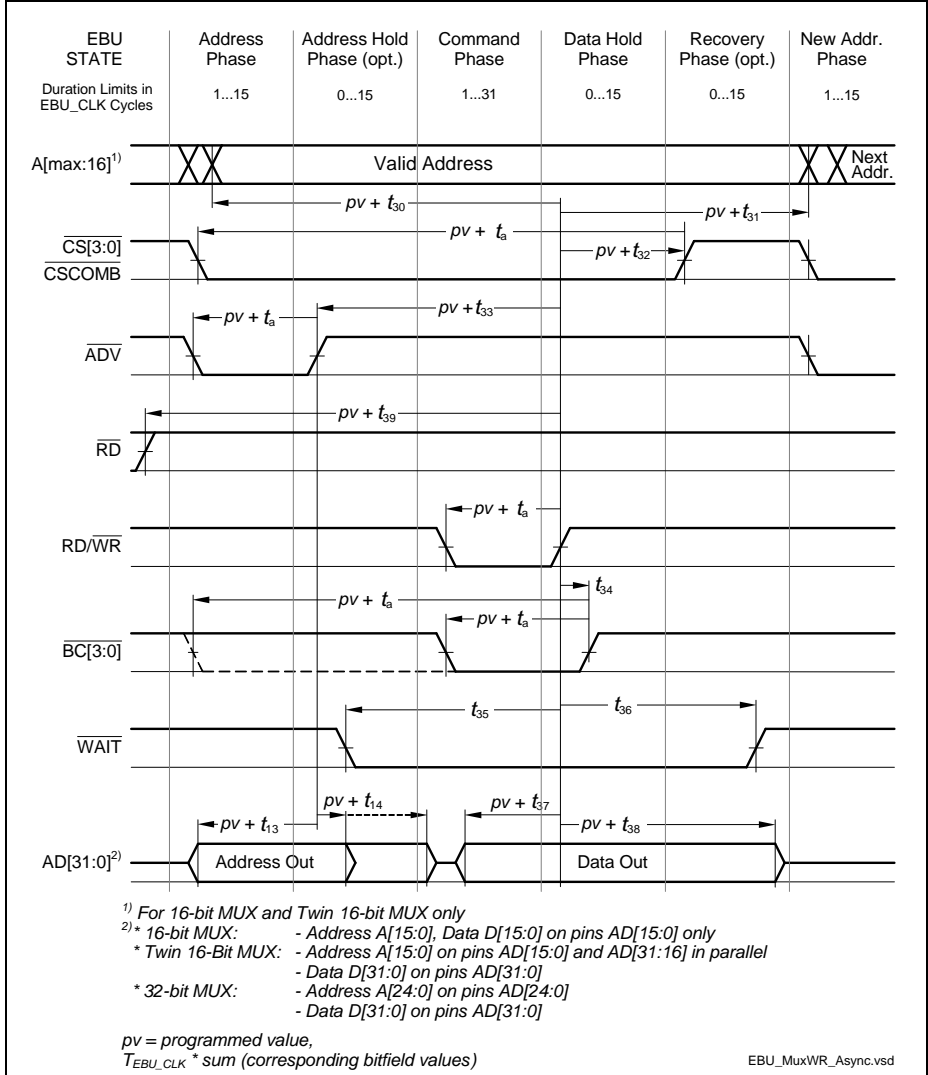
**Figure 42 Demultiplexed Read Access**

**Write Timing**

**Table 55 Asynchronous Write Timing, Multiplexed and Demultiplexed**

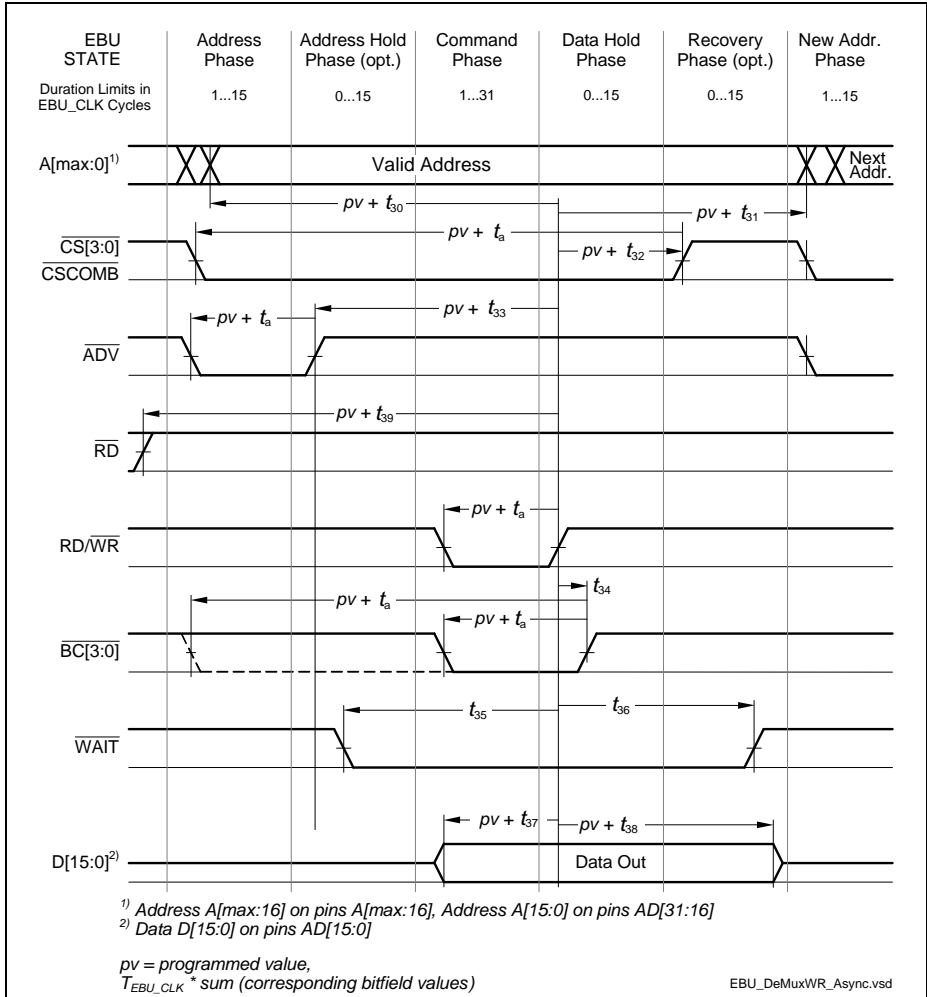
Parameter		Symbol	Limit Values		Unit	
			Min.	Max.		
A(24:0) output delay	to RD/ $\overline{\text{WR}}$ rising edge, deviation from the ideal programmed value.	CC	$t_{30}$	-2.5	2.5	ns
A(24:0) output delay		CC	$t_{31}$	-2.5	2.5	
$\overline{\text{CS}}$ rising edge		CC	$t_{32}$	-2	2	
$\overline{\text{ADV}}$ rising edge		CC	$t_{33}$	-2	4.5	
$\overline{\text{BC}}$ rising edge		CC	$t_{34}$	-2.5	2	
$\overline{\text{WAIT}}$ input setup		SR	$t_{35}$	12	–	
$\overline{\text{WAIT}}$ input hold		SR	$t_{36}$	0	–	
Data output delay		CC	$t_{37}$	-5.5	2	
Data output delay		CC	$t_{38}$	-5.5	2	
RD / $\overline{\text{WR}}$ output delay		CC	$t_{39}$	-2.5	1.5	

Multiplexed Write Timing



**Figure 43 Multiplexed Write Access**

**Demultiplexed Write Timing**



**Figure 44 Demultiplexed Write Access**



### 3.3.10.2 EBU Burst Mode Access Timing

*Note: These parameters are not subject to production test, but verified by design and/or characterization.*

*Note: Operating Conditions apply, with Class A2 pins and  $C_L = 16$  pF.*

**Table 56 EBU Burst Mode Read / Write Access Timing Parameters**

Parameter	Symbol	CC	Values			Unit	Note / Test Condition
			Min.	Typ.	Max.		
Output delay from BFCLKO rising edge	$t_{10}$	CC	-2	–	2	ns	–
$\overline{RD}$ and $\overline{RD}/\overline{WR}$ active/inactive after BFCLKO active edge <sup>1)</sup>	$t_{12}$	CC	-2	–	2	ns	–
$\overline{CSx}$ output delay from BFCLKO active edge <sup>1)</sup>	$t_{21}$	CC	-2.5	–	1.5	ns	–
$\overline{ADV}$ active/inactive after BFCLKO active edge <sup>2)</sup>	$t_{22}$	CC	-2	–	2	ns	–
$\overline{BAA}$ active/inactive after BFCLKO active edge <sup>2)</sup>	$t_{22a}$	CC	-2.5	–	1.5	ns	–
Data setup to BFCLKI rising edge <sup>3)</sup>	$t_{23}$	SR	3	–	–	ns	–
Data hold from BFCLKI rising edge <sup>3)</sup>	$t_{24}$	SR	0	–	–	ns	–
$\overline{WAIT}$ setup (low or high) to BFCLKI rising edge <sup>3)</sup>	$t_{25}$	SR	3	–	–	ns	–
$\overline{WAIT}$ hold (low or high) from BFCLKI rising edge <sup>3)</sup>	$t_{26}$	SR	0	–	–	ns	–

1) An active edge can be a rising or falling edge, depending on the settings of bits BFCON.EBSE / ECSE and the clock divider ratio.

Negative minimum values for these parameters mean that the last data read during a burst may be corrupted. However, with clock feedback enabled, this value is an oversampling not required for the internal bus transaction, and will be discarded.

2) This parameter is valid for BUSCONx.EBSE = 1 and BUSAPx.EXTCLK = 00<sub>B</sub>.

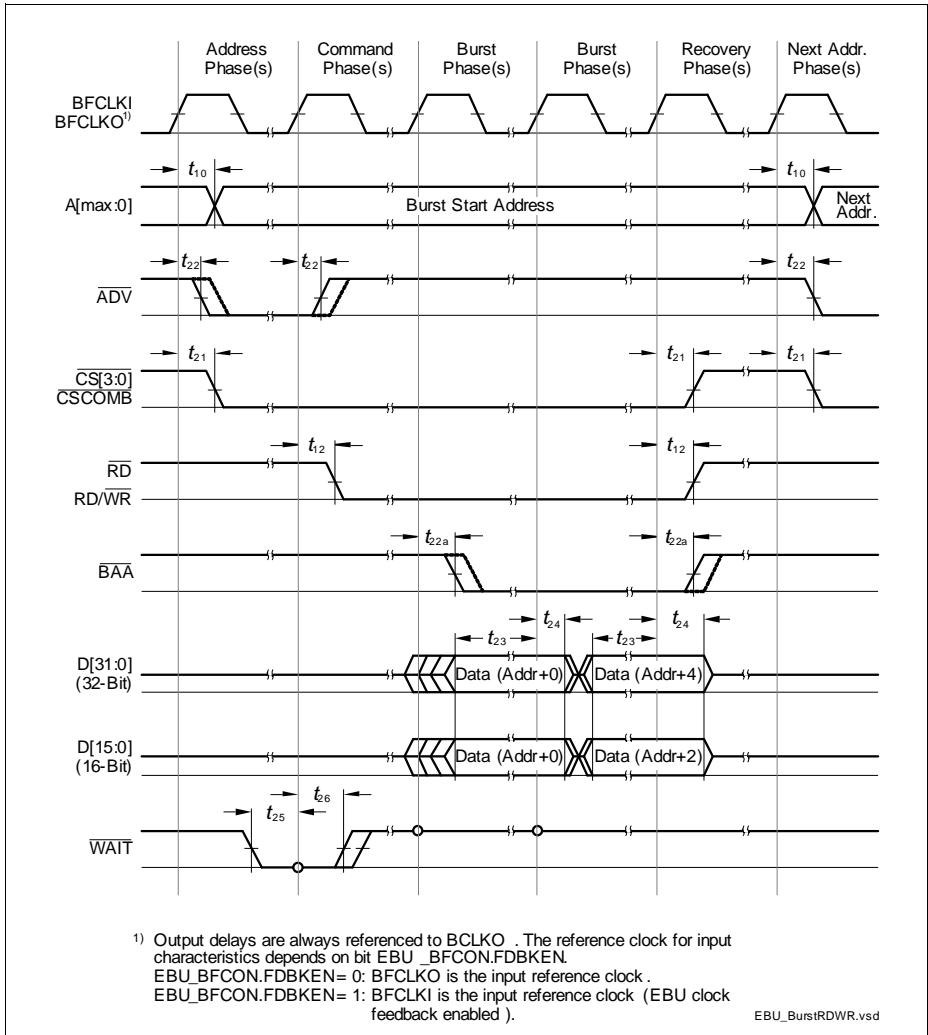
For BUSCONx.EBSE = 1 and other values of BUSAPx.EXTCLK, ADV and BAA will be delayed by 1/2 of the internal bus clock period  $T_{CPU} = 1 / f_{CPU}$ .

For BUSCONx. EBSE = 0 and BUSAPx.EXTCLK = 11<sub>B</sub>, add 2 internal bus clock periods.

For BUSCONx. EBSE = 0 and other values of BUSAPx.EXTCLK, add 1 internal bus clock period.

**Electrical Parameters**

3) If the clock feedback is not enabled, the input signals are latched using the internal clock in the same way as for asynchronous access. Thus,  $t_5$ ,  $t_6$ ,  $t_7$  and  $t_8$  from the asynchronous timing apply.



**Figure 45 EBU Burst Mode Read / Write Access Timing**

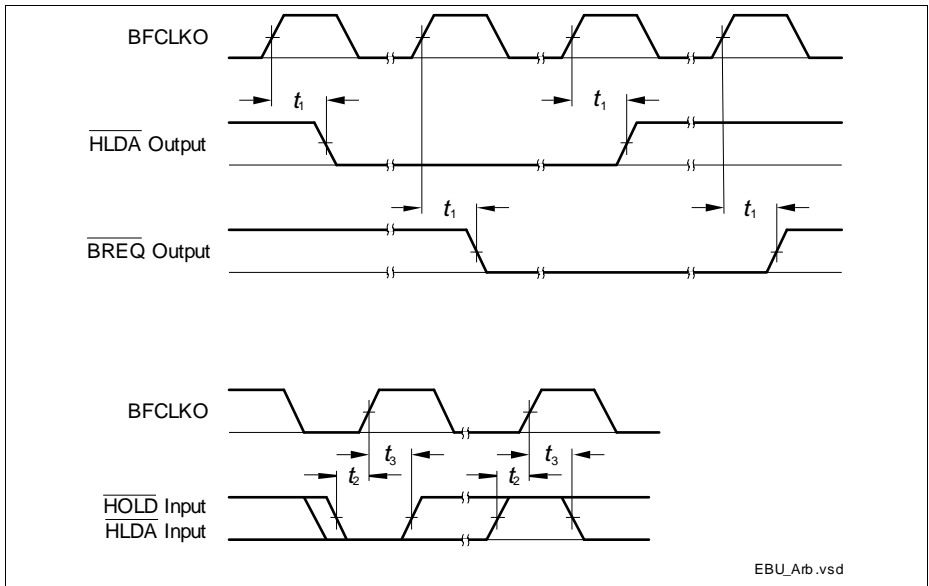
### 3.3.10.3 EBU Arbitration Signal Timing

*Note: These parameters are not subject to production test, but verified by design and/or characterization.*

*Note: Operating Conditions apply.*

**Table 57 EBU Arbitration Signal Timing Parameters**

Parameter	Symbol	Values	Unit			Note / Test Condition
			Min.	Typ.	Max.	
Output delay from BFCLKO rising edge	$t_1$ CC	–	–	16	ns	$C_L = 50$ pF
Data setup to BFCLKO falling edge	$t_2$ SR	11	–	–	ns	–
Data hold from BFCLKO falling edge	$t_3$ SR	2	–	–	ns	–



**Figure 46 EBU Arbitration Signal Timing**

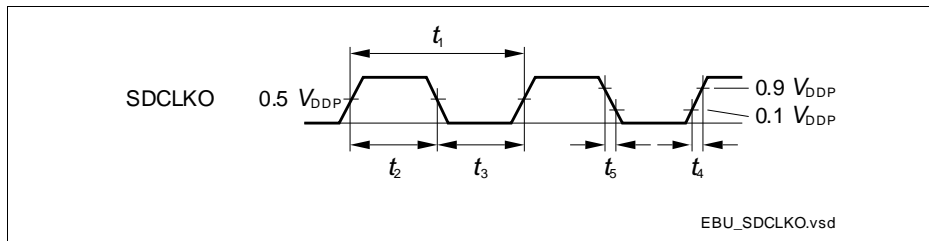
### 3.3.10.4 EBU SDRAM Access Timing

Note: These parameters are not subject to production test, but verified by design and/or characterization.

Note: Operating Conditions apply, with Class A2 pins and  $C_L = 16$  pF.

**Table 58 EBU SDRAM Access SDCLKO Signal Timing Parameters**

Parameter	Symbol		Values			Unit	Note / Test Condition
			Min.	Typ.	Max.		
SDCLKO period	$t_1$	CC	12.5	–	–	ns	–
SDCLKO high time	$t_2$	SR	5.5	–	–	ns	–
SDCLKO low time	$t_3$	SR	3.75	–	–	ns	–
SDCLKO rise time	$t_4$	SR	–	–	3.0	ns	–
SDCLKO fall time	$t_5$	SR	–	–	3.0	ns	–

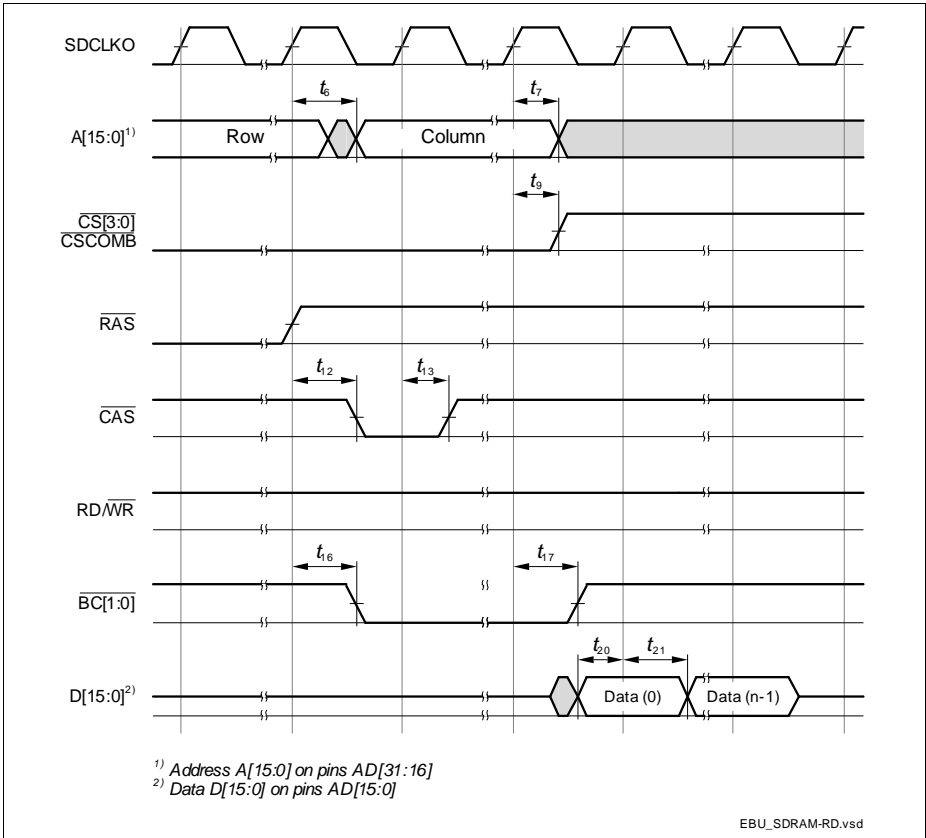


**Figure 47 EBU SDRAM Access CLKOUT Timing**

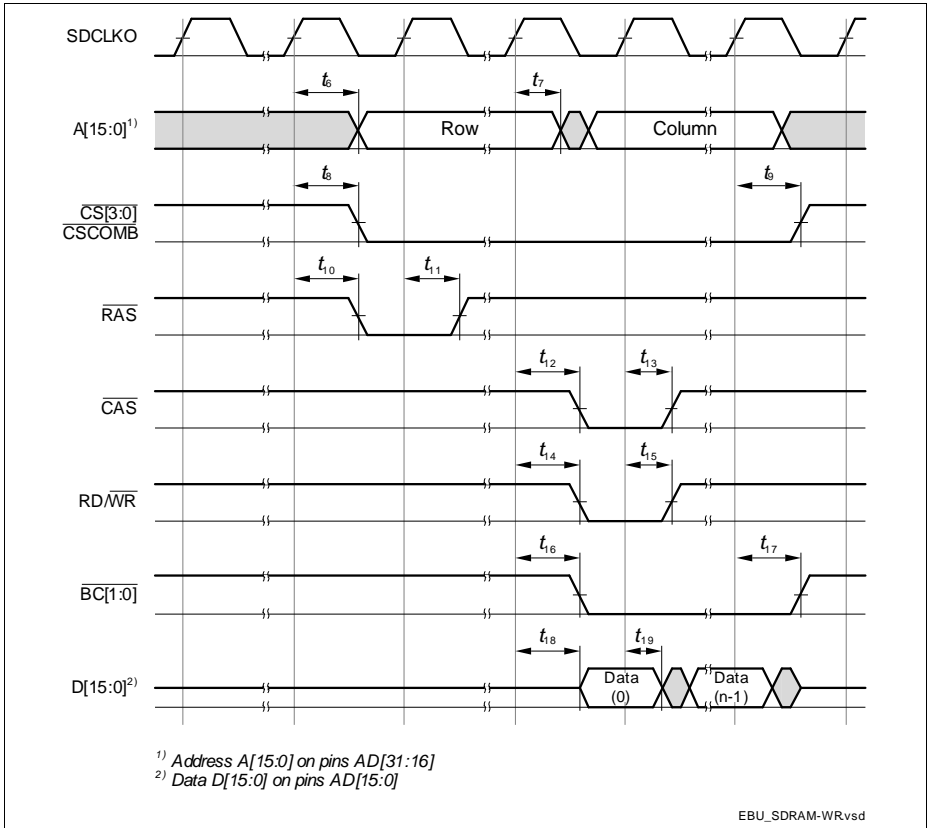
**Table 59 EBU SDRAM Access Signal Timing Parameters**

Parameter		Symbol	Limit Values		Unit	
			Min.	Max.		
A(15:0) output valid	from SDCLKO low-to-high transition	CC	$t_6$	–	9	ns
A(15:0) output hold		CC	$t_7$	3	–	
$\overline{\text{CS}}(3:0)$ low		CC	$t_8$	–	9	
$\overline{\text{CS}}(3:0)$ high		CC	$t_9$	3	–	
$\overline{\text{RAS}}$ low		CC	$t_{10}$	–	9	
$\overline{\text{RAS}}$ high		SR	$t_{11}$	3	–	
$\overline{\text{CAS}}$ low		SR	$t_{12}$	–	9	
$\overline{\text{CAS}}$ high		CC	$t_{13}$	3	–	
$\overline{\text{RD}}/\overline{\text{WR}}$ low		CC	$t_{14}$	–	9	
$\overline{\text{RD}}/\overline{\text{WR}}$ high		CC	$t_{15}$	3	–	
$\overline{\text{BC}}(3:0)$ low		CC	$t_{16}$	–	9	
$\overline{\text{BC}}(3:0)$ high		CC	$t_{17}$	3	–	
D(15:0) output valid		CC	$t_{18}$	–	9	
D(15:0) output hold		CC	$t_{19}$	3	–	
CKE output valid <sup>1)</sup>		CC	$t_{22}$	–	7	
CKE output hold <sup>1)</sup>		CC	$t_{23}$	2	–	
D(15:0) input hold		SR	$t_{21}$	3	–	
D(15:0) input setup to SDCLKO low-to-high transition	SR	$t_{20}$	4	–		

1) Not depicted in the read and write access timing figures below.



**Figure 48 EBU SDRAM Read Access Timing**



**Figure 49 EBU SDRAM Write Access Timing**

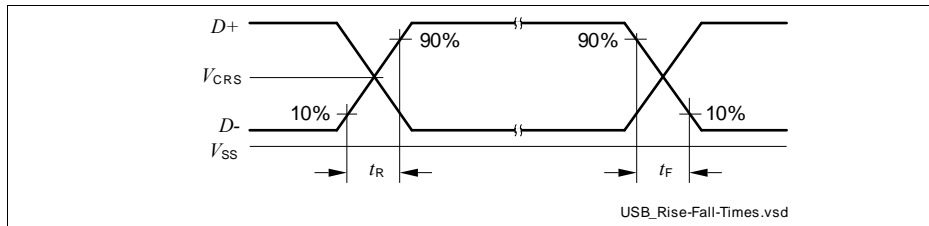
### 3.3.11 USB Interface Characteristics

The Universal Serial Bus (USB) Interface is compliant to the USB Rev. 2.0 Specification and the OTG Specification Rev. 1.3. High-Speed Mode is not supported.

*Note: These parameters are not subject to production test, but verified by design and/or characterization.*

**Table 60 USB Timing Parameters** (operating conditions apply)

Parameter	Symbol		Values			Unit	Note / Test Condition
			Min.	Typ.	Max.		
Rise time	$t_R$	CC	4	–	20	ns	$C_L = 50$ pF
Fall time	$t_F$	CC	4	–	20	ns	$C_L = 50$ pF
Rise/Fall time matching	$t_R/t_F$	CC	90	–	111.11	%	$C_L = 50$ pF
Crossover voltage	$V_{CRS}$	CC	1.3	–	2.0	V	$C_L = 50$ pF



**Figure 50 USB Signal Timing**

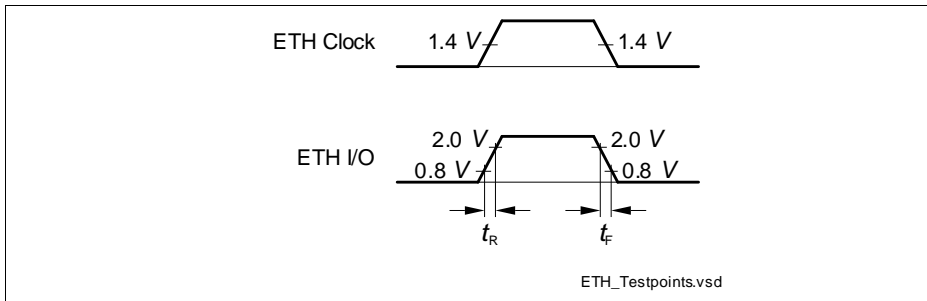


### 3.3.12 Ethernet Interface (ETH) Characteristics

For proper operation of the Ethernet Interface it is required that  $f_{SYS} \geq 100$  MHz.

*Note: These parameters are not subject to production test, but verified by design and/or characterization.*

#### 3.3.12.1 ETH Measurement Reference Points

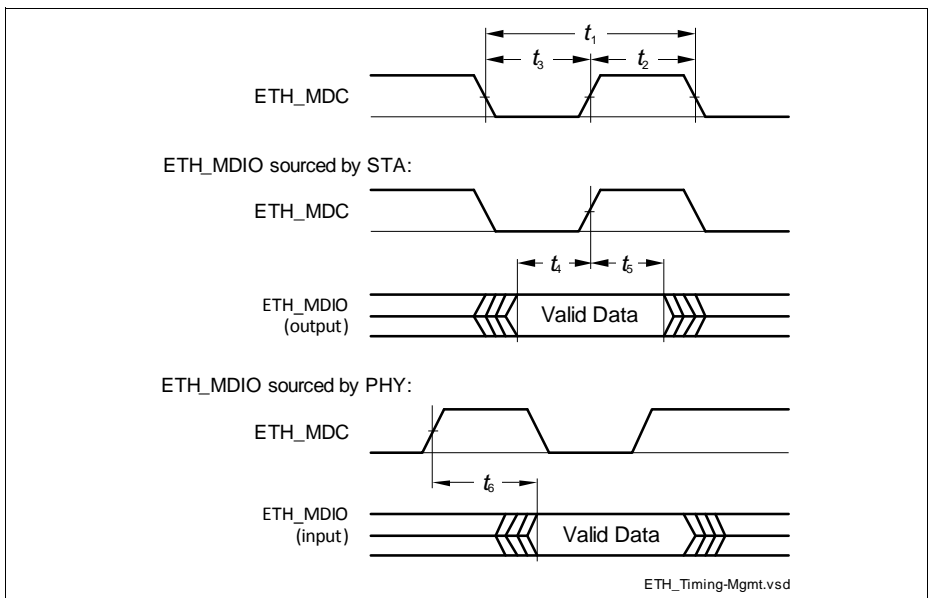


**Figure 51 ETH Measurement Reference Points**

**3.3.12.2 ETH Management Signal Parameters (ETH\_MDC, ETH\_MDIO)**

**Table 61 ETH Management Signal Timing Parameters**

Parameter	Symbol		Values			Unit	Note / Test Condition
			Min.	Typ.	Max.		
ETH_MDC period	$t_1$	CC	400	–	–	ns	$C_L = 25 \text{ pF}$
ETH_MDC high time	$t_2$	CC	160	–	–	ns	
ETH_MDC low time	$t_3$	CC	160	–	–	ns	
ETH_MDIO setup time (output)	$t_4$	CC	10	–	–	ns	
ETH_MDIO hold time (output)	$t_5$	CC	10	–	–	ns	
ETH_MDIO data valid (input)	$t_6$	SR	0	–	300	ns	



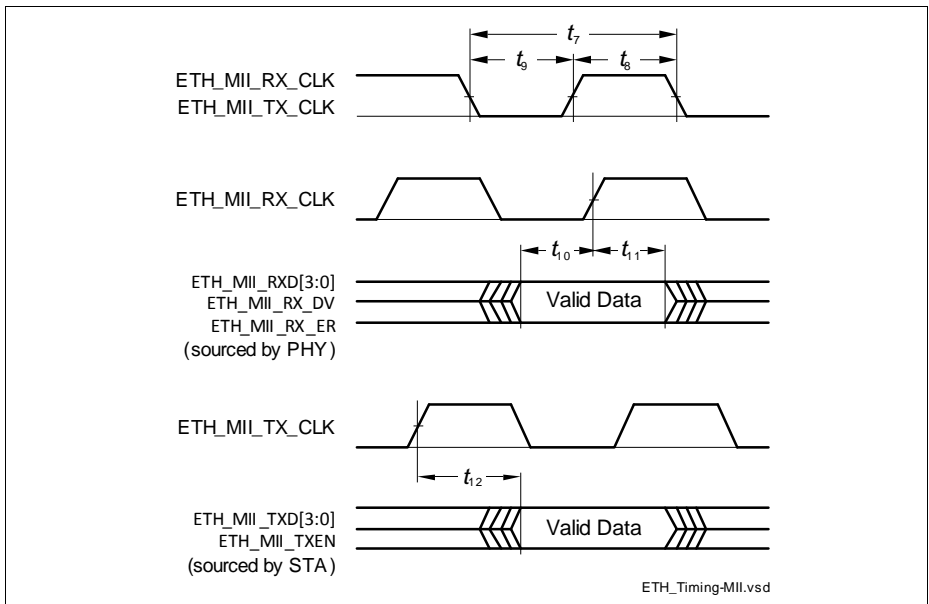
**Figure 52 ETH Management Signal Timing**

### 3.3.12.3 ETH MII Parameters

In the following, the parameters of the MII (Media Independent Interface) are described.

**Table 62 ETH MII Signal Timing Parameters**

Parameter	Symbol	SR	Values			Unit	Note / Test Condition
			Min.	Typ.	Max.		
Clock period, 10 Mbps	$t_7$	SR	400	–	–	ns	$C_L = 25 \text{ pF}$
Clock high time, 10 Mbps	$t_8$	SR	140	–	260	ns	
Clock low time, 10 Mbps	$t_9$	SR	140	–	260	ns	
Clock period, 100 Mbps	$t_7$	SR	40	–	–	ns	
Clock high time, 100 Mbps	$t_8$	SR	14	–	26	ns	
Clock low time, 100 Mbps	$t_9$	SR	14	–	26	ns	
Input setup time	$t_{10}$	SR	10	–	–	ns	
Input hold time	$t_{11}$	SR	10	–	–	ns	
Output valid time	$t_{12}$	CC	0	–	25	ns	



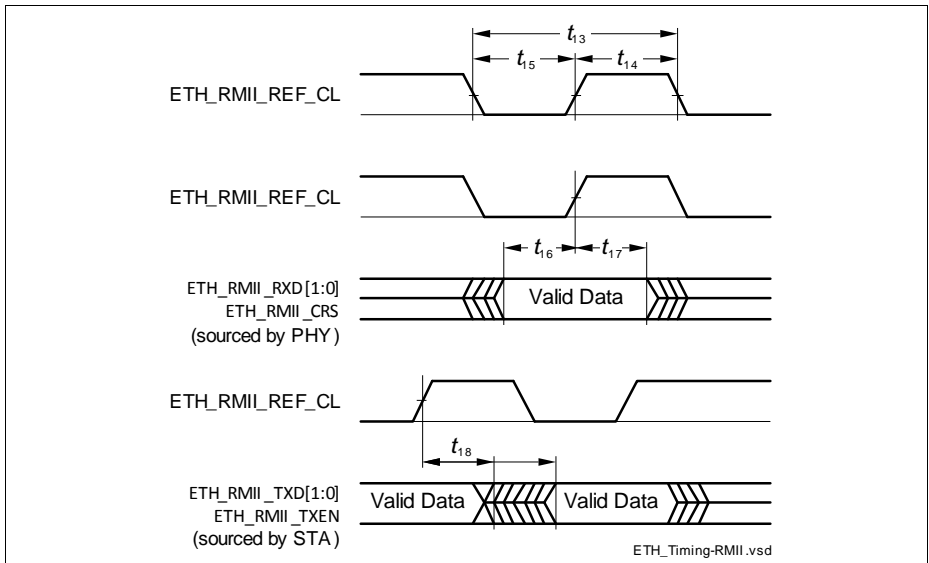
**Figure 53 ETH MII Signal Timing**

### 3.3.12.4 ETH RMII Parameters

In the following, the parameters of the RMII (Reduced Media Independent Interface) are described.

**Table 63 ETH RMII Signal Timing Parameters**

Parameter	Symbol		Values			Unit	Note / Test Condition
			Min.	Typ.	Max.		
ETH_RMII_REF_CL clock period	$t_{13}$	SR	20	–	–	ns	$C_L = 25 \text{ pF}$ ; 50 ppm
ETH_RMII_REF_CL clock high time	$t_{14}$	SR	7	–	13	ns	$C_L = 25 \text{ pF}$
ETH_RMII_REF_CL clock low time	$t_{15}$	SR	7	–	13	ns	
ETH_RMII_RXD[1:0], ETH_RMII_CRD setup time	$t_{16}$	SR	4	–	–	ns	
ETH_RMII_RXD[1:0], ETH_RMII_CRD hold time	$t_{17}$	SR	2	–	–	ns	
ETH_RMII_TXD[1:0], ETH_RMII_TXEN data valid	$t_{18}$	CC	4	–	15	ns	



**Figure 54 ETH RMII Signal Timing**

## 4 Package and Reliability

The XMC4500 is a member of the XMC4000 Family of microcontrollers. It is also compatible to a certain extent with members of similar families or subfamilies.

Each package is optimized for the device it houses. Therefore, there may be slight differences between packages of the same pin-count but for different device types. In particular, the size of the Exposed Die Pad may vary.

If different device types are considered or planned for an application, it must be ensured that the board layout fits all packages under consideration.

### 4.1 Package Parameters

**Table 64** provides the thermal characteristics of the packages used in XMC4500.

**Table 64 Thermal Characteristics of the Packages**

Parameter	Symbol	Limit Values		Unit	Package Types
		Min.	Max.		
Exposed Die Pad Dimensions (including U-Groove where applicable)	Ex × Ey CC	-	6.5 × 6.5	mm	PG-LQFP-144-18
		-	6.5 × 6.5	mm	PG-LQFP-144-24
		-	7.0 × 7.0	mm	PG-LQFP-100-11
		-	7.0 × 7.0	mm	PG-LQFP-100-25
Thermal resistance Junction-Ambient $T_j \leq 150\text{ °C}$	$R_{\Theta JA}$ CC	-	40.5	K/W	PG-LFBGA-144-10
		-	22.4	K/W	PG-LQFP-144-18 <sup>1)</sup>
		-	19.5	K/W	PG-LQFP-144-24 <sup>1)</sup>
		-	23.0	K/W	PG-LQFP-100-11 <sup>1)</sup>
		-	21.0	K/W	PG-LQFP-100-25 <sup>1)</sup>

1) Device mounted on a 4-layer JEDEC board (JESD 51-7) with thermal vias; exposed pad soldered.

*Note: For electrical reasons, it is required to connect the exposed pad to the board ground  $V_{SS}$ , independent of EMC and thermal requirements.*

#### 4.1.1 Thermal Considerations

When operating the XMC4500 in a system, the total heat generated in the chip must be dissipated to the ambient environment to prevent overheating and the resulting thermal damage.

The maximum heat that can be dissipated depends on the package and its integration into the target board. The “Thermal resistance  $R_{\Theta JA}$ ” quantifies these parameters. The

power dissipation must be limited so that the average junction temperature does not exceed 150 °C.

The difference between junction temperature and ambient temperature is determined by

$$\Delta T = (P_{\text{INT}} + P_{\text{IOSTAT}} + P_{\text{IODYN}}) \times R_{\Theta\text{JA}}$$

The internal power consumption is defined as

$$P_{\text{INT}} = V_{\text{DDP}} \times I_{\text{DDP}} \text{ (switching current and leakage current).}$$

The static external power consumption caused by the output drivers is defined as

$$P_{\text{IOSTAT}} = \Sigma((V_{\text{DDP}} - V_{\text{OH}}) \times I_{\text{OH}}) + \Sigma(V_{\text{OL}} \times I_{\text{OL}})$$

The dynamic external power consumption caused by the output drivers ( $P_{\text{IODYN}}$ ) depends on the capacitive load connected to the respective pins and their switching frequencies.

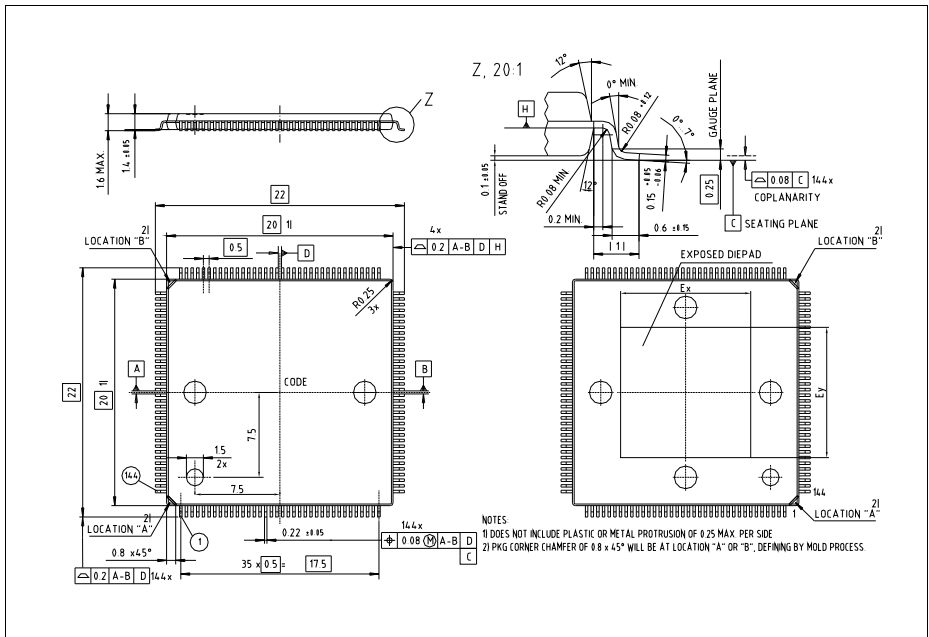
If the total power dissipation for a given system configuration exceeds the defined limit, countermeasures must be taken to ensure proper system operation:

- Reduce  $V_{\text{DDP}}$ , if possible in the system
- Reduce the system frequency
- Reduce the number of output pins
- Reduce the load on active output drivers

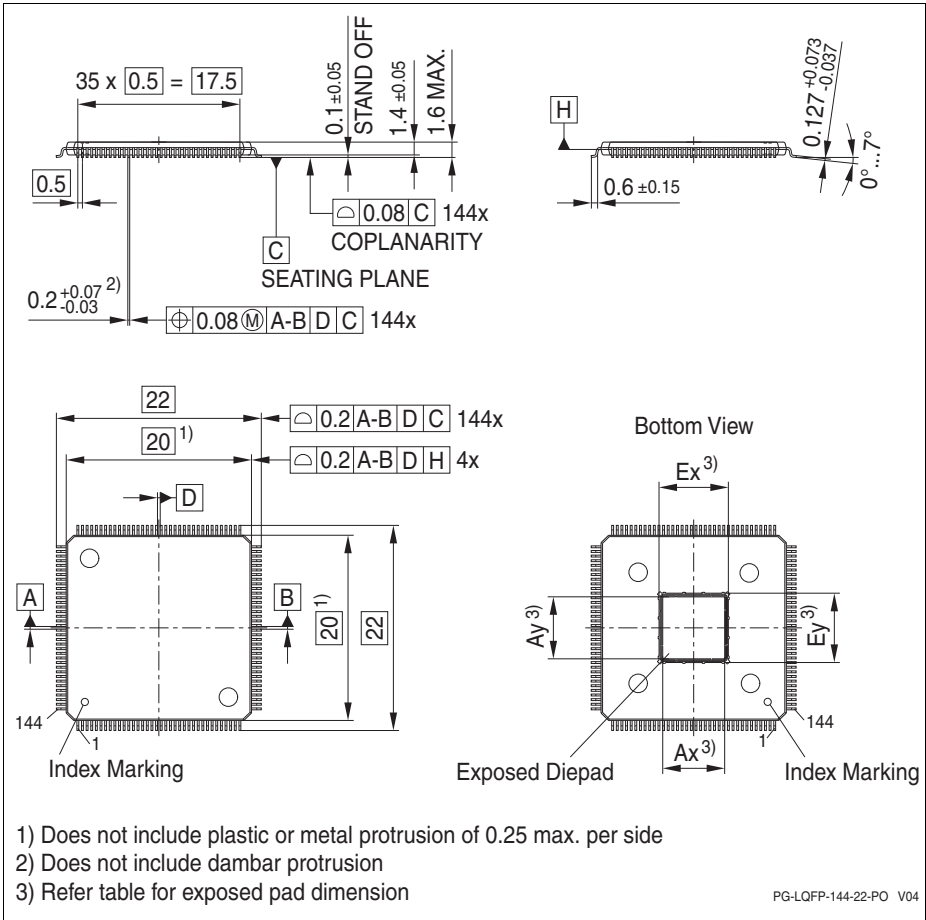
**4.2 Package Outlines**

**Table 65 Differences PG-LQFP-14-18 to PG-LQFP-144-24**

Change	PG-LQFP-144-18	PG-LQFP-144-24
Thermal Resistance Junction Ambient ( $R_{\theta JA}$ )	22.4 K/W	21.0 K/W
Lead Width	0.22 $\pm$ 0.05 mm	0.2 $\pm$ 0.07 <sub>-0.03</sub> mm
Lead Thickness	0.15 $\pm$ 0.05 <sub>-0.06</sub> mm	0.127 $\pm$ 0.073 <sub>-0.037</sub> mm
Exposed Die Pad outer dimensions	6.5 mm $\times$ 6.5 mm	6.5 mm $\times$ 6.5 mm
Exposed Die Pad U-Groove inner dimensions	n.a.	5.7 mm $\times$ 5.7 mm



**Figure 55 PG-LQFP-144-18 (Plastic Green Low Profile Quad Flat Package)**

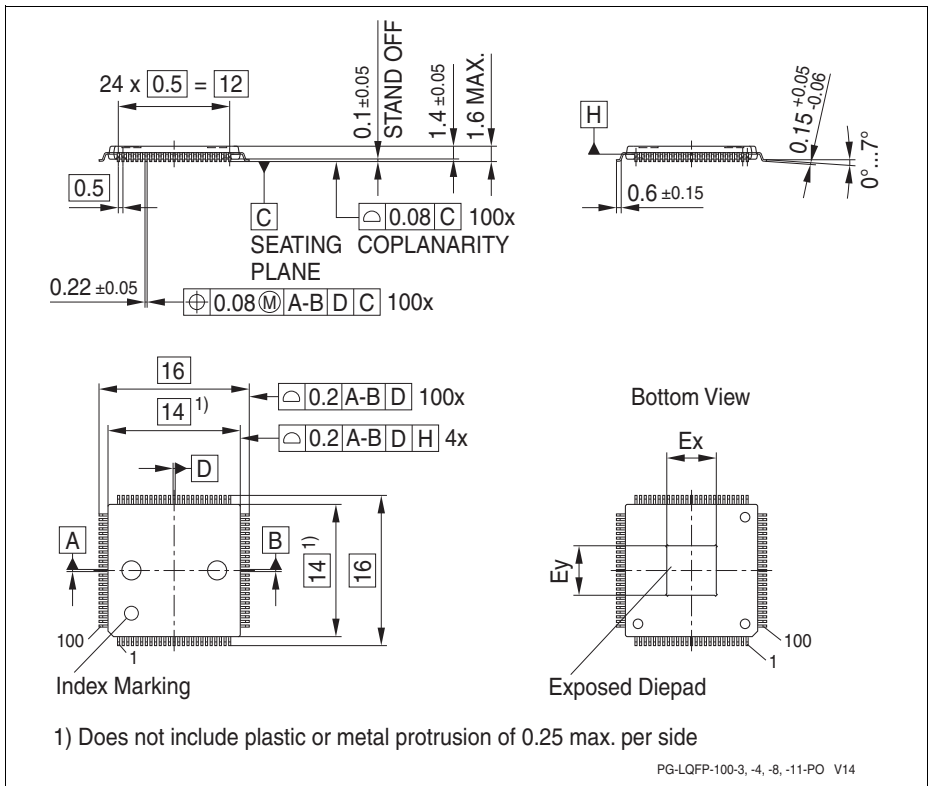


**Figure 56 PG-LQFP-144-24 (Plastic Green Low Profile Quad Flat Package)**

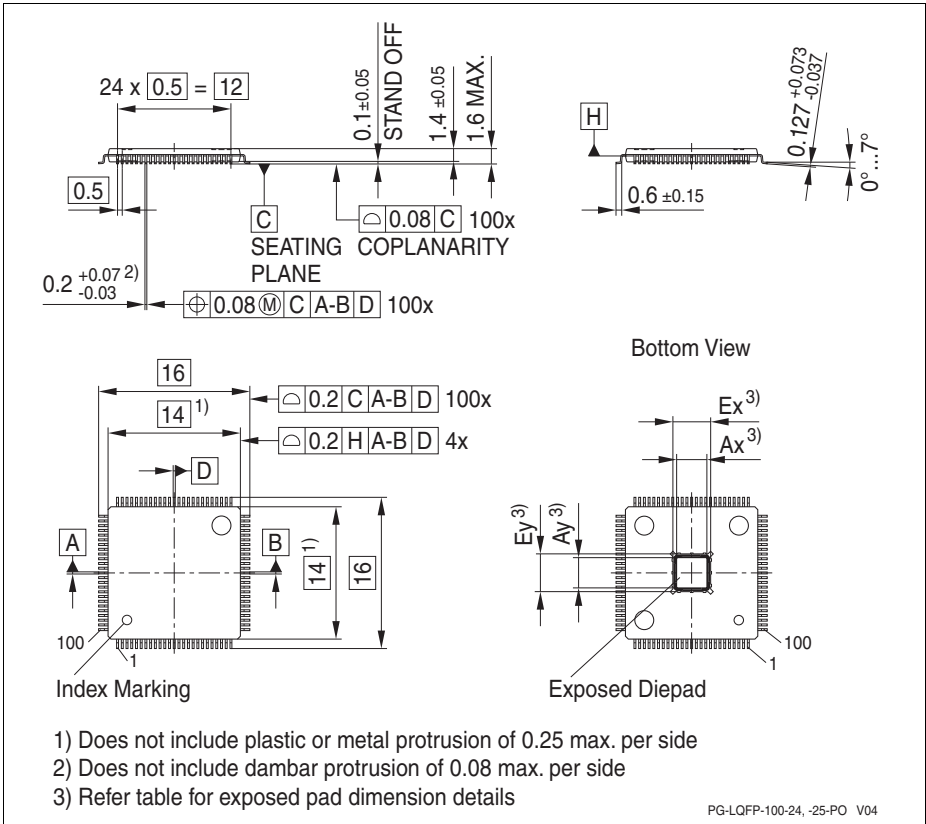


**Table 66 Differences PG-LQFP-100-11 to PG-LQFP-100-24**

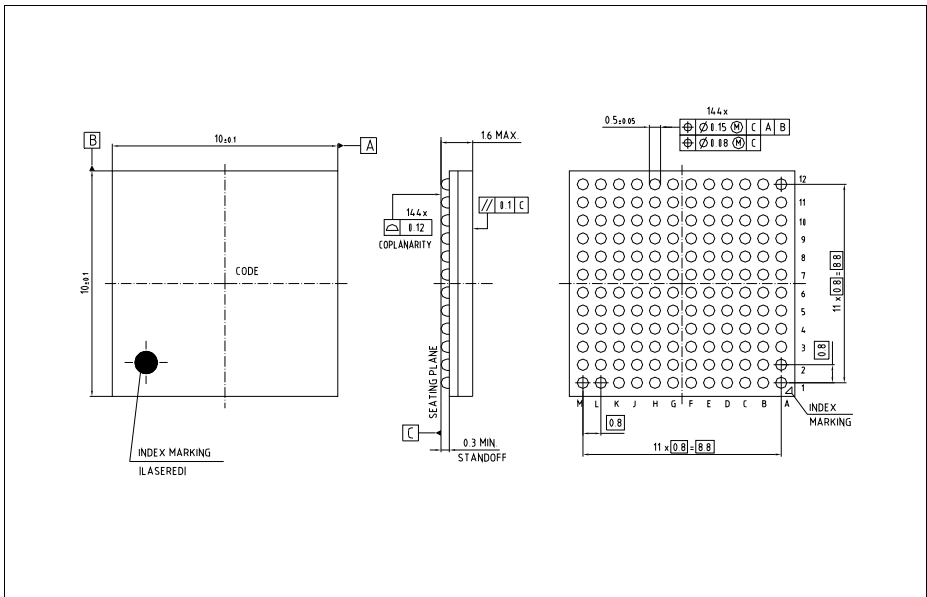
Change	PG-LQFP-100-11	PG-LQFP-100-25
Thermal Resistance Junction Ambient ( $R_{\theta JA}$ )	23.0 K/W	19.5 K/W
Lead Width	0.22 $\pm$ 0.05 mm	0.2 $^{+0.07}$ <sub>-0.03</sub> mm
Lead Thickness	0.15 $^{+0.05}$ <sub>-0.06</sub> mm	0.127 $^{+0.073}$ <sub>-0.037</sub> mm
Exposed Die Pad outer dimensions	7.0 mm $\times$ 7.0 mm	7.0 mm $\times$ 7.0 mm
Exposed Die Pad U-Groove inner dimensions	n.a.	6.2 mm $\times$ 6.2 mm



**Figure 57 PG-LQFP-100-11 (Plastic Green Low Profile Quad Flat Package)**



**Figure 58 PG-LQFP-100-25 (Plastic Green Low Profile Quad Flat Package)**



**Figure 59 PG-LFBGA-144-10 (Plastic Green Low Profile Fine Pitch Ball Grid Array)**

All dimensions in mm.

You can find complete information about Infineon packages, packing and marking in our Infineon Internet Page “Packages”: <http://www.infineon.com/packages>

### 4.3 Quality Declarations

The qualification of the XMC4500 is executed according to the JEDEC standard JESD47H.

*Note: For automotive applications refer to the Infineon automotive microcontrollers.*

**Table 67 Quality Parameters**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Operation lifetime	$t_{OP}$ CC	20	–	–	a	$T_J \leq 109^\circ\text{C}$ , device permanent on
ESD susceptibility according to Human Body Model (HBM)	$V_{HBM}$ SR	–	–	2 000	V	EIA/JESD22-A114-B
ESD susceptibility according to Charged Device Model (CDM)	$V_{CDM}$ SR	–	–	500	V	Conforming to JESD22-C101-C
Moisture sensitivity level	$MSL$ CC	–	–	3	–	JEDEC J-STD-020D
Soldering temperature	$T_{SDR}$ SR	–	–	260	$^\circ\text{C}$	Profile according to JEDEC J-STD-020D

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